

**Data Compression for Maskless Lithography Systems: Architecture,
Algorithms and Implementation**

by

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Spring 2008

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Abstract

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Sciences

University of California, Berkeley

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Future lithography systems must produce more dense microchips with smaller feature sizes, while maintaining throughput comparable to today's optical lithography systems. This places stringent data-handling requirements on the design of any maskless lithography system. Today's optical lithography systems transfer one layer of data from the mask to the entire wafer in about sixty seconds. To achieve a similar throughput for a direct-write maskless lithography system with a pixel size of 22 nm, data rates of about 12 Tb/s are required. In this thesis, we propose a datapath architecture for delivering such a data rate to a parallel array of writers. Our proposed system achieves this data rate contingent on two assumptions: consistent 10 to 1

compression of lithography data, and implementation of real-time hardware decoder, fabricated on a microchip together with a massively parallel array of lithography writers, capable of decoding 12 Tb/s of data.

To address the compression efficiency problem, we explore a number of existing binary and gray-pixel lossless compression algorithms and apply them to a variety of microchip layers of typical circuits such as memory and control. The spectrum of algorithms include industry standard image compression algorithms such as JBIG and JPEG-LS, a wavelet based technique SPIHT, general file compression techniques ZIP and BZIP2, and a simple list-of-rectangles representation RECT. In addition, we develop a new technique, Context Copy Combinatorial Coding (C4), designed specifically for microchip layer images, with a low-complexity decoder for application to the datapath architecture. C4 combines the advantages of JBIG and ZIP, to achieve compression ratios higher than existing techniques. We have also devised Block C4, a variation of C4 with up to hundred times faster encoding times, with little or no loss in compression efficiency.

The compression efficiency of various compression algorithms have been characterized on a variety of layouts sampled from many industry sources. In particular, the compression efficiency of Block C4, BZIP2, and ZIP is characterized for the Poly, Active, Contact, Metal1, Via1, and Metal2 layers of a complete industry 65 nm layout. Overall, we have found that compression efficiency varies significantly from design to design, from layer to layer, and even within parts of the same layer. It is diffi-

cult, if not impossible, to guarantee a lossless 10 to 1 compression for all lithography data, as desired in the design of our datapath architecture. Nonetheless, on the most complex Metall1 layer of our 65 nm full chip microprocessor design, we show that a average lossless compression of 5.2 is attainable, which corresponds to a throughput of 60 wafer layers per hour for a 0.77 Tb/s board-to-chip communications link. As a reference, state-of-the-art HyperTransport 3.0 offers 0.32 Tb/s per link. These numbers demonstrate the role lossless compression can play in the design of a maskless lithography datapath.

The decoder for any chosen compression scheme must be replicated in hardware tens of thousands of times, to achieve the 12 Tb/s decoding rate. As such, decoder implementation complexity is a significant concern. We explore the tradeoff between the compression ratio, and decoder buffer size for C4, which constitutes a significant portion of the decoder implementation complexity. We show that for a fixed buffer size, C4 achieves a significantly higher compression ratio than those of existing compression algorithms. We also present a detailed functional block diagram of the C4 decoding algorithm as a first step towards a hardware realization.

Professor Avidoh Zakhor
Dissertation Committee Chair

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Chapter 1

Introduction

The subject of this thesis is data compression for maskless lithography. What does it mean? Why is it important? These are the questions we hope to answer in this chapter. To begin with, broadly speaking, this research is about making billions and billions of very small things, *of human design*, packed together into the space of a few centimeters and having them work together. We are referring to, of course, the microchip, but there may be other applications in the future.

The reason we emphasize *of human design* is that in the manufacturing of the microchip, it is not enough that a billion small things are created in a tiny space. They must be organized, placed, and connected in a precise configuration. The storage, transfer and transformation of this configuration *information*, from microchip design data stored on a computer, to a physical pattern of a microchip on a silicon substrate, is called "lithography," and it is the subject of our research. It is an intersection

between the world of data compression and information theory, and the world of microchip manufacturing.

In this introductory chapter, we hope to convey to the reader the problem of maskless lithography, in contrast to state-of-the-art photolithography used to make chips. In Section 1.1, we focus specifically on the data issues associated with maskless lithography. In Section 1.2, we explore the alternatives in designing a datapath for a maskless lithography system. In the process, we demonstrate that lossless compression plays an important role.

1.1 Microchip design and maskless lithography

VLSI designs produced by microchip designers consist of multiple layers of 2D geometries stacked vertically, one on top of another. Each layer is composed of a set of polygons, arranged in a plane, and the meaning of each layer is defined by a specific patterning step in a microchip manufacturing process. Consider the complexity of a typical 45nm microchip: it can have about 10 metallic wiring layers, 10 via layers connecting the metals at specific points, 1 gate layer defining the MOSFET gate, 1 layer defining source and drain regions, and about 20 layers defining various characteristics of the transistor, such as doping and strain.

However, despite the diversity of layer types, in each case, there is a step in the manufacturing process where the 2D image of the layer drawn by designers is transferred into a chemical pattern on the wafer where it can shape the physical

structures being created. This step is known as "lithography" and the predominant technology today for doing lithography is optical photolithography.

In optical photolithography, an image of a layer is first created onto a physical mask. Laser light is then projected through the mask, forming an image of the layer geometries on the wafer. The wafer has in turn been pre-treated with a thin layer of light sensitive chemical known as photoresist. The energy of the light creates a chemical reaction in the photoresist, changing its chemical properties where the light lands, while remaining untouched where there is no light. A chemical capable of distinguishing these chemical properties is then used to develop a physical image of the layer. This physical image is then used to form metal wires, via connections, transistor gates, and so forth depending on the specific purpose of that layer, as we described above.

One alternative to optical photolithography is pixel-based maskless lithography. In this system, the physical mask and optical projection is replaced by millions of tiny pixel writers, each capable of projecting a tiny pixel onto the wafer. By turning these pixels on, i.e. white, off, i.e. black, or partially on, i.e. shades of gray, a maskless lithography system can mimic the image formed by an optical lithography system, much like the way a computer monitor forms a photo-realistic image from little pixels on a screen. In this way, a pixel-based maskless lithography writer can duplicate the capability of optical photolithography, without the initial overhead of creating a physical mask. The primary advantage of using a pixel-based maskless writer, of

course, is that the image can be easily changed by changing the value of each pixel, whereas a mask once made is difficult to modify.

However, there are several caveats to this pixel-based maskless approach. While pixels can mimic the image of the mask, this is only true if the pixels are sufficiently small. This is the concept of resolution. If the pixel grid is so fine that all polygons on a given layer are aligned to the pixel grid, then it is possible to define each pixel completely covered by a polygon as *on (white)*, and pixels left uncovered as *off (black)*. The result is a sharp, black-and-white image, as shown in Figure 1.1. However, if the pixel grid is large, then polygon edges can leave pixels partially covered. In these cases, the typical strategy is to assign to the pixel a *partially on gray value* proportional to the percentage of area covered. The exact details of this procedure is described later in Chapter 2. This results in a "blurry" gray image shown in Figure 1.2. Of course, it is possible for the pixels to be larger than the minimum feature size on a layer, e.g. a thin 45nm line under a 65nm pixel. In this case, the 45nm line feature appears as a 65nm gray square, and the image content is completely lost.

To achieve a fine resolution, a pixel-based maskless lithography system must employ a massive array of lithography writers. Each writer prints a tiny pixel tens of nanometers large using, for example, a narrow electron beam (e-beam), ion beam, a nano-droplet of a chemical material, or extreme ultra-violet photons (EUV) deflected by a MEMS micro-mirror. One candidate, shown in Figure 1.3, uses a bank of 80,000 writers operating in parallel at 24 MHz [5]. These writers, stacked vertically in a

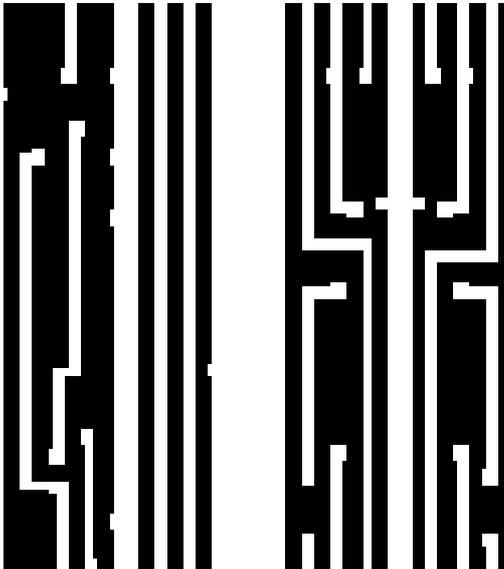


Figure 1.1: A sample of layer image data, with fine black-and-white pixels.

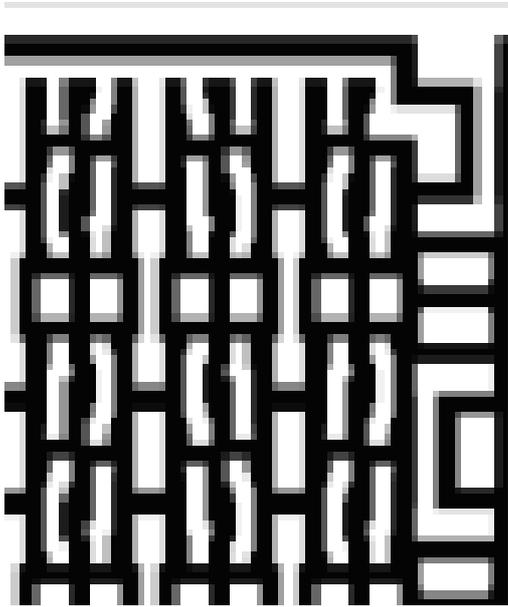


Figure 1.2: A sample of layer image data with coarse gray pixels.

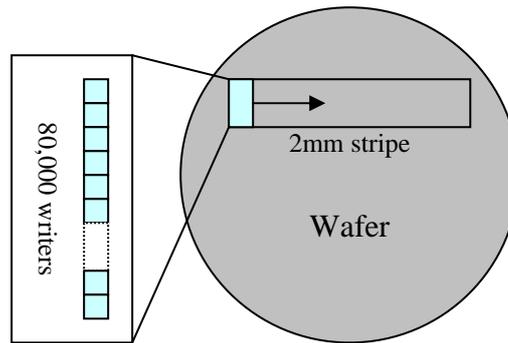


Figure 1.3: Hardware writing strategy.

column, would be swept horizontally back-and-forth across the silicon wafer, until an entire layer image is printed. Nonetheless a critical question that remains unanswered is *how to supply the necessary data to control this large array of writers*.

To gauge the data requirements of pixel-based maskless lithography, we compare it to today's state-of-the-art optical lithography systems. As described previously, optical lithography systems use a mask to project the entire image of a layer in one laser flash. Using optical projection, an entire silicon wafer can be printed with identical copies of the layer image in a few hundred such flashes. The total write time is one minute to cover one wafer with one layer (wafer layer).

In contrast, a pixel-based maskless lithography system writes the layer image one pixel at a time. For such a system to be competitive with optical lithography throughput of one wafer layer per minute, it must transfer trillions of pixels per second onto the wafer. In Table 1.1, we use an approximate specification for a hypothetical maskless lithography system for the 45 nm device generation, to form a rough projection of the data rates a pixel-based maskless lithography system would need to support.

Table 1.1: Specifications for the devices with 45 nm minimum features

Device specifications		Maskless specifications	
Minimum feature	45 nm	Pixel size	22 nm
Edge placement	≤ 1 nm	Pixel depth	5 bits / 32 gray
Chip size	10 mm \times 20 mm	Chip data (one layer)	2.1 Tb
Wafer size	300 mm	Wafer data (one layer)	735 Tb
Writing time (one layer)	60 s	Data rate	12 Tb/s

The first two columns of Table 1.1 presents an example of manufacturing requirements for devices with a 45 nm minimum feature size. To meet these requirements, the corresponding specifications for a maskless pixel-based lithography system are *estimated* on the last two columns of Table 1.1. For a layer with a minimum feature size of 45 nm, the estimate is that 22 nm pixels are required to achieve the desired resolution. This estimate is based on the industry rule-of-thumb that the pixel size less than half the minimum feature size, with the rationale that this allows independent placement and control of opposing edges of a line with minimum width. Sub-pixel edge placement control is then achieved by changing the gray pixel values, with one gray level corresponding to one edge placement increment. Assuming linear increments, 32 gray values, equivalent to 5 bits per pixel (bpp), is sufficient for $22/32 = 0.7$ nm edge placement accuracy. If we were to choose 4 bpp, then the edge placement accuracy would have been $22/16 \approx 1.4$ nm which is more coarse than the required 1 nm accuracy.

To understand why this kind of fine control over edge placement is necessary

requires some understanding of the manufacturing process. As an example, consider the illustration in Figure 1.4. Five MOSFET transistors are placed side-by-side, at a pitch of 120 nm. The transistor gates are the lines labeled (a) to (e), and the design calls for them to be identically 45 nm wide, which is our minimum feature. They are oriented vertically, lined up from left to right, spaced 75 nm apart from each other. Now, suppose the manufacturing process is such that the left-most and right-most lines in the sequence, on average, manufactures 2 nm smaller than the desired nominal 45 nm line. To counteract this effect, the solution is to enlarge the image of these outermost lines by 2 nm to 47 nm, but without reducing the minimum space between lines, because that minimum space is needed to fit the circular contacts. The solution can be implemented by moving the right edge of line (e) 2 nm to the right. Now suppose the 22 nm pixel grid happens to land on line (e) as shown by the dotted lines. Then the intensity of the pixels for a 45 nm line, from left to right is 40%, 100%, 60%. Now to move the right edge only by 2 nm, the right pixel intensity is increased from 60% to 69%. This corresponds to a 9% increase of the intensity of a 22 nm pixel, so $9\% \times 22nm = 2nm$ movement. Intuitively, it is reasonable that this change does not affect the left edge significantly, because the intervening 100% pixel isolates the influence of the right side from the left. In reality, a more rigorous proximity correction function would be needed to be computed, which depends on the specific physics of the maskless lithography system. In the concluding chapter of the thesis, we will come back to touch on the need for proximity correction. For

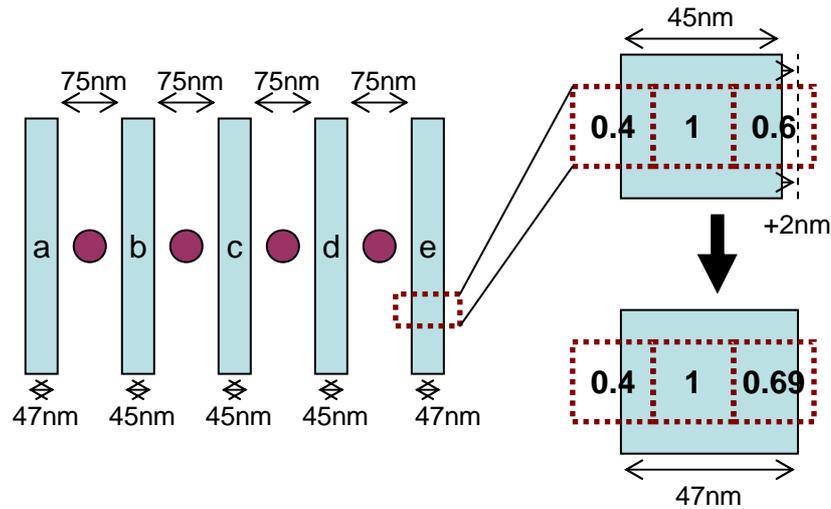


Figure 1.4: Fine edge control using gray pixels.

now consider this linear conversion from pixel intensity to edge movement to be a simplified model of reality.

Going back to Table 1.1, and using the pixel specifications there, a $10\text{ mm} \times 20\text{ mm}$ chip then represents $\frac{10\text{mm} \times 20\text{mm}}{\text{chip}} \times \frac{\text{pixel}}{22\text{nm} \times 22\text{nm}} \times \frac{5\text{bits}}{\text{pixel}} \approx 2.1\text{ Tb}$ of data per chip layer. A 300 mm wafer contains 350 copies of the chip, resulting in 735 Tb of data per wafer layer. This data volume is an extremely difficult to manage, especially considering a microchip has over 40 layers. Moreover, exposing one wafer layer per minute requires a throughput of $\frac{735\text{Tb}}{60\text{s}} \approx 12\text{ Tb/s}$, which is another significant data processing challenge. These tera-pixel writing rates force the adoption of a massively parallel writing strategy and system architecture. Moreover, as we shall see, physical limitations of the system place a severe restriction on the processing power, memory size, and data bandwidth.

1.1.1 Data representation

An important issue intertwined with the overall system architecture is the appropriate choice of data representation at each stage of the system. The chip layer delivered to the 80,000 writers must be in the form of pixels. Hierarchical formats, such as those found in GDS, OASIS, or MEBES files, are compact as compared to the pixel representation. However, converting the hierarchical format to the pixels needed by the writers in real time requires processing power to first flatten the hierarchy into polygons, and then to rasterize the polygons to pixels. An alternative is to use a less compact polygon representation, which would only require processing power to rasterize polygons to pixels. Flattening and rasterization are computationally expensive tasks requiring an enormous amount of processing and memory to perform. The following sections examine the use of all of these three representations in our proposed system: pixel, polygon, and hierarchical.

1.2 Maskless Lithography System Architecture Designs

1.2.1 Direct-connection architecture

The simplest design, as shown in Figure 1.5, is to connect the disks containing the chip layer directly to the writers. Here, the only choice is to use a pixel representa-

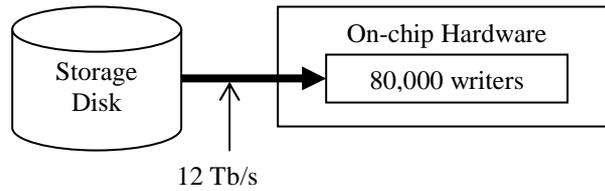


Figure 1.5: Direct connection from disk to writers.

tion because there is no processing available to rasterize polygons, or to flatten and rasterize hierarchical data. Based on the specifications, as presented in 1.1, the disks would need to output data at a rate of 12 Tb/s. Moreover, the bus that transfers this data to the on-chip hardware must also carry 12 Tb/s of data. Clearly this design is infeasible because of the extremely high throughput requirements it places on storage disk technology.

1.2.2 Memory architecture

The second design shown in Figure 1.6 attempts to solve the throughput problem by taking advantage of the fact that the chip layer is replicated many times over the wafer. Rather than sending the entire wafer image in one minute, the disks only output a single copy of the chip layer. This copy is stored in memory fabricated on the same substrate as the hardware writers themselves, so as to provide data to the writers as they sweep across the wafer. Because the memory is placed on the same silicon substrate as the maskless lithography writers, the 12Tb/s data transfer rate should be achievable between the memory and the writers. The challenge here is to be able to cache the entire chip image for one layer, estimated in Table 1.1 to be 2.1

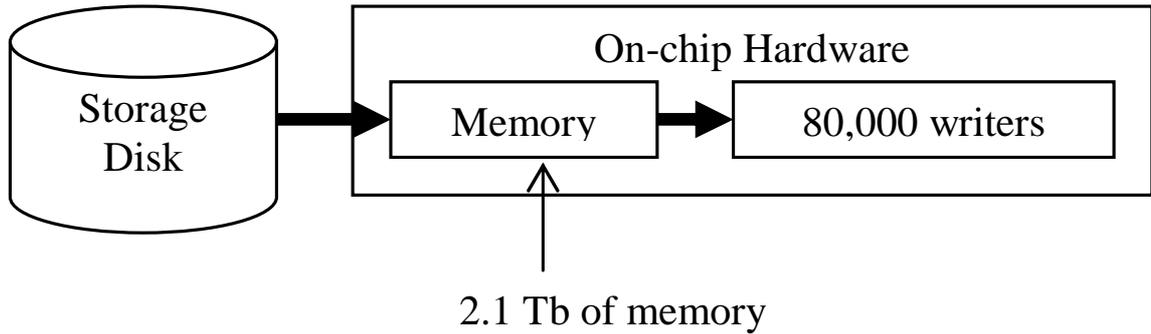


Figure 1.6: Storing a single microchip layer in on-chip memory.

Tb of data, while the highest density DRAM chip available, we estimate will only be 16 Gb in size [24]. This option is likely to be infeasible because of the extremely large amount of memory that must be present on the same die as the hardware writers.

1.2.3 Compressed memory architecture

One way to augment the design in Figure 1.6 is to apply compression to the chip layer image data stored in on-chip memory. This may be in the form of a compact hierarchical polygonal representation of the chip, such as OASIS, GDS, or MEBES, or it may utilize one of the many compression algorithms discussed in this thesis. Whatever the case may be, this data cannot be directly used by the pixel-based maskless direct-write writers without further data processing. In Figure 1.7, we have added additional processing circuitry to the previous design, called “on-chip decoder”, which shares data with the on-chip memory and writers. This decoder performs whatever operations are necessary to transform the data stored in on-chip memory, into the pixel format required by the writers. If OASIS, GDS, or MEBES

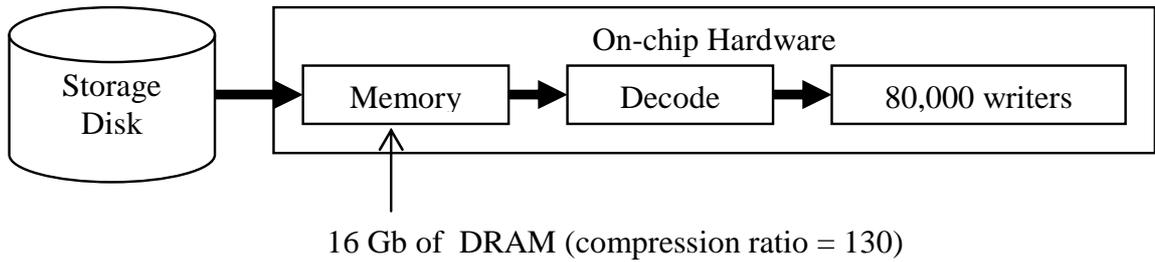


Figure 1.7: Storing a compressed chip layer in on-chip memory.

is used, then the decoder must flatten the hierarchy and rasterize the polygons into pixels. If image compression is used, then the decoder must decompress the data.

The problem with the design in Figure 1.7 is that it is extremely difficult to fit such complex decoding circuitry on the chip, while sharing area on the substrate with the memory and writers. Even if all the on-chip area is devoted to memory, the maximum memory size that can be realistically built on the same substrate as the writers is about $16Gb$, resulting in a required compaction/compression ratio of about $\frac{2.1Tb}{16Gb} \approx 130$, already a challenging number. To make room for the decoder, we would need to reduce the amount of on-chip memory, forcing the compression target even higher. Generally speaking, to get a higher compaction/compression ratio would require even more complex algorithms, resulting in complex larger decoding circuitry. The result is a no-win situation where compression, adds to the problem at hand, i.e. lack of memory.

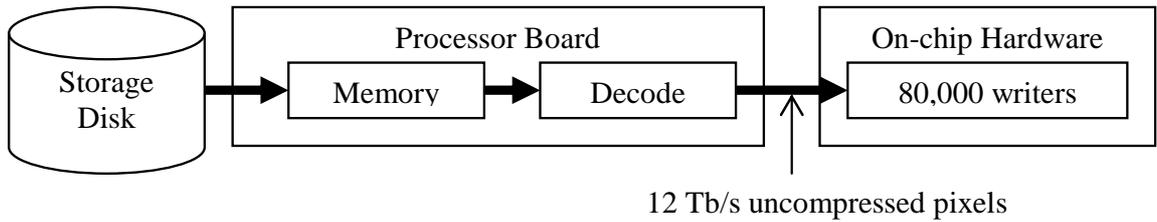


Figure 1.8: Moving memory and decode off-chip to a processor board.

1.2.4 Off-chip compressed memory architecture

To resolve the competition for circuit area between the memory and the decoder, it is possible to move the memory and decoder off the writer chip onto a processor board, as shown in Figure 1.8. Now multiple memory chips are available for storing chip layer data, and multiple processors are available for performing decompression, rasterization, or flattening. However, after decoding data into the bitmap pixel domain, the transfer rate of data from the processor board to on-chip writers is once again 12 Tb/s. The anticipated state-of-the-art board-to-chip communications for this device generation is expected to be 1.2 Tb/s, e.g. 128 pins at 6.4 Gb/s [23]. This represents about a factor of $\frac{12\text{Tb/s}}{1.2\text{Tb/s}} \approx 10$ difference, between the desired pixel data rate to the writers and the actual rates possible. A factor of 10 slowdown in throughput, while not desirable, is within the realm of possibility, taking into consideration that the values in Table 1.1 are approximate, and that industry may be willing to accept a slower wafer throughput in exchange for the flexibility a maskless approach provides. Nonetheless, it is still worth considering whether there is an alternative that does not require this sacrifice in throughput.

1.2.5 Off-chip compressed memory with on-chip decoding architecture

The drawback of the previous approach, is the burden of communicating decompressed data from a processing board to the chip containing the maskless lithography writers. By moving the decoding circuitry back on-chip, and leaving the memory off-chip, this board-to-chip communication can now be performed in a compressed manner, improving the effective throughput. This new architecture is shown in Figure 1.9. Analyzing the system from the right to the left, it is possible to achieve the 12 Tb/s data transfer rate from the decoder to the writers because they are connected with on-chip wiring, e.g. 20,000 wires operating at 600 MHz. The input to the decoder is limited to 1.2 Tb/s, limited by the communication bandwidth from board to chip, as mentioned previously. The data entering the on-chip decoder at 1.2 Tb/s must, therefore, be compressed by at least 10 to 1, for the decoder to output 12 Tb/s. The decoding circuitry is limited to the area of a single chip, and must be extremely high throughput, so complex operations such as flattening and rasterization should be avoided. Thus, to the left of the on-chip decoder, the system uses a 10 to 1 compressed pixel representation in the bitmap domain.

In summary, there are several key challenges that must be met for the design of Figure 1.9 to be feasible. The transfer of data from the processor board to the writer-decoder chip is bandwidth limited by the capability of board to chip communications. The anticipated state-of-the-art board-to-chip communications for this device gener-

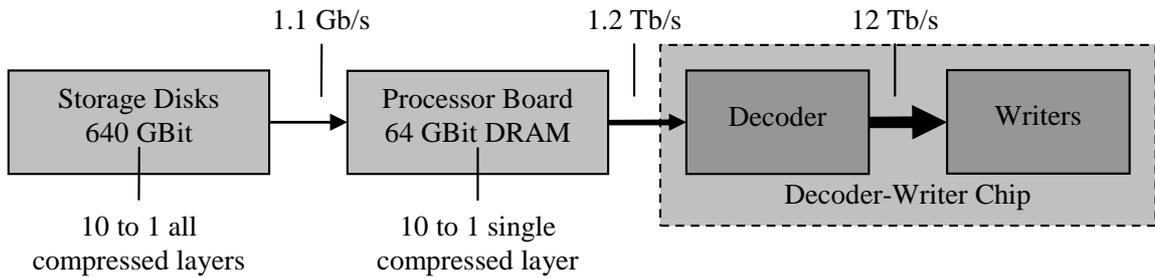


Figure 1.9: System architecture of a data-delivery system for maskless lithography.

ation is 1.2 Tb/s, e.g. 128 pins at 6.4 Gb/s. The first challenge is to maximize the input data rate available to the decoder-writer chip.

On the other hand, the decoder-writer chip is required to image 2.4 Tpixel/s to the wafer to meet the production throughput target of one wafer per layer per minute achieved by today's mask based lithography writers. Assuming each pixel can take a gray value from 0 to 31, and a standard 5-bit binary representation, the effective output data rate of the decoder-writer chip is about 12 Tb/s. The shortfall between the input data rate and the output data rate is reconciled through the use of data compression, and a quick division, $\frac{12Tb/s}{1.2Tb/s} \approx 10$, yields the required average compression ratio. This is the second challenge, i.e. developing lossless compressed representations of lithography data over 10 times smaller than the 5-bit gray pixel representation.

The third challenge involves the feasibility of building a decoder circuitry, a powerful data processing system in its own right, capable of decoding an input data rate of 1.2 Tb/s to an output data rate of 12 Tb/s. These data rates are many times larger than that achieved by any single chip decoding circuitry in use today. Moreover, this

is not merely a challenge to the creativity and competence of the hardware circuit designer. Depending on the compression algorithm used, the decoding circuitry has different buffering, arithmetic, and control requirements, and in general, higher compression ratios can be achieved at a cost of greater amount of hardware resources and longer decoding times, both of which are limited in this application. The decoder circuitry must share physical chip space with the writers, and it must operate fast enough to meet the extremely high input/output data rates. These observations are intended to establish the groundwork for discussion of feasibility and tradeoffs in the construction of a maskless lithography data delivery system, as well as approximate targets for research into meeting the three challenges outlined in this section.

The first challenge, though important, is answered by the evolution of chip I/O technologies of the computer industry [23], which is beyond the scope of this thesis. Chapter 2 answers the second challenge by presenting and evaluating the compression ratio achieved on modern industry lithography data by a spectrum of techniques: industry standard image compression techniques such as JBIG [8] and JPEG-LS [16], wavelet techniques such as SPIHT [21], general byte stream compression techniques such as Lempel-Ziv 1977 (LZ77) [6] as implemented by ZIP, Burrows-Wheeler Transform (BWT) [15] as implemented by BZIP2 and RECT, an inherently compressed representation of a chip layer as a list of rectangles. JBIG, ZIP, and BZIP2 are found to be strong candidates for application to maskless lithography data.

Chapter 3 is a overview of 2D-LZ, another compression algorithm previously de-

veloped by us for compressing maskless lithography data [3]. The basic idea behind 2D-LZ is to expand on the success of the LZ-algorithm used in ZIP, and compress using a 2D dictionary, taking advantage of the fact that layer image is inherently 2 dimensional. This strategy works to a certain extent; very good compression results are achieved for repetitive layouts, but for non-repetitive layouts, both LZ77 and 2D-LZ perform worse than JBIG.

Chapter 4 expands on knowledge gained in Chapter 2 and 3 to develop novel custom compression techniques for layer image data. Learning from the experience of 2D-LZ and JBIG and the characteristics of layer images which each takes advantage of, another novel compression technique is developed, Context-Copy-Combinatorial-Coding (C4). The “Context” refers to the context based prediction technique used in JBIG. The “Copy” refers to the dictionary copying technique used in 2D-LZ and its predecessor, LZ77. The “Combinatorial” coding is a computationally simpler replacement for the arithmetic entropy coder used in JBIG. C4 is designed with a simple decoder, suitable for implementation in the architecture in Figure 1.9. It also successfully captures the advantages of both JBIG and 2D-LZ to exceed the performance of both, and on industry test layer images, C4 meets the compression ratio requirement of 10 for all types.

Chapter 5 describes Block C4, a variation of C4 which improves the encoding speed by over 100, with little or no loss in compression efficiency. Even though encoding speed is not an explicit bottleneck of the architecture in Figure 1.9, because

it is performed off-line, C4 encoding, as presented in Chapter 4 is so slow, that a full-chip encoding is estimated to take over *18 CPU years*. While the C4 compression complexity is not impossible to meet, using 520 CPUs, to reduce runtime to 1.8 weeks, Block C4 takes this a step further and speeds up compression by a factor of $100\times$ to a very reasonable 49 CPU days, i.e. less than a day on a 100-CPU computing cluster.

Chapter 7 answers the third challenge, and tackles the problem of implementing the decoder circuitry for C4. The C4 decoding algorithm is successively broken down into hardware blocks until the implementation for each block becomes clear.

Finally, Chapter 8 summarizes the research presented in this thesis, and points out several avenues for future research.

Chapter 2

Data Compression Applied to Layer Data

As described in Chapter 1, for a next-generation 45-nm maskless lithography system, using 22 nm, 5-bit gray pixels, a typical image of only one layer of a $2\text{cm} \times 1\text{cm}$ chip represents 2.1 Tb of data. A direct-write maskless lithography system with the same specifications requires data transfer rates of 12 Tb/s in order to meet the current industry production throughput of one wafer per layer per minute. These enormous data sizes, and data transfer rates, motivate the application of lossless data compression to microchip layer data.

2.1 Hierarchical flattening and rasterization

VLSI designs produced by microchip designers consist of multiple *layers* of 2-D polygons stacked vertically, representing wires, transistors, etc. The de-facto file format for this data, GDS, organizes this geometric data as a hierarchy of cells. Each cell contains a list polygons, and a list of references to other cells, forming a tree-like hierarchy. Each polygon is represented by a sequence of (x, y) coordinates of its vertices, and a layer number representing its vertical position on the stack.

The GDS data format is different from the data format required by the writers in Figure 1.3 of Chapter 1. They require control signals in the form of individual pixel intensities. To convert GDS data to pixel intensities requires two data processing steps. The first is *flattening*, where each cell reference is replaced by the list of polygons they represent, removing the hierarchical structure. The next is layer-by-layer *rasterization*, where all polygons on a layer are drawn to a pixel grid. These two steps are compute intensive, and are typically performed by multiprocessor systems with large memories and multiple boards of dedicated rasterization hardware.

The GDS format is in fact, a compact representation of the microchip layer, which can be further compressed as in [20], or OASIS [25]. This immediately raises the question as to whether the GDS can be used as a possible candidate for the compression scheme needed by Figure 1.9 of Chapter 1. Closer examination though reveals that this is not a feasible option. Specifically, a GDS type representation stored on disk, would require the decoder-writer chip to perform both hierarchical

flattening and rasterization in real-time. We believe that performing these operations, traditionally done by powerful multi-processor systems over many hours, with a single decoder-writer chip is impractical.

The alternative approach adopted in this thesis is to perform both hierarchical flattening and rasterization off-line, and then apply compression algorithms to the pixel intensity data. This approach offers a number of advantages. First, the decoder only needs to perform decompression, greatly simplifying its design. Second, any necessary signal processing, such as proximity correction or adjusting for resist sensitivity, can be computed off-line and incorporated into the pixel-intensity data before compression.

It is possible to adopt an approach in-between the two extremes, in which a fraction of the flattening and rasterization operation is performed off-line, and the remainder is performed in real-time by decoder-writer chip. Alternatives include adopting a more limited hierarchical representation that involves only simple arrays or cell references, or organizing rectangle and polygon information into a form that is easily rasterized. Nonetheless it is unclear whether such representations offer either higher compression ratios or simpler decoding than the compressed pixel representation. As an example, a naïve list-of-rectangles representation, described shortly in Section 2.4.6 as RECT, does not, in fact, offer more compression for the layouts tested, as shown later in Table 2.2 of Section 2.6.

2.2 Effect of rasterization parameters on compression

The goal of rasterization is to convert polygonal layer data into pixel intensity values which can be directly used to control the pixel-based writers themselves. Therefore, parameters of rasterization, such as the pixel-size and the number of gray-values, are specified by the lithography writer. Ideally, these parameters would be independent of the layer data itself, but in practice, such is not the case. For example, it is possible to write 300 nm minimum feature data with a state-of-the-art 50 nm maskless lithography writer using 25nm pixels, but doing so is extremely cost inefficient. Realistically speaking, lithography data is designed with some writer specification in mind, though this is not explicitly stated in the GDS file. Hence, compression results should be reported with this target pixel size in mind.

What is troublesome about this situation is that compression ratios are data dependent, and it is entirely possible to report inflated compression ratios by artificially rasterizing the same GDS data to a grid finer than the target pixel size the designers have in mind. However, because the target pixel size is not explicitly stated, it is difficult to ascertain whether this is or is not the case. For the layouts which we report compression results on, the writer specification is obtained from the microchip owner, or is deduced from the GDS file by measuring the minimum feature of the data. In all cases, time and effort is taken to verify that in each layer image, there

exists some feature which is two-pixels wide, corresponding to the two-pixels per minimum feature rule-of-thumb for pixel-based lithography writers, described previously in Chapter 1.

GDS files specify their polygons and structures on a 1 nm grid rather than the pixel grid described above. However, most layouts are built on a coarser address-grid that determines exact edge placement, in addition to the pixel grid defined by the minimum feature described above. When the edge-placement grid is equal to the pixel grid, then each pixel will be entirely covered, or uncovered by polygons. The straightforward interpretation is to translate fully covered pixels as white, and fully uncovered pixels as black, and the resulting rasterized layer image is a black-and-white binary image. Note, that although straightforward, this is in fact an interpretation or model of the way that pixels print, which we refer to as the “binary pixel printing model”. This is made more clearly in the following discussion.

When the edge-placement grid is finer than the pixel grid, then the possibility exists for a pixel to be partially covered by a polygon. How should we interpret this? In reality, what needs to be understood is that the polygon represents the *target shape a designer would like to put on the wafer*. Even though we interpret the 2D-array of pixels intensities as an image, all they truly represent are the intensity settings of individual maskless lithography pixel writers. The ideal solution is to provide the set of pixel intensities which most faithfully reproduces the polygon target on the wafer. The computation needed to find such a solution is generally known as proxim-

ity correction or inverse lithography, and it requires some model or prior knowledge of the transfer function from pixels to polygon shape. For optical projection systems, this transfer function is the well-known transmission cross coefficient (TCC), in conjunction with resist thresholding [37]; but for maskless lithography systems which are non-optics based, this transfer function may be something else entirely. The consideration of proximity correction depends on the physics of an actual maskless lithography system, a good example of which is found in [28] where a pixelized Spatial Light Modulator is used. For this thesis however, we focus on an “idealized pixel printing model” illustrated in Figure 2.1.

The starting point for this model is the binary pixel printing model, as illustrated in the top part of the figure. In this model a column of 2 adjacent pixels, fully on, prints a vertical line exactly 2 pixels wide aligned to the pixel grid. If the pixels are 22nm in size, then the line is 44nm wide. This is a reasonable assumption, based essentially on the definition of a “pixel”. Now, suppose in this simple one dimensional case, a third column of pixels is turned 20% on, as shown in the lower part of the figure. In this case, the printing model makes an idealization that this shifts the right edge of the line by exactly $20\% \times 22 \text{ nm pixel size} = 4.4\text{nm}$ to the right, printing a 48.4nm line.

Why does this seem reasonable? At one level, it is consistent with the intuition provided by the “binary pixel printing model”, in that if we extrapolate further, and turn the third column of pixels 100% on, the resulting prediction that the line edge

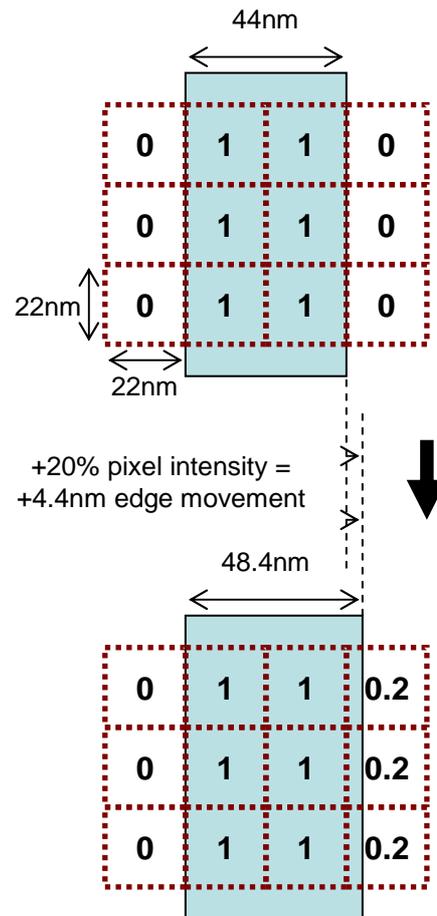


Figure 2.1: An illustration of the idealized pixel printing model, using gray values to control sub-pixel edge movement.

moves $100\% \times 22 \text{ nm pixel} = 22 \text{ nm}$ to the right, resulting in a 66 nm line, which coincides with an exactly 3-pixel linewidth. In addition, this behavior approximates the behavior of electron beam and laser based mask writers which use similar pixel-like elements [29] [30] [31] [32] [33]. In each of these cases, an e-beam or laser beam spot creates a 2D Gaussian-like intensity distribution centered on the pixel. Intensities can be modulated using either multiple-exposures, or through modulation of the e-beam or laser-beam itself. Intensities from neighboring pixels add in such a way that after physical image is developed in a thresholding process, a partially "on" pixel shifts the printed line edge, in a manner that closely approximates the idealized pixel printing model. In fact, the e-beam or laser-beam shape is often chosen specifically to approximate the model as closely as possible. Deviations from this model is often "corrected" in software.

The reason the "ideal pixel printing model" is so attractive from an implementation perspective, is that it is easily inverted, so that the correct gray pixel value can be computed easily from a polygon shape. Consider again Figure 2.1, except let us invert the model and ask the question, "What pixel value will move the right edge by 4.4nm?" The answer can easily be computed by finding the fraction $4.4 \text{ nm} / 22 \text{ nm pixel} = 0.2$. So in the case of lines, the gray value can be computed by the linear fraction of the pixel covered by the edge of the line. Extending this rationale for an arbitrary 2D polygon, the gray value should be the area fraction of the pixel covered by the polygon. The final step is to quantize the area fraction to the nearest integer

fraction of the number of pixel gray values. For example, suppose our 22 nm pixels have 33 gray values, 0 to 32. Then $6/32 = 0.19$ is the closest integer fraction, so the pixel value would be $6/32$ often abbreviated to just 6, preserving only the numerator.

2.3 Properties of layer images and their effect on compression

After the rasterization process described in the previous section, the design data has been converted to a *layer image* which can be directly passed along to the writers. We ignore for the moment what would happen if this is not the case and some proximity function needs to be applied as in [28] instead of the idealized pixel model described in the previous section. This is taken into consideration later when compression is applied to proximity corrected data in Chapter 6.

In a layer image, pixels may be binary or gray depending on both the design of the writer and the choice of coarse or fine grids. A magnified sample of a binary image is shown in Fig. 2.2(a) and a gray image is shown in Fig. 2.2(b).

Clearly, these lithography images differ from natural or even document images in several important ways. They are synthetically generated, highly structured, follow a rigid set of design rules, and contain highly repetitive regions cells of common structure. Consequently, we should not expect existing compression algorithms, designed for natural or document images, to take full advantage of the properties of layer im-

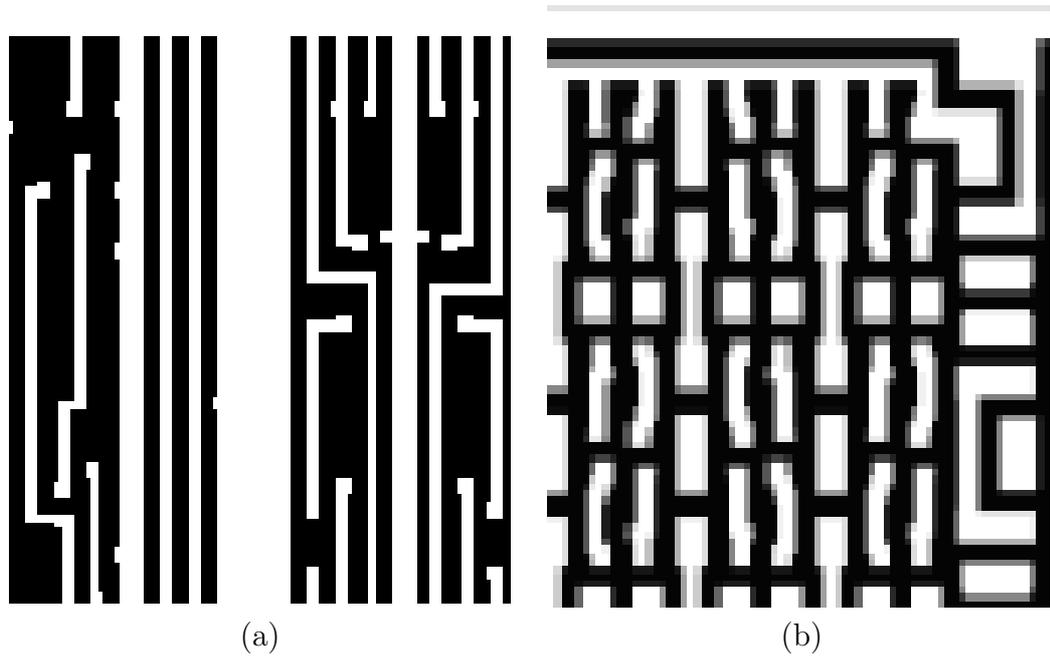


Figure 2.2: A sample of layer image data (a) binary and (b) gray.

ages. Nonetheless, applying a spectrum of existing techniques to layer images has its own merit: it provides a basis for comparison, and the efficacy of each technique provides insight into the properties of layer image data. The techniques considered here are as follows: industry standard image compression techniques such as JBIG [8] and JPEG-LS [16], wavelet techniques such as SPIHT [21], general byte stream compression techniques such as Lempel-Ziv 1977 (LZ77) [6] as implemented by ZIP, Burrows-Wheeler Transform (BWT) [15] as implemented by BZIP2, and RECT, an inherently compact representation of a microchip layer as a list of rectangles. Among these, JBIG, ZIP, and BZIP2 are found to be strong candidates for application to layer image data.

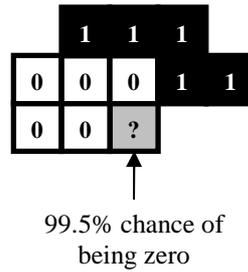


Figure 2.3: Example of 10-pixel context-based prediction used in JBIG compression.

2.4 A Spectrum of Compression Techniques

First, we begin with a brief overview of each of the aforementioned existing techniques.

2.4.1 JBIG

JBIG is a standard for lossless compression of binary images, developed jointly by the CCITT and ISO international standards bodies [8]. JBIG uses a 10-pixel context to estimate the probability of the next pixel being white or black. It then encodes the next pixel with an arithmetic coder [19] based on that probability estimate. Assuming the probability estimate is reasonably accurate and heavily biased toward one color, as illustrated in Figure 2.3, the arithmetic coder can reduce the data rate to far below one bit per pixel. The more heavily biased toward one color, the more the rate can be reduced below one bit per pixel, and the greater the compression ratio. JBIG is used to compress binary layer images.

2.4.2 Set Partitioning in Hierarchical Trees (SPIHT)

The lossless version of Set Partitioning in Hierarchical Trees (SPIHT) [21] is based on an integer multi-resolution transform similar to wavelet transformation designed for compression of natural images. Compression is achieved by taking advantage of correlations between transform coefficients. SPIHT is a state-of-the-art lossless natural image compression technique, and is used in this research to compress gray-pixel layer images.

2.4.3 JPEG-LS

JPEG-LS [16], an ISO/ITU-T international standard for lossless compression of grayscale images, adopts a different approach, using local gradient estimates as context to predict the pixel values, achieving good compression when the prediction errors are consistently small. It is another state-of-the-art lossless natural image compression technique. used to compress gray-pixel layer images.

2.4.4 Ziv-Lempel 1977 (LZ77, ZIP)

ZIP is an implementation of the LZ77 compression [6] method used in a variety of compression programs such as pkzip, zip, gzip, and WinZip. It is highly optimized in terms of both speed and compression efficiency. The ZIP algorithm treats the input as a generic stream of bytes; therefore, it is generally applicable to most data formats, including text and images.

Stream of bytes	LZ77 code
<i><u>on the disk.</u></i> <u>these</u> disks	-> (copy,10,4)
<i><u>on the disk.</u></i> <i><u>these</u></i> disks	-> (literal,s)
<i><u>on the disk.</u></i> <i><u>these</u></i> <u>disks</u>	-> (copy,12,5)

Figure 2.4: Example of copying used in LZ77 compression, as implemented by ZIP.

To encode the next few bytes, ZIP searches a window of up to 32 kilobytes of previously encoded bytes to find the longest match. If a long enough match is found, the match position and length is recorded; otherwise, a literal byte is encoded. An example of ZIP in action is shown in Figure 2.4. The first column is the stream of bytes to be encoded, and the second column is the LZ77 encoded stream. The rows represent 3 stages in the encoding process; characters in bold-italics have already been encoded. Matches and literals are underlined. At stage 1, “the” matches 10 bytes back, with a match length of 4 bytes. The resulting LZ77 codeword is (copy,10,4). At stage 2, the only match available is the “s” which is too short. Consequently, the resulting codeword is (literal,s). At stage 3, “e disk” matches 12 bytes back, with a match length of 5 bytes. The resulting codeword is (copy,12,5). The LZ77 codeword is further compressed using a Huffman code [22].

In the example in Figure 2.4, recurring byte sequences represents recurring words, but applied to image compression recurring byte sequences represent repeating pixel patterns, i.e. repetitions in the layer. In general, longer matches and frequent repetitions increase the compression ratio. ZIP is used to compress both binary and gray-pixel images. For binary layer images, each byte is equivalent to 8 pixels in

sort key			sort key	
c	ompression	sort rows by key →	n	compressio
o	mpressionc		r	essioncomp
m	pressionco		s	ioncompres
p	ressioncom		o	mpressionc
r	essioncomp		o	ncompressi
e	ssioncompr		c	ompression
s	sioncompre		i	oncompress
s	ioncompres		m	pressionco
i	oncompress		p	ressioncom
o	ncompressi		s	sioncompre
n	compressio		e	ssioncompr

Figure 2.5: BZIP2 block-sorting of “compression” results in “nrsoocimpse”.

raster scan order. For gray-pixel layer images, each byte is equivalent to one gray-pixel value.

2.4.5 Burrows-Wheeler Transform (BWT)

BZIP2 is an implementation of the Burrows-Wheeler Transform (BWT) [15]. Similar to ZIP, BZIP2 is a general algorithm to compress a generic stream of bytes and is generally applicable to most data formats, including text and images. Unlike ZIP, BIZP2 uses a technique called block-sorting to permute a sequence of bytes to make it easier to compress. For illustration purposes, we apply BZIP2 to text strings in Figures 2.5 and 2.6.

Under block-sorting, each character in a string is sorted *based on the string of bytes immediately following it*. For example, in Figure 2.5, the characters of the string “compression” are block-sorted. The sort key for “c”, is “ompression”, the sort key for “o” is “mpressionc”, etc. Since “ompression” comes 6th in lexicographical order,

	sort key
:	
t	ion (x,y) ...
s	ion of th ...
s	ion ratio ...
g	ion speci ...
s	ions, cap ...
g	ions, fre ...
:	

Figure 2.6: BZIP2 block-sorting applied to a paragraph.

“c” is the 6th letter of the permuted string; “mpressionc” comes fourth, so “o” is the fourth letter; etc. The block sorting result is the permuted string “nrsoocimpse”, which is in fact, not any easier to compress than “compression”! For block sorting to be effective, it must be applied to very long strings to produce an appreciable effect. Using, for example, the previous paragraph as a string, Figure 2.6 illustrates the effect of block sorting. Because the sub-strings “gion”, “sion”, and “tion” occur frequently, the sort keys beginning with “ion...” groups “g”, “s”, and “t” together. The resulting permuted string “...tssgsg ...” is easy to compress using a simple adaptive technique called move-to-front coding [15]. In general, the longer the block of bytes, the more effective the block-sorting operation is at grouping, and the greater the compression ratio. The standard BZIP2 implementation of the BWT [38], for example, allows block sizes ranging from 100KB to 900KB. This is in sharp contrast to the memory requirement of LZ77, which only requires about 4KB of memory to be effective. While these numbers are trivial in terms of implementation on a microprocessor, it becomes prohibitively large when the implementation is a small

hardware circuit fabricated on the same substrate as an array of maskless lithography writers.

2.4.6 List of rectangles (RECT)

RECT is not a compression algorithm, but simply an inherently compressed representation. Each layer image is generated from the rasterization of a collection of rectangles. Each rectangle is stored as a four 32-bit integers $(x, y, width, height)$, along with the necessary rasterization parameters, resulting in a compressed representation of the image data. As stated in Section 2.1, the drawback of this approach is that decoding this representation involves the complex process of rasterization in real-time.

2.5 Compression results of existing techniques for layer image data with binary pixels

To test the compression capability of these compression techniques JBIG, JPEG-LS, SPIHT, ZIP, BZIP2 and RECT, we have generated several images from different sections of various microchip layers, based on rasterization of industry GDS files. The first GDS file consists of rectangles with a minimum feature of 600 nm, aligned to a coarse 300 nm edge-placement grid. Using the methodology described in Section 2.2, this data is rasterized to a 300 nm pixel grid, producing a black-and-white binary

layer image. Image blocks 2048-pixel wide and 2048-pixel tall are sampled across each microchip layer. Each image represents a 0.61 mm by 0.61 mm section of the chip, covering about 0.1% of the chip area.

3 image samples are generated across each each layer, chosen by hand to cover different areas of the chip design, *Memory*, *Control*, and a mixture of both *Mixed*. The reason for hand sampling rather than random sampling has to do with limited memory available to the hardware decoders as described in Chapter 1. Specifically, because of limited memory, the compression ratio must be above a certain level across all portions of the layer as much as possible. Consequently, by hand sampling, we target areas of the design with a high density of geometric shapes which are difficult to compress, in contrast to blank areas of the chip design, which are trivial to compress.

Similarly, the 3 layers sampled are the polysilicon layer (Poly) used to form transistor gates, and the primary and secondary wiring layers, Metal 1 and Metal 2 used for wiring connections. In particular, Poly and Metal 1 are “critical layers”, and much of the effort of designing a chip goes into these layers. The layout for these layers resemble dense maze like structures of thin lines and spaces. Consequently, they have high density of geometric shapes per unit area, and are difficult to compress. Metal 2 is a higher level metal layer with thicker wires and larger spaces, and therefore, it is considerably less dense.

The compression results for these binary image samples are show in Table 2.1. The first column is the name of the horizontal sample across a layer. “Memory” layout

Table 2.1: Compression ratios for JBIG, ZIP, and BZIP2 on 300 nm, binary layer images.

Type	Layer	JBIG	ZIP	BZIP2
Memory	Metal 2	58.7	88.0	171
	Metal 1	9.77	47.9	55.5
	Poly	12.4	50.7	82.5
Control	Metal 2	47.0	22.1	24.4
	Metal 1	20.0	10.9	11.2
	Poly	41.6	18.9	23.2
Mixed	Metal 2	51.3	28.3	39.4
	Metal 1	21.2	11.9	12.1
	Poly	41.3	22.9	27.8

consists of densely arrayed, regularly repeating cells. “Control” layout is irregular and less dense compared to memory. “Mixed” layout comes from a section of a chip that contains some control intermingled with the memory cells. The second column is the chip layer from which the sample is drawn. Compression ratios of JBIG, ZIP, and BZIP2 are on columns 3 to 5, respectively. Each row represents compression ratios for each of the sample binary layer images. As explained in Section 1.2, the approximate compression ratio target, in order to achieve a throughput of one wafer layer per minute, is 10. Ratios less than this threshold are highlighted in boldface.

Examining the column 3 of Table 2.1 reveals that JBIG performs better on control, mixed type layouts than on memory. It also performs better on metal 2 than on metal 1 and poly. These layer images are sparser in terms of polygon density. In particular, JBIG’s performance is lowest when applied to the most dense regular layout, Metal 1 Memory. Even though the memory cells are very repetitive, JBIG’s limited ten-pixel context is not enough to model this repetition of cells. Conceptu-

ally, we could increase the context size of the JBIG algorithm until it covers an entire repetition cell. However, the complexity of JBIG's context-based prediction mechanism increases exponentially with the number of context pixels; so it is infeasible to use more than a few tens of pixels, whereas cells easily span hundreds of pixels. The effectiveness of JBIG-style prediction is explored more thoroughly in Chapter 4, when we describe a compression algorithm custom tailored to layer image data. For now, the key observation is that JBIG's compression efficiency is inversely proportional to geometric density.

In contrast to JBIG, ZIP's compression ratios, shown in column 4, suggest that it is well suited to compressing memory layout, exhibiting compression ratios of 50 or higher. The repetition of memory cells allows the ZIP algorithm to find plenty of long matches, which translates into high compression ratios. On the other hand, ZIP performs poorly on irregular layouts found in control and mixed layouts. For these, ZIP is unable to find long matches, and frequently outputs literals, resulting in performance loss in these areas. We examine the effectiveness of ZIP-style copying more thoroughly in Chapter 3, which extends the effectiveness of ZIP (LZ77) copying to two dimensional copy regions for image data.

In general the compression ratio of BZIP2 follows a pattern similar to ZIP across the layer image samples, but with larger compression ratios. Block-sorting takes advantage of the same repetition structure that ZIP does, but more efficiently, in part because it operates on a significantly larger block of data, from 100KB to 900KB. This

is in contrast to the 4KB of memory which ZIP uses. The tradeoff between decoder memory and compression efficiency is explored more thoroughly when we examine implementation issues associated with the architecture presented in Figure 1.9.

Examining Table 2.1 row-by-row, it is evident that for each layer image sample, at least one algorithm achieves the compression ratio target of 10. However, these compression results are reported for an image with binary pixels, whereas the compression ratio requirement of 10 is determined for an image with gray pixels. Certainly, if a particular layer with 50 nm minimum feature size could be rasterized using 25 nm pixels with black-and-white pixels, so that all edges are aligned on a 25 nm grid, for that layer, the required output data rate can be reduced by a factor of 5. This can potentially reduce the compression ratio requirement to 5, which is easily achieved by all the techniques tested in Table 2.1. All four compression techniques remain strong candidates for application to maskless lithography. To better extrapolate compression ratio achievable on future lithography data, we next consider the compression results of more modern layer data.

2.6 Compression results of existing techniques for layer image data with gray pixels

More recently, we have obtained the use of a GDS file containing the active layer data of a piece of modern industry microchip with the understanding that this layer

Table 2.2: Compression ratios for SPIHT, JPEG-LS, RECT, ZIP, BZIP2, on 75 nm, 5 bpp data

Image	SPIHT	JPEG-LS	RECT	ZIP	BZIP2 (100K)	BZIP2 (900K)
active_a	8.44	9.27	33.9	45.7	227	227
active_b	9.69	9.76	61.1	61.1	497	800
active_c	5.00	5.31	18.7	46.4	296	518
active_d	7.44	8.45	24.5	60.1	319	409
active_e	9.37	11.3	72.8	47.3	189	195

would be fabricated using state-of-the-art lithography tools capable of printing 150 nm feature sizes, with an edge placement accurate to approximately 5 nm. Applying the rasterization methodology presented in Section 2.2, 150 nm feature size, using 2 pixels per minimum feature, equates to a 75 nm pixels. To achieve 5 nm edge placement accuracy using 75 nm pixels requires $75/5 = 15$ gray levels which rounds up to 5 bits-per-pixel (bpp). Finally, polygons on the layer are placed on a 75 nm pixel grid. Fully covered pixels are white, fully uncovered pixels are black, and partially covered pixels are assigned a gray value equivalent to the fraction of area covered, quantized to the nearest $n/15$. To this data we apply SPIHT image compression, JPEG-LS image compression, a lossless version of the industry standard JPEG, ZIP byte stream compression, another industry standard, BZIP2 byte stream compression, and the RECT compressed representation. The results are presented in Table 2.2.

Column 1 of Table 2.2 names the layer image to which the compression techniques are applied. Active_a is a 1000×1000 pixel image, corresponding to a $75\mu m \times 75\mu m$ square randomly selected from the center area of the chip. Active_b is a 2000×2000 pixel image, corresponding to a $150\mu m \times 150\mu m$ square selected from the same area

as active_a, and includes active_a. Active_c through active_e are 2000×2000 pixel images, corresponding to a $150\mu m \times 150\mu m$ squares randomly selected from different parts of the chip, covering approximately 0.01% of a chip. Each sample is visually inspected to ensure that it is not mostly black.

The numbers in columns 2-7 are compression ratios for SPIHT, JPEG-LS, RECT, ZIP, and BZIP2 respectively, with each row corresponding to one of the active layer images. Comparing the second and third columns, JPEG-LS achieves slightly better compression than SPIHT; however, ZIP, 2D-LZ, and BZIP2 outperform them by more than a factor of 4. Even though SPIHT and JPEG-LS are state-of-the-art lossless natural image compressors, they cannot take full advantage of the highly structured nature of images generated from microchip designs. The fourth column RECT, represents the effective compression ratio achieved if no rasterization is performed, and the relevant rectangles are stored in a list. A rectangle is considered relevant if any portion of it intersects the area being rasterized. The size of the RECT representation increases linearly with the number of rectangles inside the rasterization region, so a large “compression ratio” indicates few rectangles in the region, and a small “compression ratio” indicates more rectangles in the region. RECT’s “compression ratio” can therefore be interpreted as an inverse measure of rectangle density, which varies dramatically in different areas of the layer. Although at times RECT performs similarly to ZIP for active_b and active_e, it achieves less than half the compression ratio of ZIP for active_c and active_d.

In the last four columns, compression ratios for ZIP, and BZIP2 are listed. For BZIP2 there are two results corresponding to two different block sizes used for block sorting, 100KB blocks and 900KB blocks. Impressively, all three techniques exceed the target compression ratio of 10 with considerable margins. This is likely a function of applying compression to the active layer, which is considerably less challenging than Poly, Metal 1, and Metal 2 described previously, due to low polygon density. In general, the compression ratio of BZIP2 exceeds that of ZIP. In the next chapter, we will revisit the compression ratio of ZIP and BZIP2 applied to the more challenging Poly, Metal 1, and Metal 2 layers of modern industry microchip design, in addition to introducing two novel compression algorithms designed specifically for layer image data.

Chapter 3

Overview of 2D-LZ Compression

In the preceding chapter, we have shown that LZ77 compression, as implemented by ZIP, is quite effective at compression of layout data, surpassing state-of-the-art image compression algorithms such as SPIHT and JPEG-LS. On the other hand, LZ77 is an inherently one-dimensional algorithm, which suggests that there may be room for improvement, because layer image data is certainly 2 dimensional. In response to this basic observation, we developed 2D-LZ, a two-dimensional variant of the LZ77 algorithm [3] [4]. In the remainder of this chapter, we provide an brief overview of 2D-LZ and characterize its performance. In doing so, we show that while 2D-LZ is well suited to compressing repetitive layouts, it is ineffective for irregular layouts.

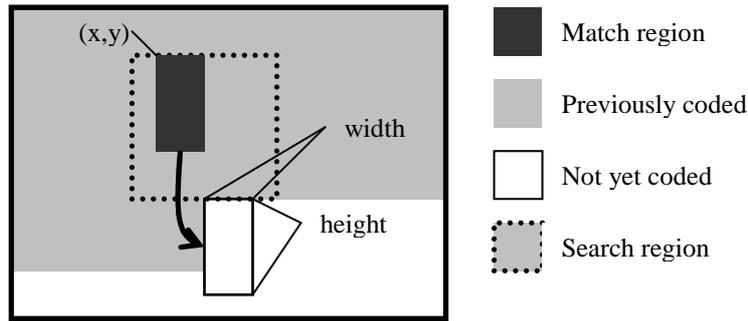


Figure 3.1: 2D-LZ Matching

3.1 A Brief Introduction to the 2D Matching Algorithm

The 2D-LZ algorithm extends the LZ77 algorithm to two dimensions, thereby taking advantage of the inherent two-dimensional nature of layout data, for the system architecture proposed in Chapter 1. Pixels are still encoded using raster scan order. However, the linear search window, which appears in LZ77, is replaced with a rectangular search region of previously coded pixels. This search window is illustrated in Figure 3.1.

As illustrated in Figure 3.1, a match is now a rectangular region, specified with four coordinates: a pair of coordinates, (x, y) , specify the match position, and another pair of integers, $(width, height)$, specify the extent of the match. If a match of minimum size cannot be found, then a literal is outputted representing a vertical column of pixels. A sequence of control bits is also stored so the decoder can determine whether the output is a literal or a match. To further compress the output, five Huffman

codes are used: one for each of the match coordinates x , y , width, height, and one for the literal.

2D-LZ behaves similarly to LZ77 in that longer matches and frequent repetitions increase the compression ratio. Therefore, several complex heuristics are employed in 2D-LZ to maximize the size of match regions, with the goal of improving compression efficiency for repetitive layouts. A more detailed explanation of these heuristics can be found in [3].

The decoding of 2D-LZ is simple. First the match region x , y , width, and height, and the literals are Huffman decoded. Similar to the encoder, the decoder also keeps a buffer of previously decoded pixels. The size of this buffer must be large enough to contain the height of the search window and the width of the image for matching purposes. Each time a match is read, the decoder simply copies data from the corresponding match region among the previously decoded pixels and fills it in the not yet decoded area. If a literal is read, the decoder simply fills in a vertical column of pixels in the not yet coded area. The decoder does not need to perform any searches, and is therefore much simpler in design and implementation than the encoder.

3.2 2D-LZ compression results

In Table 3.1, we compare 2D-LZ compression against JBIG, ZIP, and BZIP2 on the same binary image layouts as presented in Chapter 2. These binary images contained various layers of several layout types such as memory, control, and mixed logic. The

Table 3.1: Compression ratio for 2D-LZ, as compared to JBIG, ZIP, and BZIP2 on 300 nm, binary layer images.

Type	Layer	JBIG	ZIP	BZIP2	2D-LZ
Memory	Metal 2	58.7	88.0	171	233
	Metal 1	9.77	47.9	55.5	79.1
	Poly	12.4	50.7	82.5	120
Control	Metal 2	47.0	22.1	24.4	25.5
	Metal 1	20.0	10.9	11.2	11.2
	Poly	41.6	18.9	23.2	20.4
Mixed	Metal 2	51.3	28.3	39.4	34.4
	Metal 1	21.2	11.9	12.1	12.6
	Poly	41.3	22.9	27.8	27.2
Decoder Buffer (kB)		-	4	128	32

Table 3.2: Compression ratio for 2D-LZ, as compared to SPIHT, JPEG-LS, RECT, ZIP, BZIP2, on 75 nm, 5 bpp data

Image	SPIHT	JPEG-LS	RECT	ZIP	BZIP2 (100)	BZIP2 (900)	2D-LZ
active_a	8.44	9.27	33.9	45.7	227	227	111
active_b	9.69	9.76	61.1	61.1	497	800	144
active_c	5.00	5.31	18.7	46.4	296	518	328
active_d	7.44	8.45	24.5	60.1	319	409	273
active_e	9.37	11.3	72.8	47.3	189	195	145
Decoder Buffer (kB)	-	-	-	4	100	900	262

compression ratio of 2D-LZ is shown in column 6. In general, 2D-LZ performs about the same as BZIP2, and better than ZIP. For memory cells in particular, 2D-LZ compresses twice as well as ZIP. Memory cells are regularly arrayed both vertically and horizontally, and 2D-LZ takes full advantage of this two-dimensional repetition. For irregular layout found in control and mixed logic, 2D-LZ exhibits a performance loss as compared to JBIG.

In Table 3.2, we compare 2D-LZ compression against SPIHT, JPEG-LS, RECT, ZIP, 2D-LZ, and BZIP2 on the same gray pixel image layouts as presented in Chapter

2. These gray pixel images are taken from the active layer of an industry layout. The compression ration of 2D-LZ is shown in column 8. Again 2D-LZ performs slightly worse than BZIP2, significantly better than ZIP, and RECT, and far exceeds the efficiency of JPEG-LS and SPIHT.

In summary, even though 2D-LZ exceeds the performance of ZIP by taking advantage of the 2D structure of layout data, it remains highly optimized for compressing repetitive layout. Specifically, it still retains the basic weakness of the LZ77 algorithm in that for irregular layout where large repetitive regions cannot be found, 2D-LZ still cannot exceed the compression efficiency of the JBIG algorithm. This observation is the genesis for the C4 algorithm, as we search for a way to combine the best aspects of 2D-LZ and JBIG, without the large buffering requirements of BZIP2.

Chapter 4

Context-Copy-Combinatorial

Coding (C4)

Our work with existing algorithms as well as 2D-LZ shows that layout data has 2 major qualities to be exploited for lossless compression. First it is highly repetitive, and this is the used by LZ77 and 2D-LZ to achieve high compression efficiency. Second, where the layout is not repetitive, it can be compressed by context-based prediction schemes such as JBIG. In developing C4, we attempt to fuse these 2 ideas into a single compression algorithm, applicable to repetitive and non-repetitive layouts alike.

4.1 C4 Compression

The basic concept underlying C4 compression is to integrate the advantages of two disparate compression techniques: local context-based prediction and LZ-style copying, as characterized by JBIG and 2D-LZ respectively. This is accomplished through automatic segmentation of an image into *copy regions* and *prediction regions*. Each pixel inside a copy region is copied from a pixel preceding it in raster-scan order. Each pixel inside a prediction region, i.e. not contained in any copy region, is predicted from its local context. However, neither predicted values nor copied values are 100% correct, so *error bits* are used to indicate the position of these prediction or copy errors. These error bits can be compressed using any binary entropy coder, but in C4, we apply a new technique called hierarchical combinatorial coding (HCC) to be described shortly as a low-complexity alternative to arithmetic coding. Only the copy regions and compressed error bits are transmitted to the decoder.

In addition, as discussed in Chapter 1, for our application to direct-write maskless lithography, the C4 decoding algorithm must be implemented in hardware as a parallel array of thousands of C4 decoders fabricated on the same substrate as a massively parallel array of writers [4]. As such, the C4 decoder must have a low implementation complexity. In contrast, the C4 encoder is under no such complexity constraint. This basic asymmetry in the complexity requirement between encoding and decoding, which is common to many compression applications, is central to the design of the C4 algorithm.

Fig. 4.1 shows a high-level block diagram of the C4 encoder and decoder for binary layer images. First, a prediction error image is generated from the layer image, using a simple 3-pixel context-based prediction model. In generating this prediction error image, we assume as a starting point that the entire image is encoded using context based prediction. Next, we successively add *copy regions* onto the background *prediction region* where appropriate, in order to further improve compression efficiency. The reason that prediction is used as “background” is that it is globally applicable to layout as a whole, whereas copy regions are specific to repetitive layout, and the period of repetition varies from region to region. The result is a segmentation map of copy regions on top of a prediction region background.

As specified by the segmentation map, the Predict/Copy block estimates each pixel value, either by copying or by prediction. The result is compared to the actual value in the layer image. Correctly predicted or copied pixels are indicated with a “0”, and incorrectly predicted or copied pixels are indicated with a “1”, equivalent to a Boolean XOR of predicted/copied pixel values with the original layer image. These error bits are compressed without loss by the Hierarchical Combinatorial Code (HCC) encoder, which are transmitted to the decoder, along with the segmentation map. The segmentation map itself is represented as a list of copy region rectangles, with each rectangle specified by its position (x, y) , size (w, h) , and copy parameters $(left/above, d)$ in binary format.

The decoder mirrors the encoder, but skips the complex steps necessary to find

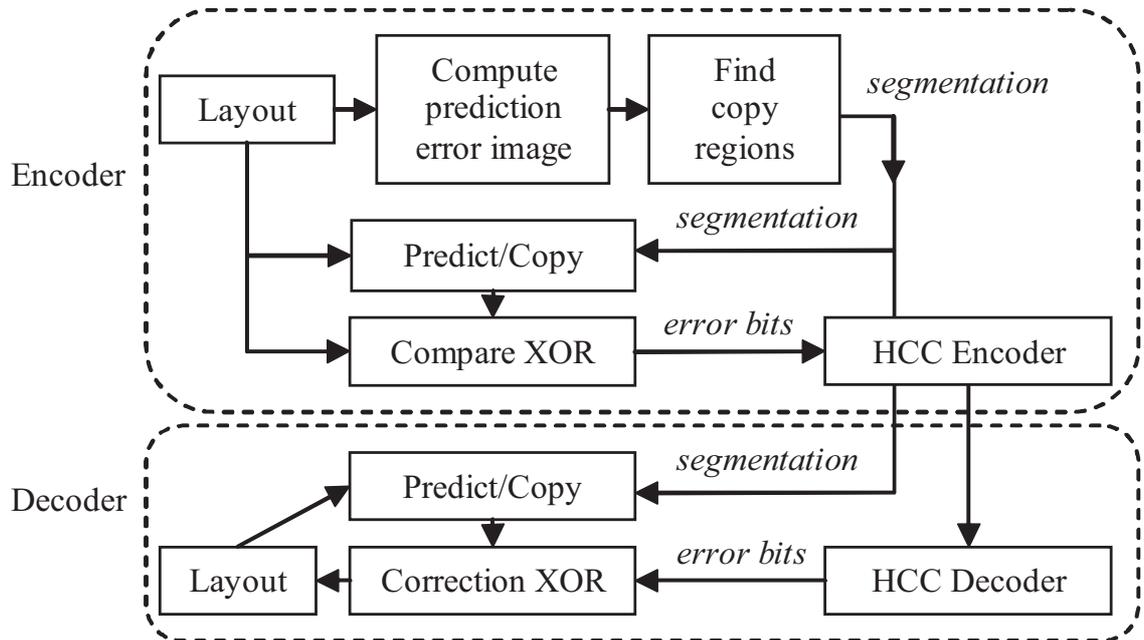


Figure 4.1: Block diagram of C4 encoder and decoder for binary images.

the segmentation map, which are received from the encoder. Again as specified by the segmentation, the Predict/Copy block estimates each pixel value, either by copying or by prediction. The HCC decoder decompresses the error bits from the encoder. If the error bit is “0” the prediction or copy is correct, and if the error bit is “1” the prediction or copy is incorrect and must be inverted, equivalent to a per-pixel Boolean XOR operation between the error bit and the estimated pixel value. Since there is no data modeling performed in the C4 decoder, it is considerably simpler to implement than the encoder, satisfying one of the requirements of our application domain.

Table 4.1: The 3-pixel contexts, prediction, and the empirical prediction error probability for a sample layer image

Context	Prediction	Error	Error probability
			0.0055
			0.071
			0.039
			0
			0
			0.022
			0.037
			0.0031

4.2 Context-based Prediction Model

For our application domain, i.e. microchip layer image compression, we use a simple 3-pixel binary context-based prediction model in C4, which is much simpler than the 10-pixel model used in JBIG [8]. Since the number of contexts scales exponentially with the number pixels used for prediction, this represents a significant complexity reduction of the C4 prediction mechanism at the decoder, as compared to JBIG. Nonetheless, this simple 3-pixel context captures the essential “Manhattan” structure of layer data, as well as some design rules, as seen in Table 4.1.

The pixels used to predict the current coded pixel are the ones above, left, and above-left of the current pixel. The first column shows the 8 possible 3-pixel contexts, the second column shows the prediction, the third column shows what a prediction error represents, and the fourth column shows the empirical prediction error proba-

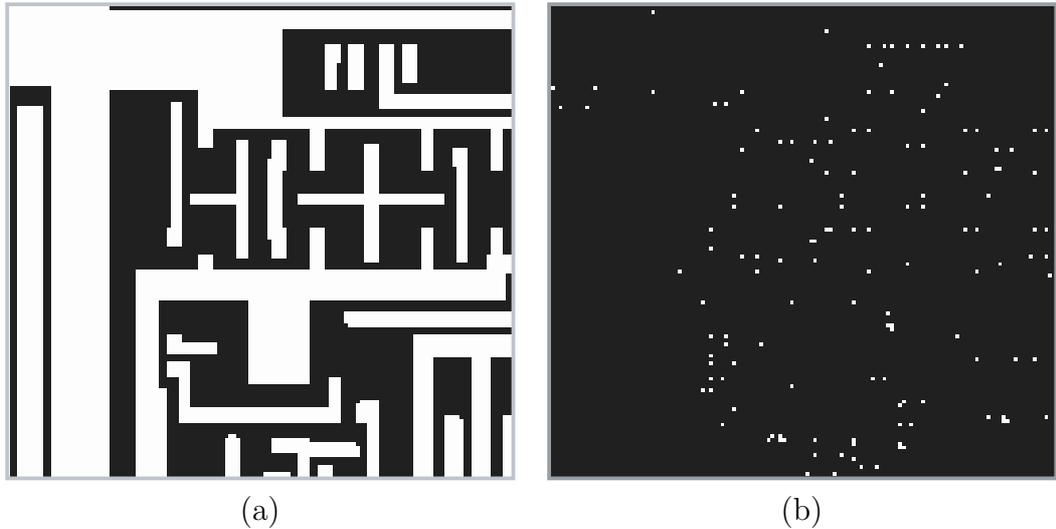


Figure 4.2: (a) Non-repetitive layer image data and (b) its resulting prediction error image.

bility for an example layer image. From these results, it is clear that the prediction mechanism works extremely well. Layer data is dominated by vertical edges, horizontal edges, and regions of constant intensity. The simple 3-pixel context predicts all these cases perfectly. Consequently, we do not expect much benefit to increasing the number of context pixels to 4 or higher, and in fact, this intuition matches our empirical observations. Visual inspection of the prediction error reveals that prediction errors primarily occur at the corners in the layer image. The two exceptional 0% error cases in rows 5 and 6 represent design rule violations.

To generate the prediction error image, each correctly predicted pixel is marked with a “0”, and each incorrectly predicted pixel is marked with a “1”, creating a binary image which can be compressed with a standard binary entropy coder. The fewer the number of incorrect predictions, the higher the compression ratio achieved.

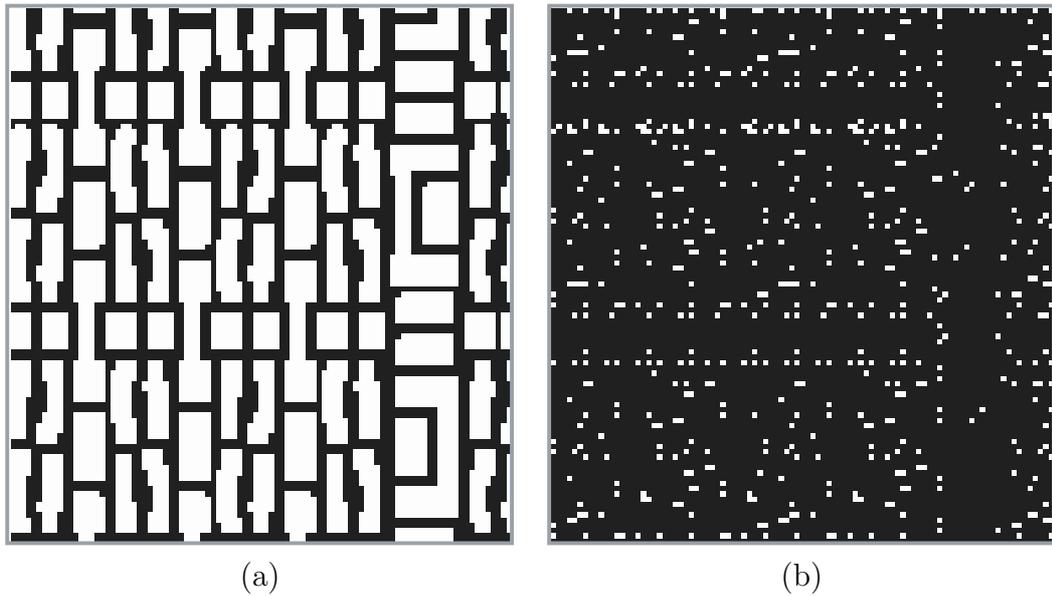


Figure 4.3: (a) Dense repetitive layer image data and (b) its resulting prediction error image.

In fact, as we shall explain shortly, this “prediction only” mode is used as a basis of comparison for generating copy regions, i.e. a copy region is added only if it improves the overall compression efficiency as compared to simply using context-based prediction everywhere.

Alternatively, it is also possible to group pixels by their context, forming 8 separate binary streams, each to be compressed separately by its own entropy coder. Empirically, for layer images, we have found that operating on the prediction error image is nearly as efficient as grouping pixels by context.

An example of non-repetitive layout for which prediction works well is shown in Fig. 4.2(a), and its corresponding prediction error image is shown in Fig. 4.2(b).

In contrast to the non-repetitive layout shown in Fig. 4.2(a), some layer image

data contains regions that are visually “dense” and repetitive. An example of such a region is shown in Fig. 4.3(a). This visual “denseness” results in a dense, large number of prediction errors as seen clearly in the prediction error image in Fig. 4.3(b).

The high density of prediction errors translates into low compression ratios using prediction alone. In C4, areas of dense repetitive layout are covered by copy regions to reduce the number of errors, as described in Section 4.3.

4.3 Copy Regions and Segmentation

As seen in Fig. 4.3(a) of the previous section, some layer images are highly repetitive. We can take advantage of this repetitiveness to achieve compression by specifying *copy regions*, i.e. a rectangular region that is copied from another rectangular region preceding it in raster-scan order.

The copy itself can be defined both in the layer image data domain, or the prediction error image domain. Although there is a one-to-one correspondence between the two images, copy regions defined in one domain are not the same as the other domain. Nonetheless, they are extremely similar, differing only at the boundaries of the copy regions. Tests on layout show negligible differences in compression efficiency between these two approaches. C4 defines copy regions on the layer image data, which is perhaps the more intuitive of the two choices.

A copy region in C4 is defined as a rectangle inside which every pixel is copied from either d pixels to its *left*, or d pixels *above*. Consequently the region is com-

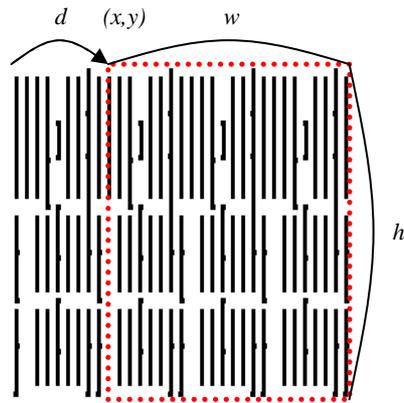


Figure 4.4: Illustration of a copy left region.

pletely specified by six parameters: (x, y) position of the upper left hand corner of the rectangle, the size of the rectangle (w, h) , the copy direction ($dir = left/above$) and the copy distance d . An example of a copy region is illustrated in Figure 4.4. In the figure, the dashed red rectangle is the copy region. It is positioned at (x, y) , has size (w, h) , and every pixel inside it is copied d pixels from the *left* as indicated by the arrow. Although the entire region is copied, the copy itself need not be 100% correct. Similar to the prediction error map, there is a corresponding copy error map within the copy region. Each correctly copied pixel is indicated with a “0”, and each incorrectly copied pixel each incorrectly predicted pixel is marked with a “1”, creating a binary sub-image which can be compressed with a standard binary entropy coder.

This method of copying is related to LZ77 [6] copying, but extended to two dimensions (2D) with errors allowed. Conceptually, this allows us to capture the 2D-repetitions found in layer images. In addition, note that in Fig. 4.4 the single copy region spans three horizontal periodic repetitions, with period d . In C4, an entire

periodic array can be described with a single copy region. This simple feature is extremely important for extracting compression efficiency from layer data, which can contain large periodic 2D-arrays.

This method of copying contrasts sharply with the method of copying used in JBIG2 [9] called “soft-pattern matching” [17], which constructs an explicit dictionary of pixel blocks that can be throughout the image. In JBIG2, each individual copy in a 2D periodic array must be separately referenced [9], leading to a lower compression efficiency in comparison to C4 for this type of data.

The C4 copy mechanism is a restricted version of the copy mechanism allowed by 2D-LZ in Figure 3.1. Whereas 2D-LZ allows copies from any direction, C4 restricts the copy direction to ($dir = left/above$). This restriction allows C4 to significantly expand the copy distance d beyond that allowed by 2D-LZ while reducing the number of bits needed to represent copies. For example, to specify copy from any direction in a 256 pixel square region is equivalent to specifying a point (cx, cy) in that region which takes 8 bits for cx and 8 bits for cy . So 2D-LZ uses 16-bits to specify a copy direction and distance within a 256 pixel square region. In contrast C4 uses one bit to specify the copy direction ($dir = left/above$) and allows the copy distance d to extend to 1024-pixels which takes 10-bits to represent. So C4 uses 11-bits to represent a copy direction and distance, 5 fewer bits than 2D-LZ. This tradeoff means that C4 can better compress horizontal and vertical repetitions with fewer bits in comparison to 2D-LZ, at a cost of disallowing diagonal copies. This tradeoff is worthwhile because

of the Manhattan structure of layout design.

As described in Section 4.1, the C4 encoder automatically segments the image into copy regions and the prediction region, i.e. all pixels not contained in any copy region. Each copy region has its own copy parameters and corresponding copy error map, and the background prediction region has a corresponding prediction error map. Together, the error maps merge to form a combined binary prediction/copy error map of the entire image, which is compressed using HCC as a binary entropy coder. The lower the number of the total sum of prediction and copy errors, the higher the compression ratio achieved. However, this improvement in compression by the introduction of copy regions, is offset by the *cost* in bits to specify the copy parameters $(x, y, w, h, left/above, d)$ of each copy region. Moreover, copy regions that overlap with each other are undesirable: each pixel should ideally only be coded once, to save as many bits as possible.

Ideally, we would like the C4 encoder to find the set of non-overlapping copy regions, which minimizes the sum of number of compressed prediction/copy error bits, plus the number of bits necessary to specify the parameters of each copy region. An exhaustive search over this space would involve going over all possible non-overlapping copy region sets i.e. a combinatorial problem, generating the error bits for each set, and performing HCC compression on the error bits. This is clearly infeasible. To make the problem tractable, a number of simplifying assumptions and approximate metrics are adopted.

First we use entropy as a heuristic to estimate the number of bits generated by the HCC encoder to represent error pixels. If p denotes the percentage of prediction/copy error pixels over the entire image, then error pixels are assigned a per-pixel cost of $C = -\log_2(p)$ bits, and correctly predicted or copied pixels are assigned a per-pixel cost of $-\log_2(1 - p) \approx 0$. Of course, given a segmentation map, p can be easily measured by counting the number of prediction/copy error bits; at the same time, p affects how copy regions are generated in the first place, as discussed shortly. In C4, we solve this chicken and egg problem by first estimating a value of p , finding a segmentation map using this value, counting the percentage of prediction/copy error pixels, and using this percentage as a new value for p as input to the segmentation algorithm. This process can be iterated until the estimated p matches the percentage of error pixels; however, in practice we find that one iteration is sufficient if the starting estimate is reasonable. Empirically, we have found a reasonable starting estimate to be the percentage of error pixels when no copy regions are used, then discounted by a constant factor of 4.

Next, for any given copy region, we compare the cost, in bits, of coding that region using copy, versus the cost of coding the region using prediction. If the cost of copying is lower, then the amount by which it is lower is the *benefit* of using this region. The cost of copying is defined as the sum of the cost of describing the copy parameters, plus the cost of coding the copy error map. For our particular application domain, the description cost is 51 bits. Here we have restricted x , y , w , h to 10-bits each

which is reasonable for our 1024×1024 test images. In addition, the copy direction and distance (*left/above, d*) can be represented with 11 bits, where *d*, represented by 10 bits, denotes the distance left or above to copy from, and *left/above*, represented by 1 bit, denotes the direction left or above to copy from. The cost of coding the copy error map is estimated as $C \times E_{copy}$, where C denotes the estimated per-pixel cost of an error pixel, as discussed previously, and E_{copy} denotes the number of copy error pixels in the region. Correctly copied pixels are assumed to have 0 cost, as discussed previously. So the total cost of copying is $51 + C \times E_{copy}$.

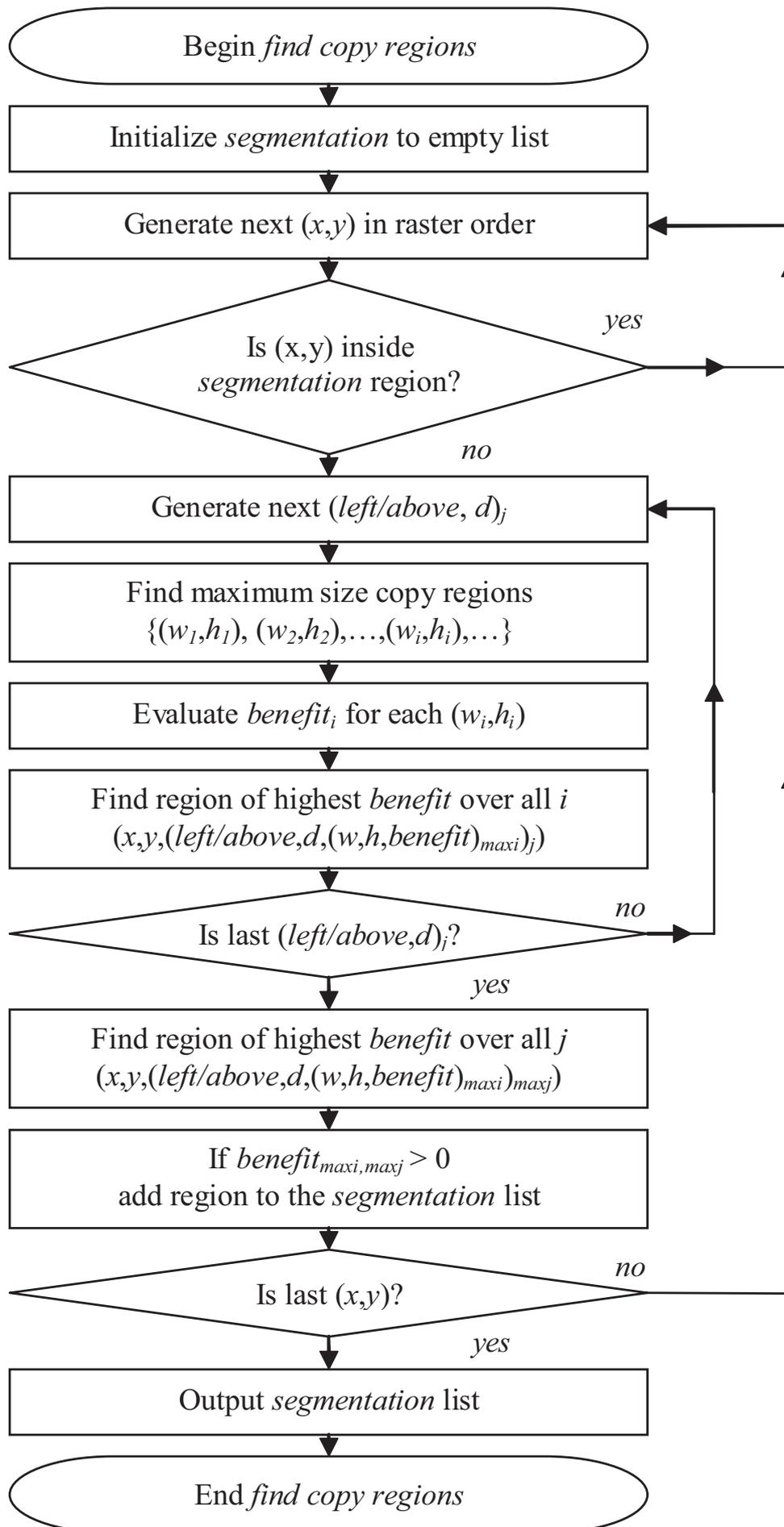
The cost of coding the region using prediction is the cost of coding the prediction error map of that region. It is estimated as $C \times E_{context}$, where $E_{context}$ denotes the number of prediction error pixels in the region. Finally, the *benefit* of a region is the difference between these two costs, $C \times (E_{context} - E_{copy}) - 51$. Note that it is possible for a region to have negative benefit if $E_{context} - E_{copy} \leq (51/C)$. The threshold $T = (51/C)$ is used to quickly disqualify potential copy regions in the search algorithm presented below.

Using *benefit* as a metric, the optimization goal is to find the set non-overlapping copy regions, which maximizes the sum of *benefit* over all regions. This search space is combinatorial in size, so exhaustive search is prohibitively complex. Instead we adopt a greedy approach, similar to that used in the 2D-LZ algorithm described in [4]. The basic strategy used by the *find copy regions* algorithm in Fig. 4.1 is as follows: start with an empty list of copy regions; and in raster-scan order, add copy

regions of maximum benefit, that do not overlap with regions previously added to the list. The completed list of copy regions is the *segmentation* of the layer image. A detailed flow diagram of the *find copy regions* algorithm is shown in Fig. 4.5, and described in the remainder of this section.

In raster-scan order, we iterate through all possible (x, y) . If (x, y) is inside any region in the *segmentation* list, we move on to the next (x, y) ; otherwise, we iterate through all possible $(left/above, d)$. Next for a given $(x, y, left/above, d)$, we maximize the size of the copy region (w, h) with the constraint that a *stop pixel* is not encountered; we define a *stop pixel* to be any pixel inside a region in the *segmentation* list, or any pixel with a copy error. These conditions prevent overlap of copy regions, and prevent the occurrence of copy errors, respectively. Later, we describe how to relax this latter condition to allow for copy errors. The process of finding maximum size copy regions (w, h) , is discussed in the next paragraph. Finally, we compute the benefit of all the maximum sized copy regions, and, if any region with positive benefit exists, we add the one with the highest positive benefit to the *segmentation* list.

We now describe the process of finding the maximum size copy region (w, h) . For any given $(x, y, left/above, d)$ there is actually a set of maximum size copy regions, bordered by stop pixels, because (w, h) is a two-dimensional quantity. This is illustrated in the example in Fig. 4.6. In the figure, the position of the stop pixels are marked with \otimes and three overlapping maximum copy regions are shown namely (x, y, w_1, h_1) (x, y, w_2, h_2) and (x, y, w_3, h_3) . The values $w_1, h_1, w_2, h_2, w_3,$ and h_3 are



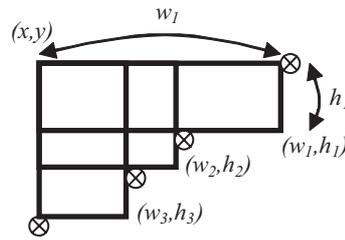


Figure 4.6: Illustration of three maximum copy regions bordered by four stop pixels.

found using the following procedure: initialize $w = 1$, $h = 1$. Increment w until a stop pixel is encountered; at this point $w = w_1$. Next increment h , and for each h , increment w from 1 to w_1 , until a stop pixel is encountered; at this point $h = h_1$, and $w = w_2$. Again increment h , and for each h increment w from 1 to w_2 , until a stop pixel is encountered; at this point $h = h_2$, and $w = w_3$. Finally, increment h , and for each h increment w from 1 to w_3 , until a stop pixel is encountered; at this point $h = h_3$, and $w = 1$. The maximum size algorithm is terminated when a stop pixel is encountered at $w = 1$.

As stated previously, any pixel inside a region in the *segmentation* list, and any pixel with a copy error, is a *stop pixel*. Recall the algorithm to find maximum size copy regions, the stop-pixel limits the copy region from expanding further. We relax the definition of a stop-pixel to merge smaller, error free, copy regions, into larger copy regions with a few number of copy errors. The basic premise is to tradeoff the 51-bits necessary to describe a new copy region against the introduction of bits needed to code copy errors, by excluding some copy error pixels from being *stop pixels*. For each copy error pixel, we examine a look-ahead window (LAW) of W pixels in a row,

where the left most pixel is the copy error. For this LAW we consider 3 scenarios.

First suppose the current copy region is extended to include the LAW. In the LAW, there is at least one copy error of course, but possibly a few more. Let us denote this quantity as E_{copy} .

Next suppose the current copy region is not extended to include the LAW. Then the LAW could be entirely part of a background prediction region. Assuming the LAW is entirely a prediction region, we can count the number prediction errors and denote it as $E_{predict}$.

Finally, suppose in the final segmentation neither the current copy region, nor the background region covers the entire LAW. It could be that the LAW is covered by an unknown mix of copy regions and prediction regions. In this case, our target is to do no worse than the expected number of errors in a LAW of W pixels = Wp

Suppose in the final result $E_{copy} < E_{predict}$, this indicates that for the LAW, it is better to continue the copy region than it is to allow this area to become a predict region.

Suppose in the final result $E_{copy} < Wp$, this indicates that for the LAW, continuing the copy region would do better than our expectation.

If both of these are true, then reasoning would indicate that it is likely to be advantageous to extend the copy region than to cut it off. In this case, that specific copy error at the left-most pixel of the LAW is no longer treated as a stop-pixel for the purpose of maximizing the copy region.

The size of the look-ahead window W is a user-defined input parameter to the C4 algorithm. Empirically, larger values of W correspond to fewer, larger copy regions, at the expense of increasing the number of copy errors. Note that if W is sufficiently small, such that $Wp < 1$, then copy errors are effectively disallowed, as $E_{copy} > 1$.

4.4 Hierarchical Combinatorial Coding (HCC)

We have proposed and developed combinatorial coding (CC) [10] as an alternative to arithmetic coding to encode the error bits in Fig. 4.1. The basis for CC is universal enumerative coding [11] which works as follows. For any binary sequence of known length N , let k denote the number of ones in that sequence. k ranges from 0 to N , and can be encoded using a minimal binary code [14], i.e. a simple Huffman code for uniform distributions, using $\lceil \log_2(N + 1) \rceil$ bits. There are exactly $C(N, k) = N! / (N - k)!k!$ sequences of length N with k ones, which can be hypothetically listed. The index of our sequence in this list, known as the *ordinal* or *rank*, is an integer ranging from 1 to $C(N, k)$, which can again be encoded using a minimal binary code, using $\lceil \log_2 C(N, k) \rceil$ bits. Enumerative coding is theoretically shown to be optimal [11] if the bits to be compressed are independently and identically distributed (i.i.d.) as *Bernoulli*(θ) where θ denotes the unknown probability that “1” occurs, which in C4, corresponds to the percentage of error pixels in the prediction/copy error map. The drawback of computing an enumerative code directly is its complexity: the algorithm to find the rank corresponding to a particular binary sequence of length N , called

ranking in the literature, is $O(N)$ in time, is $O(N)$ in memory, and requires $O(N)$ bit precision arithmetic [11].

In CC, we address this problem by first dividing the bit sequence into blocks of fixed size M . For today's 32-bit architecture computers, $M = 32$ is a convenient and efficient choice. Enumerative coding is then applied separately to each block, generating a $(k, rank)$ pair for each block. Again, using the same assumption that input bits are i.i.d. as *Bernoulli*(θ), the number of ones k in a block of M bits are i.i.d. as *Binomial*(M, θ). Even though the parameter θ is unknown, as long as the Binomial distribution is not too skewed, e.g. $0.01 < \theta < 0.99$, a dynamic Huffman code efficiently compresses the k -values with little overhead, because the range of k is small. Given there are k ones in a block of M bits, the rank remains uniformly distributed, as in enumerative coding. Therefore, *rank*-values are efficiently coded using a minimum binary code.

The efficiency of CC, as described, is on par with arithmetic coding, except in cases of extremely skewed distributions, e.g. $\theta < 0.01$. In these cases, the probability that $k = 0$ approaches 1 for each block, causing the Huffman code to be inefficient. To address this issue, we have developed an extension to CC called hierarchical combinatorial coding (HCC). It works by binarizing sequence of k -values such that $k = 0$ is indicated with a "0" and $k = 1$ to 32 is indicated with a "1". CC is then applied to the binarized sequence of "0" and "1", and the value of k , ranging from 1 to 32 in the "1" case, is Huffman coded. Clearly, this procedure of CC encoding, binarizing the

k -values, then CC encoding again can be recursively applied in a hierarchical fashion, to take care of any inefficiencies in the Huffman code for k -values, as θ approaches 0.

Figure 4.7 is an example of HCC in action with 2-levels of hierarchy and block size $M = 4$. Only values in bold italics are coded and transmitted to the decoder. Looking at rows from bottom to top, the original data is in the lowest row labeled “bits – level 0”. Applying CC with $M = 4$, the next two rows show the *rank* and k value for each block in level 0. Note that when $k = 0$ no *rank* value is needed as indicated by the hyphen. The high frequency of 0 in “ k – level 0” makes it inefficient for coding directly using Huffman coding. Instead, we binarize “ k – level 0”, to form “bits – level 1”, using the binarization procedure described in the previous paragraph. CC is recursively applied to “bits – level 1”, to compute “*rank* – level 1” and “ k – level 1”. Finally, to code the data, “ k – level 1” is coded using a Huffman code, “*rank* – level 1” is coded using a minimal binary code, *non-zero* values of “ k – level 0” are coded using a Huffman code, and “*rank* – level 0” is coded using a minimal binary code.

The rationale for choosing Huffman coding and minimal binary coding is the same as CC. If the input is assumed to be i.i.d. as *Bernoulli*(θ), then the distribution of *rank* – level i given k – level i is uniformly distributed from 1 to $C(M, k)$. Furthermore, although the exact distribution of k -values is unknown, a dynamic Huffman code can adapt to the distribution with little overhead, because the dynamic range of k – level i is small. Finally, for highly skewed distributions of k – level i , which

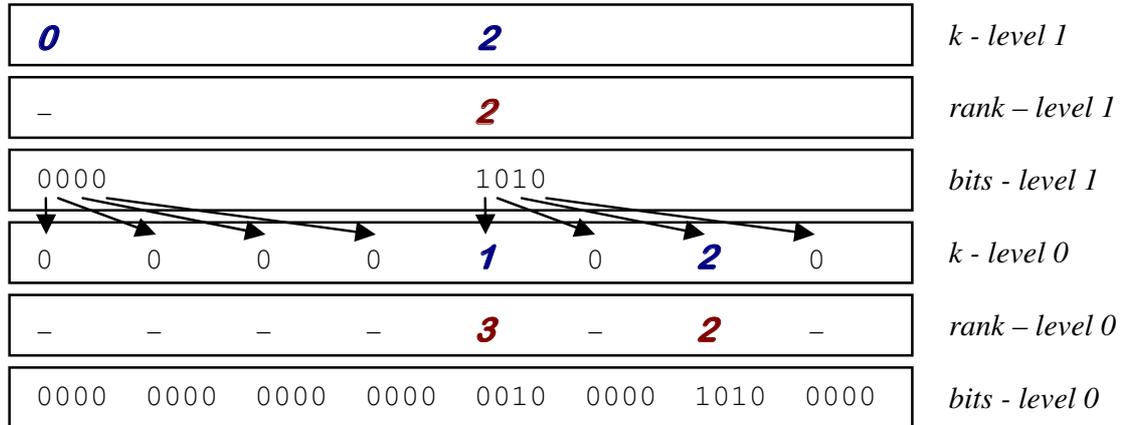


Figure 4.7: 2-level HCC with a block size $M = 4$ for each level.

hurts the compression efficiency of Huffman coding, the binarization process reduces the skew by removing the most probable symbol $k = 0$.

Studying the example in Fig. 4.7, we can intuitively understand the efficiency of HCC: the single Huffman coded **0** in “ k - level 1” decodes to M^2 zeroes in “bits - level 0”. In general, for L -level HCC, a single Huffman coded **0** in level $L - 1$ corresponds to M^L zeroes in “bits - level 0”. HCC’s ability to effectively compress blocks of zeroes is critical to achieving high compression ratios, when the percentage of the error pixels is low. In this HCC operates similiarly to various run-length codes, which also focus on compacting blocks of 0’s. The differences are highlighted below.

In addition to achieving efficient compression, HCC also has several properties favorable to our application domain. First, the decoder is extremely simple to implement: the Huffman code tables are small because the range of k -values is small, unranking is accomplished with a simple table lookup, comparator, and adder, and

minimal binary decoding is also accomplished by a simple table lookup and an adder. Second, the decoder is fast: blocks of $M^{(L+1)}$ zeroes can be decoded instantly when a zero is encountered at level L . Third, HCC is easily parallelizable: block sizes are fixed and block boundaries are independent of the data, so the compressed bitstream can be easily partitioned and distributed to multiple parallel HCC decoders. This is in contrast to run-length coding schemes such as Golomb codes [12], which also code for runs of zeroes, but have data-dependent block boundaries.

Independent of our development of HCC, a similar technique called Hierarchical Enumerative Coding (HEC) has been developed in [13]. The main difference between HEC and HCC is the method of coding k values at each level. HCC uses binarization and simple Huffman coding, whereas HEC uses hierarchical integer enumerative coding, which is more complex [13]. Due to this complexity, at higher levels of hierarchy, HEC merges 2 groups at a time, whereas HCC merges M groups, e.g. $M = 32$, together through binarization. Consequently, HCC requires fewer levels of hierarchy to achieve the same level of compression efficiency as HEC.

To compare HCC with existing entropy coding techniques, we apply 3-pixel context based modeling as described in Section 4.2 to a 242 kb layer image, and group pixels by context into 8 binary streams. We then apply Huffman coding to blocks of 8-bits, arithmetic coding, Golomb run-length coding, HEC, and HCC to each binary stream, and report the compression ratio obtained by each algorithm. In addition, we report the encoding and decoding times as a measure for complexity of these

Table 4.2: Result of 3-pixel context based binary image compression on a 242 kb layer image for a P3 800 MHz processor

Metric	Huf8	Arith.	Golomb	HEC	HCC
Comp. ratio	7.1	47	49	48	49
Enc. time(s)	0.99	7.46	0.52	2.43	0.54
Dec. time(s)	0.75	10.19	0.60	2.11	0.56

algorithms. The results are shown in Table 4.2.

Among these techniques, HCC is one of the most efficient in terms of compression, and one of the fastest to encode and decode, justifying its use in C4. The only algorithm comparable in both efficiency and speed, among those tested, is Golomb run-length coding. However, as previously mentioned, HCC has fixed, data-independent block boundaries, which are advantageous for parallel hardware implementations; run-length coding does not. Run-times are reported for 100 iterations on an 800 MHz Pentium III workstation. All algorithms are written in C# and optimized with the assistance of VTune to eliminate bottlenecks. The arithmetic coding algorithm is based on that described in [14].

4.5 Extension to Gray Pixels

So far, C4 as described is a binary image compression technique. To extend C4 to encode 5-bit gray-pixel layer image, slight modifications need to be made to the prediction mechanism, and the representation of the error. Specifically, the local 3-pixel context based prediction described in Section 3, is replaced by 3-pixel linear prediction with saturation, to be described later; furthermore, in places of prediction

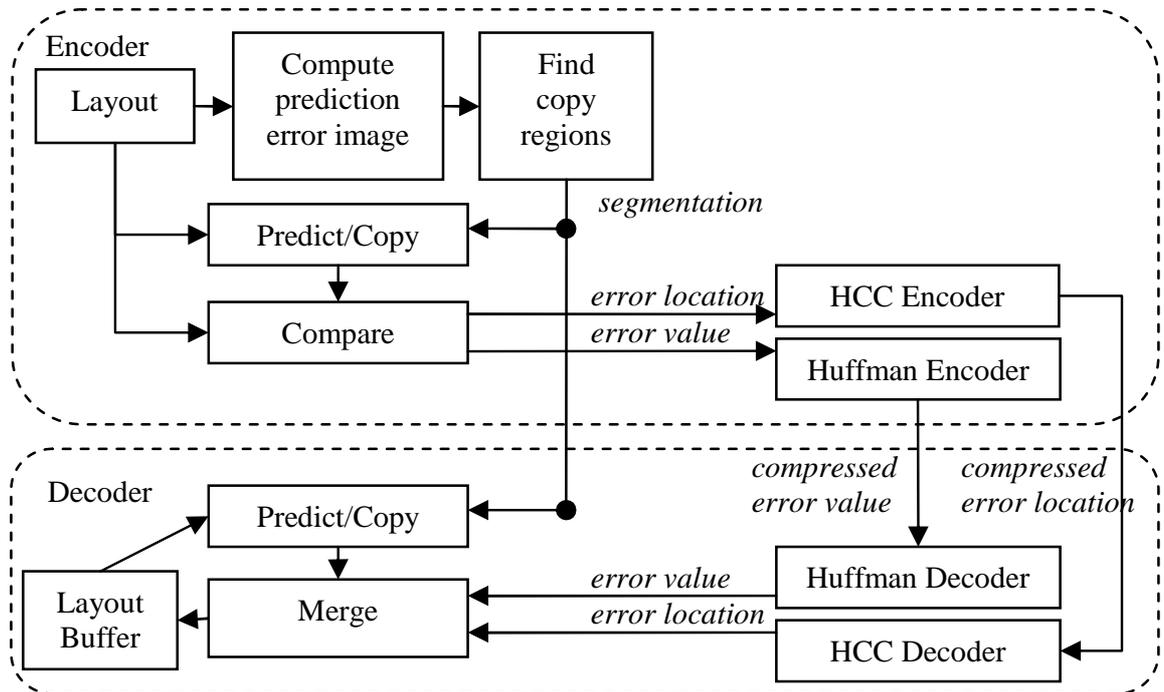


Figure 4.8: Block diagram of C4 encoder and decoder for gray-pixel images.

or copy error, where the error location bit is "1", an *error value* indicates the correct value of that pixel. A block diagram of the C4 encoder and decoder for gray-pixel images is shown in Fig. 4.8.

First, a prediction error image is generated from the layer image, using a simple 3-pixel linear prediction model. The error image is a binary image, where "0" denotes a correctly predicted gray-pixel value and "1" denotes a prediction error. The copy regions are found as before in binary C4, with no change in the algorithm. As specified by the copy regions, the Predict/Copy generates pixel values either using copying or linear prediction. The result is compared to the actual value in the layer image. Correctly predicted or copied pixels are indicated with a "0", and incorrectly predicted

a	b	$x = b - a + c$
c	?	if $(x < 0)$ then $? = 0$
		if $(x > \text{max})$ then $? = \text{max}$
		otherwise $? = x$

Figure 4.9: 3-pixel linear prediction with saturation used in gray-pixel C4.

or copied pixels are indicated with a “1” with an error value generated indicating the true value of the pixel. The error location bits are compressed with a HCC encoder, and the actual error values are compressed with a Huffman encoder.

As in binary C4, the gray-pixel C4 decoder mirrors the encoder, but skips the complex steps necessary to find the copy regions. The Predict/Copy block generates pixel values either using copying or linear prediction according to the copy regions. The HCC decoder decodes the error location bits, and the Huffman decoder decodes the error values. If the error location bit is “0” the prediction or copy is correct, and if the error location bit is “1” the prediction or copy is incorrect and the actual pixel value is the error value.

The linear prediction mechanism used in gray-pixel C4 is analogous to the context-based prediction used in binary C4. Each pixel is predicted from its 3-pixel neighborhood as shown in Fig. 4.9. x is predicted as a linear combination of its local 3-pixel neighborhood a , b , and c , using the equation $x = b - a + c$. Intuitively, there are several ways to understand this formula. First, rewriting as $x - c = b - a$ it says the change moving right from a to b is the same as the change moving right from c to x . Second, rewriting as $x - b = c - a$ it says the change moving top to bottom from a to c , is the same as the change moving top to bottom from b to x . Taken

Table 4.3: Compression ratios of JBIG, JBIG2, ZIP, 2D-LZ, BZIP2 and C4 for 2048×2048 binary layer image data.

Type	Layer	JBIG	JBIG2	ZIP	2D-LZ	BZIP2	C4
Mem. Cells	M2	59	68	88	233	260	332
	M1	10	12	48	79	56	90
	Poly	12	14	51	120	83	141
Ctrl. Logic	M2	47	52	22	26	32	50
	M1	20	23	11	11	11	22
	Poly	42	43	19	20	23	45
Encode Time (s)		6	11	2	640	4	720
Decode Time (s)		6	7	1	2	4	2
Decode Buffer (kB)		-	-	4	64	512	512

together, this means that the local derivative in both the x and y directions remains constant, i.e. x is predicted to lie on the same 2D plane as a , b , and c . Specifically for Mahattan layout, it means horizontal edges are predicted to continue, vertical edges are predicted to continue, and regions of constant intensity remain constant. If the prediction value x is negative or exceeds the maximum allowed pixel value max , the result is clipped to 0 or max respectively. Interestingly, this linear predictor can also be applied to a binary image by setting $max = 1$, resulting in the same predicted values as binary context-based prediction described in Section 4.2. It is also similar to the median predictor used in JPEG-LS [16].

4.6 Compression Results

We apply a suite of existing and general lossless compression techniques as well as C4 to binary layer image data. Compression results are listed in Table 4.3. The original data are 2048×2048 binary images with 300 nm pixels sampled from an

industry microprocessor microchip, which corresponds to a 0.61 mm by 0.61 mm section, covering about 0.1% of the chip area. Each entry in the table corresponds to the compression ratio for one such image.

The first column “Type” indicates where the sample comes from, memory, control, or a mixture of the two. Memory circuits are typically extremely dense but highly repetitive. In contrast, control circuits are highly irregular, but typically much less dense. The second column “Layer” indicates which layer of the chip the image comes from. Poly and Metall1 layers are typically the densest, and mostly correspond to wire routing and formation of transistors. The remaining columns from left to right are compression ratios achieved by: JBIG, JBIG2, ZIP, 2D-LZ our 2D extension to the LZ77 copying [4], BZIP2 based on the Burrows-Wheeler Transform [15], and C4. The bold numbers indicate the highest compression for each row.

As seen, C4 outperforms all these algorithms for repetitive layouts, and is tied for first with JBIG2 for non-repetitive layouts. This is significant, because most layouts contain a heterogeneous mix of memory and control circuits. ZIP, 2D-LZ and BZIP2 take advantage of repetitions resulting in high compression ratios on memory cells. In contrast, where the layout becomes less regular, the context modeling of JBIG and JBIG2 has an advantage over ZIP, 2D-LZ, and BZIP2. It is worth noting that the compression efficiency of JBIG2 varies with the encoder implementation, and our tests are based on the JBIG2 encoder implementation used within Adobe Acrobat 6.0.

Table 4.4: Compression ratio of run length, Huffman, LZ77, ZIP, BZIP2, and C4 for 5-bit gray layer image data.

Layer	RLE	Huf	LZ77 256	LZ77 1024	ZIP	BZIP2	C4
M2	1.4	2.3	4.4	21	25	28	35
M1	1.0	1.7	2.9	5.0	7.8	11	15
Poly	1.1	1.6	3.3	4.6	6.6	10	14
Via	5.0	3.7	10	12	15	24	32
N	6.7	3.2	13	28	32	42	52
P	5.7	3.3	16	45	52	72	80
Enc (s)	1	1	6	10	4	8	1680
Dec (s)	1	1	2	2	2	8	3
Dec Buffer (kB)	0	0	0.2	1	4	900	656

The last two rows report the encoder and decoder runtime of the various algorithms on a 1.8GHz Mobile Pentium 4 with 512MB of RAM running Windows XP. Each algorithm is asked to compress and decompress a suite of 10 binary layer image files, and runtimes are measured to the nearest second by hand. Unfortunately, a more precise measurement has not been possible due to the varying input/output formats of the different softwares. The most striking result is the slow speed of the C4 encoder, in contrast to the fast performance of the C4 decoder. This is a direct consequence of the segmentation algorithm at the encoder, that is absent from the decoder implementation. Even though it can be argued that encoder complexity is not a direct concern in the our maskless lithography architecture in Chapter 1, some algorithmic improvements and optimizations to improve the speed of the segmentation are needed. These are addressed with Block C4 algorithm, to be discussed in Chapter 5.

Table 4.4 shows compression results for more modern layer image data with 65 nm

pixels and 5-bit gray layer image data. For each layer, 5 blocks of 1024×1024 pixels are sampled from two different layouts, 3 from the first, and 2 from the second, and the *minimum* compression ratio achieved for each algorithm over all 5 samples is reported. The reason for using minimum rather than the average has to do with limited buffering in the actual hardware implementation of maskless lithography writers. Specifically, the compression ratio must be consistent across all portions of the layer as much as possible. From left to right, compression ratios are reported in columns for a simple run-length encoder, Huffman encoder, LZ77 with a history buffer length of 256, LZ77 with a history buffer length of 1024, ZIP, BZIP2, and C4. Clearly, C4 still has the highest compression ratio among all these techniques. Some notable lossless gray-pixel image compression techniques have been excluded from this table including SPIHT and JPEG-LS. Our previous experiments in [2] have already shown that they do not perform well as simple ZIP compression on this class of data.

Again, the last two rows report the encoder and decoder runtime of the various algorithms on a 1.8GHz Mobile Pentium 4 with 512MB of RAM running Windows XP. Each algorithm is asked to compress and decompress a suite of 10 gray layer image files, and runtimes are measured to the nearest second by hand. Again, the slow speed of the C4 encoder contrasts the fast performance of the C4 decoder.

In Table 4.5, we show results for 10 sample images from the data set used to obtain Table 4.4, where each row is information on one sample image. In the first column “Type”, we visually categorize each sample as repetitive, non-repetitive, or containing

Table 4.5: Percent of each image covered by copy regions (Copy%), and its relation to compression ratios for Linear Prediction (LP), ZIP, and C4 for 5-bit gray layer image data.

Type	Layer	LP	ZIP	C4	Copy%
Repetitive	M1	3.3	7.8	18	94%
	Poly	2.1	6.6	18	99%
Non-Rep.	M1	14	12	16	18%
	Poly	7.3	9.6	14	42%
Mixed	M1	7.5	12	15	44%
	Poly	4.1	10	14	62%
	M2	15	26	35	33%
	N	18	32	52	21%
	P	29	52	80	33%
	Via	7.1	15	32	54%

a mix of repetitive and non-repetitive regions. The second column is the chip layer from which the sample is drawn. The third column “LP” is the compression ratio achieved by linear prediction alone, equivalent to C4 compression with copy regions disabled. The fourth and fifth columns are the compression ratio achieved by ZIP and the full C4 compression respectively. The last column “Copy%” is the percent of the total sample image area covered by copy regions, when C4 compression is applied. Any pixel of the image not covered by copy regions is, by default, linearly predicted from its neighbors.

Clearly, the Copy% varies dramatically from image to image ranging from 18% to 99% across the 10 samples, testifying to C4’s ability to adapt to different types of layouts. In general a high Copy% corresponds to repetitive layout, and low Copy% corresponds to non-repetitive layout. Also, the higher the Copy%, the more favorably ZIP compares to LP compression. This agrees with the intuition that LZ-style

techniques work well for repetitive layout, and prediction techniques work well for non-repetitive layout. At one extreme, in the non-repetitive-M1 row, where 18% of the image is copied in C4, LP's compression ratio exceeds ZIP. At the other extreme, in the repetitive-Poly row, where 99% of the image is copied, ZIP's compression ratio is more than 3 times that of LP. In some cases, the compression ratio becomes high for both LP and ZIP, e.g. the rows labeled Mixed-N and Mixed-P. These layouts contain large featureless areas, which are easily compressible by both copying and prediction. In these cases, C4 favors using prediction to avoid the overhead of specifying copy parameters.

4.7 Tradeoff Between Memory and Compression Efficiency

Compression algorithms, in general, require the use of a memory buffer at the decoder to store information about the compressed data. In general, larger buffers allow more information to be stored, which may lead to higher compression ratios. On the other hand, the size of this buffer, which must be implemented in decoder hardware, has a direct impact on implementation complexity. For copy-based compression algorithms, such as C4, LZ77, and ZIP, the buffer stores previously decoded data to copy from. For BZIP2, the buffer stores the block of data over which block-sorting is performed. For simpler schemes such as Huffman coding, the buffer stores symbol

statistics and the code table. For the very simple run-length code, the buffer stores the current symbol being repeated, and the number of remaining repetitions.

In C4, most of the decoder buffer is used to support the copy operations; after all, data cannot be copied unless it is stored somewhere accessible. Copying from above requires storing multiple rows of image data at the decoder to enable the copy operation. To allow copies from 1 to *maxdy* pixels above, the decoder needs buffering to store the current row, and *maxdy* rows above, for a total of *maxdy* + 1 rows. Clearly, increasing *maxdy* potentially allows more copy regions to be discovered. However each stored row requires *image width* × *bits per pixel* = *bits per row* bits of buffering. Total decoder buffering is *bits per row* × (*maxdy* + 1) + *constant* where the *constant* is used as overhead to support other aspects of C4, i.e. prediction, decoding copy regions. For the 1024 × 1024 image with 5-bit gray pixels used in our experiments, *bits per row* is 5120 bits or 640 bytes, and the constant is 3410 bits or 427 bytes.

Using the same Poly layer layer image data as in Table 4.4, i.e. modern layer image data with 65 nm pixels and 5-bit gray levels, we tested C4 with 2, 32, 64, 128, 256, 1024 stored rows, corresponding to total decoder buffer of 1.7 kB, 21 kB, 41 kB, 82 kB, 164 kB, 656 kB, respectively. Results of the tradeoff between decoder buffer and compression ratio for C4, as compared to run-length, Huffman, LZ77, ZIP, and BZIP2, are shown in Figure 4.10.

The x-axis is the decoder buffer size plotted on a logarithmic scale, and the y-axis

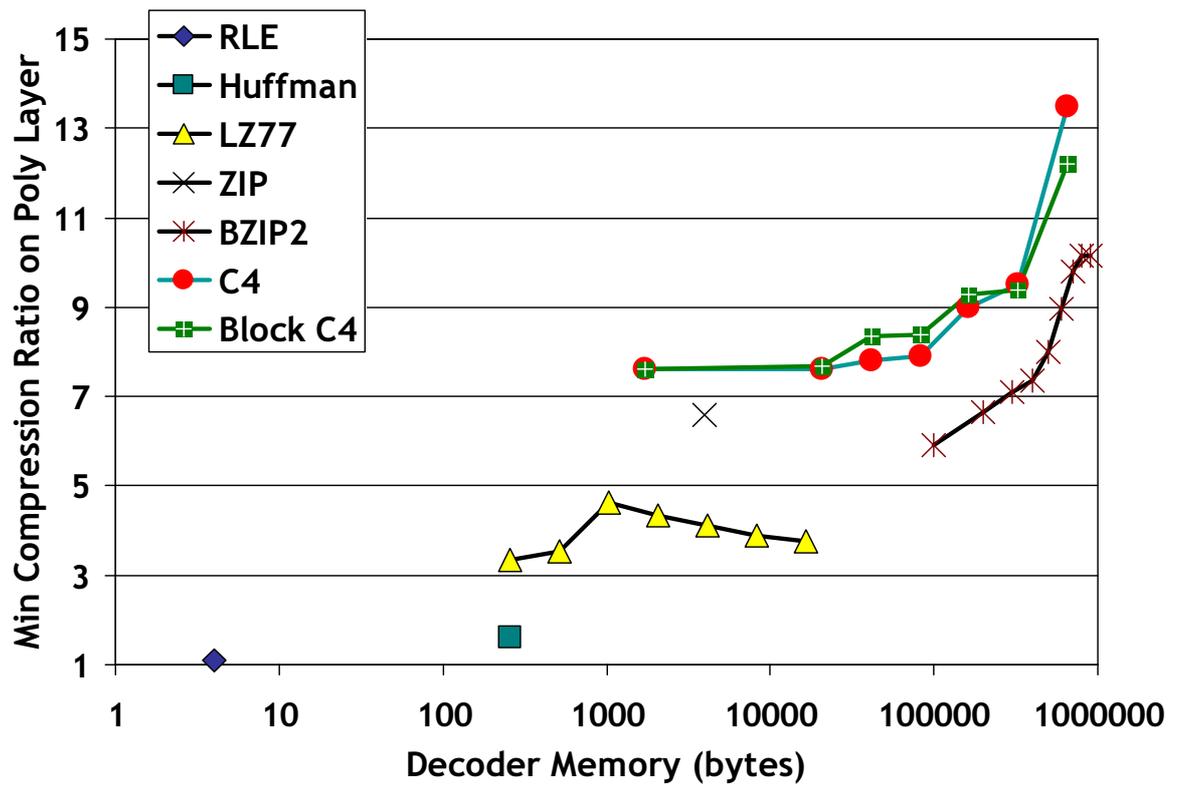


Figure 4.10: Tradeoff between decoder memory size and compression ratio for various algorithms on Poly layer.

is the minimum compression ratio achieved on 5 blocks of 1024×1024 pixels are sampled by hand from 2 different microchip designs, 3 from the first microchip, and 2 from the second. The reason for using minimum rather than the average is that in a practical system, the minimum compression ratio over a layer determines the speed at which the writers operate. Otherwise, we would need to add yet another large buffer to absorb compression ratio variability, so as to smooth out the data rate. Each individual curve represents one compression algorithm. Block C4 is a variation of C4 with a large improvement in encoding speed, to be discussed shortly in Chapter 5.

The C4 and Block C4 curves are nearly the same. Both lie above the curves for BZIP2, ZIP, and LZ77, indicating that variants of C4 offers a higher compression ratio for the same decoder buffer size as BZIP2 and LZ77. Overall, there is an upward trend to the right, implying that larger decoder buffers result in higher compression efficiency, at a cost of increased decoder implementation complexity. For C4, this is caused by an increase in the number of “copy above” regions being uncovered by a larger *maxdy*.

Due to the limited implementation area in the maskless lithography datapath, the likely point of operation is in the 1-10KB region of the graph. In this region, both C4 and Block C4 have a flat curve. Therefore, the most advantageous choice is to use the smallest buffer possible, 1.7 kB with a *maxdy* = 1. In this case, only 2 image rows are stored, the minimum necessary to support prediction, copy left operations

and copying from immediate row above.

Chapter 5

Block C4 - A Fast Segmentation

Algorithm for C4

Block C4 is an improvement to the Context Copy Combinatorial Coding (C4) compression algorithm described in Chapter 4. It provides about the same compression efficiency as C4 but at a tiny fraction of the encoding time. How large is the speedup? In Table 5.1, we compare the compression efficiency and encoding time of two 1024×1024 5-bit grayscale layer images, generated from two different sections of the poly layer of an industry microchip. In columns, from left to right, are the layer image name, C4 compression ratio, C4 encode time, Block C4 compression ratio, and Block C4 encode time. Both C4 and Block C4 use the smallest 1.7 kB buffer, corresponding to only 2 stored rows of data. Encoding times are generated on an Athlon64 3200+ Windows XP desktop with 1 GB of memory. A quick glance

Table 5.1: Comparison of compression ratio and encode times of C4 vs. Block C4.

Image	C4 Comp. Ratio	C4 Encode Time	Block C4 Comp. Ratio	Block C4 Encode Time
Poly-memory	7.60	1608 s (26.8 min)	7.63	14s (115x speedup)
Poly-control	9.18	12113 s (3.4 hrs)	9.18	13.9s (865x speedup)

at this table reveals the speed advantage of Block C4, i.e. 115 times faster for the Poly-memory image, and 865 times faster on the Poly-control image with no loss in compression efficiency. There are some images for which BlockC4 has significantly lower compression efficiency, but the speed advantage is universal. A more complete table of results appears in Section 5.4 of this chapter.

The significance of a speedup of this magnitude in encoding time cannot be understated. Indeed, if we extrapolate from an average encoding time of 30 minutes per 1024×1024 layer image, a $20 \text{ mm} \times 10 \text{ mm}$ chip die with drawn on a 25 nm 5-bit grayscale grid would take over 18 CPU years to encode. Block C4 reduces this to number to 49 CPU days, still a large number, but manageable by today’s multi-CPU compute systems. Another benefit of Block C4, less readily apparent, is a constant computation time of 14 s per 1024×1024 layer image, independent of the layer data, as compared to widely varying computation times of C4, from 27 minutes to 3.4 hours in Table 5.1. A predictable and consistent computation time is important to project planners managing the overall data processing flow, for example, when planning jobs to maximize tool usage.

The remainder of this chapter describes how Block C4 achieves this encoding

speed up with little or no loss to compression efficiency. In Section 5.1, we introduce the segmentation algorithm of C4 and contrast it with Block C4. In Section 5.2, we examine the problem of choosing a block size for Block C4. In Section 5.3, we describe how the Block C4 segmentation is encoded for compression efficiency.

5.1 Segmentation in C4 vs. Block C4

The basic concept underlying both C4 and Block C4 compression is exactly the same. Layer data is characterized by a heterogenous mix of non-repetitive and repetitive structures, examples of which are previously shown in Figures 4.2 and 4.3 respectively. Repetitive structures are better compressed using Lempel-Ziv (LZ) style copying, whereas non-repetitive structures are better compressed using localized context-prediction techniques, as described in Chapter 4. The task of both the C4 and Block C4 encoder is to automatically partition the image between repetitive copy regions, and non-repetitive prediction regions, in a process called *segmentation*. The resulting *segmentation map* indicates which algorithm should be used to compress each pixel of the image, i.e. either copy or prediction. Once the segmentation is complete, it becomes a simple matter to encode each pixel according to this segmentation map. The segmentation must also be encoded and included as part of the compressed data, so that the decoder can know which algorithm to apply to each pixel for decoding.

In fact, the task of computing this segmentation accounts for nearly all the computation time of the C4 encoder. Of the encode times reported in Table 5.1, the encode

time excluding segmentation, is a constant 1.2 seconds, for C4 and Block C4. In other words, over 99.9% of the encode time of C4 and 91% of the encode complexity of Block C4 is attributable to segmentation. Why is segmentation such a complicated task? To answer this question, we need to understand segmentation algorithm for both C4 and Block C4.

In C4, the segmentation is described as a list of rectangular copy regions. An example of a copy region is shown previously in Figure 4.4. Recall that each copy region is a rectangle, enclosing a repetitive section of layer, described by 6 values, the rectangle position (x, y) , width and height (w, h) , the direction of the copy ($dir = left/above$), and the distance to copy from (d) i.e. the period of the repetition.

What makes automated C4 segmentation such a complex task is that the “best” segmentation, or even a “good” segmentation is hardly obvious. Even in such a simple example shown in Figure 4.4, there are many potential copy regions, a few of which are illustrated in Figure 5.1 as colored rectangles, e.g the dashed blue rectangle and a dot-dashed orange rectangle. Assuming a $N \times N$ pixel image, the number of all possible copy regions is $O(N^5)$, where each copy region parameter (x, y, w, h, d) contributes one $O(N)$. Then, choosing the best set of copy regions for a given image is a combinatorial problem. Exhaustive search on this space is prohibitively complex, and C4 already adopts a number of greedy heuristics to make the problem tractable, as described in Chapter 4. However, clearly further complexity reduction of the segmentation algorithm is desirable, for all the reasons we have already described at

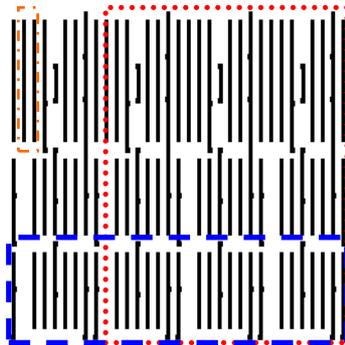


Figure 5.1: Illustration of alternative copy region.

the start of this chapter.

Block C4 adopts an entirely different segmentation algorithm from C4, which is far more restrictive, and therefore much faster to compute. Specifically, C4 allows for copy regions to be placed in arbitrary (x, y) positions with arbitrary (w, h) sizes whereas Block C4 restricts both the position and sizes to fixed $M \times M$ blocks on a grid. Figures 5.2 and 5.3 illustrate the difference between Block C4 and C4 segmentation. In Figure 5.2, the segmentation for C4 is composed of 3 rectangular copy regions, with 6 values (x, y, w, h, dir, d) describing each copy region. In Figure 5.3, the segmentation for Block C4 is composed of 20 $M \times M$ tiles, with each tile marked as either prediction (P), or the copy direction and distance (dir, d) . This simple change reduces the number of possible copy regions to $O(N^3/M^2)$, i.e. N^2/M^2 blocks times $O(N)$ variations on (dir, d) , a substantial N^2M^2 reduction in search space compared to C4. For the experiment in Table 5.1, $N = 1024$ and $M = 8$, so the copy region search space has been reduced by a factor of 64 million. However, this complexity reduction potentially comes at some cost to compression efficiency.

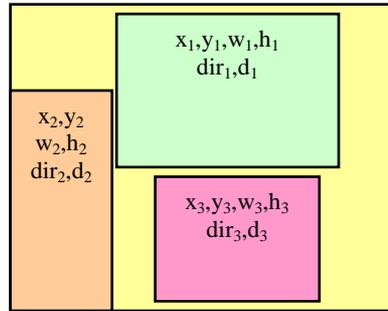


Figure 5.2: C4 Segmentation

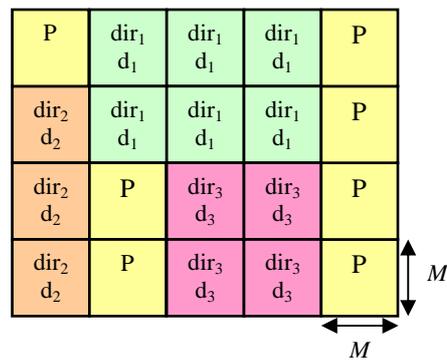


Figure 5.3: Block C4 Segmentation.

5.2 Choosing a block size for Block C4

Comparing the segmentation of C4 in Figure 5.2 to Block C4 in Figure 5.3, we see that what was once 3 large copy regions has been divided into 13 small square blocks in this example. In general, a large repetitive $w \times h$ region is broken up into approximately wh/M^2 tiles in Block C4. Even though each copy region tile in BlockC4 is represented with only 2 values (dir, d) , whereas each copy region in C4 is represented with 6 values (x, y, w, h, dir, d) , if a sufficiently large region is broken up into tiles, there might be a net increase in the amount of data needed to store the segmentation information. This extra data translates into lower compression ratios. Smaller values of M accentuate this effect, motivating the use of larger M ; however, larger values of M cause the following quantization problem: Comparing the segmentation of C4 in Figure 5.2 to Block C4 in Figure 5.3, we see that the rectangles are forced to snap to the coarse grid in Block C4. In C4, the rectangle boundaries are optimized in order to separate repetitive regions from non-repetitive regions. In Block C4, the coarse grid causes this separation to be sub-optimal. Consequently, at the boundary of the copy regions, we might observe repetitive regions which are predicted, and non-repetitive regions which are copied. This sub-optimal segmentation lowers the compression efficiency. Of course, the smaller and finer the grid, the less grid snapping occurs, motivating the use of a smaller M .

These arguments would suggest that there is an optimal M value that trades off between grid snapping and the breakup of large copy regions. Empirically, we have

found among the values of $M = 4$, $M = 8$, and $M = 16$, $M = 8$ exhibits the best compression efficiency for nearly all test cases. The reason for this requires further investigation and is outside the scope of this thesis. Our Block C4 algorithm offers the block size as a tunable parameter. In this thesis, we set $M = 8$ for Block C4 unless otherwise specified.

5.3 Context-based block prediction for encoding

Block C4 segmentation

To further improve the compression efficiency of Block C4, we note that the segmentation shown in Figure 5.3 is highly structured. Indeed, consider that the segmentation represents boundaries in a layer image separating repetitive regions from non-repetitive regions, and that these repetitions are caused by design cell hierarchies, which are placed on an Manhattan grid. Consequently, Block C4 segmentation has an Manhattan structure, and C4 already employs a reasonable method for compressing Manhattan structures placed on a grid, namely context-based prediction.

To encode the segmentation, blocks are treated as pixels, and the (P, dir, d) triplet as a “color”. The value of the triplet $z = (P, dir, d)_z$ is predicted from its 3-block neighborhood $a = (P, dir, d)_a$, $b = (P, dir, d)_b$, and $c = (P, dir, d)_c$, as shown in Figure 5.4. The prediction formula is the following conditional: *if* $(c = a)$ *then* $z = b$, *else* $z = c$. For vertical copy region boundaries, it is true that $c = a$ and $z =$

a	b	$\text{If } (c = a) \text{ then } z = b$ $\text{else } z = c$
c	z	

Figure 5.4: 3-block prediction for segmentation in Block C4

P	dir ₁ d ₁	dir ₁ d ₁	dir ₁ d ₁	P	P	dir ₁ d ₁	√	√	P
dir ₂ d ₂	dir ₁ d ₁	dir ₁ d ₁	dir ₁ d ₁	P	dir ₂ d ₂	dir ₁ d ₁	√	√	√
dir ₂ d ₂	P	dir ₃ d ₃	dir ₃ d ₃	P	√	P	dir ₃ d ₃	√	P
dir ₂ d ₂	P	dir ₃ d ₃	dir ₃ d ₃	P	√	√	√	√	√

(a) (b)

Figure 5.5: (a) Block C4 segmentation (b) with context-based prediction.

b , so the prediction is accurate. For horizontal copy region boundaries, the center of copy regions, and the center of prediction regions, it is true that $z = c$ so the prediction is accurate. Consequently, prediction failures occur only near the corners of copy regions. Applying context-based block prediction to the segmentation in Figure 5.5(a), we get the result in Figure 5.5(b) where $\sqrt{\quad}$ marks indicate correct predictions. The pattern of $\sqrt{\quad}$ marks is compressed using hierarchical combinatorial coding (HCC) and the remaining values of (P, dir, d) are Huffman coded, exactly analogous to the method of coding copy/prediction error location bits and error values used in C4.

5.4 Compression results for Block C4

As we have seen in the previous sections, Block C4 speeds up C4 by introducing a coarse fixed grid of $M \times M$ pixel blocks for the segmentation. This change dramatically reduces the size of the search space for copy regions, resulting in a large speedup of the encoding time. In general, the coarse grid results in lowered compression efficiency, but we have tuned the block size, and applied context-based block prediction to reduce this effect. The full table of results, comparing Block C4 to C4 is shown in Table 5.2. In it, we compare the compression efficiency and encoding time of various 1024×1024 5-bit grayscale images, generated from different sections and layers of an industry microchip. In columns, from left to right, are the layer image name, C4 compression ratio, C4 encode time, Block C4 compression ratio, and Block C4 encode time. Both C4 and Block C4 use the smallest 1.7 kB buffer, corresponding to only 2 stored rows of data. Encoding times are generated on an Athlon64 3200+ Windows XP desktop with 1 GB of memory.

A quick glance at this table makes clear the speed advantage of Block C4 over C4 is universal, over 100 times faster than C4, for images of all layers and sections of layout tested. In general, the compression efficiency of Block C4 matches that of C4. One exception is row 5 of Table 5.2, where C4 significantly exceeds the compression efficiency of Block C4, on the highly regular M1-memory layer image.

On this image, C4's compression ratio is 13.1, while Block C4's compression ratio is 9.5. The reason is that in this particular case, the layout of the polygons is

Table 5.2: Comparison of compression ratio and encode times of C4 vs. Block C4 for 1024×1024 , 5 bpp images.

Image	C4 Comp. Ratio	C4 Encode Time	Block C4 Comp. Ratio	Block C4 Encode Time
Poly-memory	7.60	1608 s (26.8 min)	7.63	14s (115x speedup)
Poly-control	9.18	12113 s (3.4 hrs)	9.18	13.9s (865x speedup)
Poly-mixed	10.59	1523 s (25.4 min)	11.35	13.9s (110x speedup)
M1-memory	13.1	3841 s (1.1 hrs)	9.50	13.9s (276x speedup)
M1-control	18.7	13045 s (3.6 hrs)	17.3	13.9s (938x speedup)
M1-mixed	15.5	13902 s (3.9 hrs)	14.7	13.9s (1000x speedup)
Via-dense	10.2	3350 s (55.8 min)	15.5	14.1s (237x speedup)
Via-sparse	16.0	7478 s (2.1 hrs)	21.6	13.7s (546x speedup)

extremely repetitive, and C4 covers 99% of the entire 1024×1024 image with only 132 copy regions. Moreover, many of these copy regions are long narrow strips, less than 8-pixels wide, which Block C4 cannot possibly duplicate. Consequently, Block C4 exhibits a significant loss of compression efficiency as compared to C4, in this particular case.

On the other hand, in the last two rows of Table 5.2, the compression ratio of Block C4 significantly exceeds the compression ratio of C4 for the dense and sparse Via layer images. The reason for this is that the Via layer consists of a large number of small squares scattered like flakes across the image. It is best compressed with a large number of small copy regions, each covering a few squares. Block C4 has two

advantages in this case: first, it uses fewer bits to represent each copy region than C4; second, it takes advantage of correlations between copy regions, using context-based block prediction. For example, in the Via-sparse layer image, C4 applies 945 copy regions to cover only $\approx 50\%$ of the layout. In contrast, BlockC4 covers $\approx 96\%$ of the same image with copy regions, thereby achieving significantly higher compression ratio.

Chapter 6

Full Chip Characterizations of Block C4

From the results of the previous chapter, it is clear that Block C4 enjoys several advantages over C4. First, its encoding time is 2 orders of magnitude faster than C4. Second, its run time is consistently predictable; all the variations in speedup in Table 5.2 come from wildly varying runtimes in C4. Third, its compression ratio is comparable, if not equal to that of C4.

With the speedup and consistent runtimes provided by Block C4, it becomes reasonable to consider runs on full chip, multi-layer layouts, something that remains nearly impossible to do for C4. In these next set of experiments, we re-examine the comparison between Block C4, ZIP, and BZIP2, only this time, statistics are presented for a full production industry microprocessing chip, rather than individual

images sampled here and there across a chip.

The layout used for these calculations are for an industry standard microprocessor designed for the 65nm device generation. The specifications for manufacturing this design is shown in Table 6.1. The layout is $8.3mm \times 14.1mm$ in size with polygons laid out on a 1nm grid. The appropriate pixel size for this generation is $32nm \times 32nm$, with 33 (0-32) levels of gray to achieve 1nm edge placement control, which requires 6-bits per pixel. The computed rasterized pixel image data is 2.1 Tb per chip layer, 241 Tb per wafer layer. The manufacturing throughput requirement for lithography is 1 wafer layer per 60s. Therefore, the required average maskless lithography data rate over one wafer layer is 4.0 Tb/s.

This data rate is 1/3 the 12 Tb/s we have projected in Table 1.1 for two reasons. First, this microprocessor is a 65 nm chip design, and as such, its pixel size is $(65/45)^2 = 2$ times larger in area than that of a 45 nm chip. A $2 \times$ larger pixel means 1/2 the number of pixels per unit area, and therefore, 1/2 the data per unit area. Second, this microprocessor is only $8.3mm \times 14.1mm = 117mm^2$ which is approximately 2/3 the size of the $10mm \times 20mm = 200mm^2$ chip, as assumed in Table 1.1. The combination of these two factors, a larger device generation, and a smaller chip design, accounts for the $1/2 \times 2/3 = 1/3$ reduction in data rate, as compared to the data rate in Table 1.1.

In previous chapters, individual layout clips are characterized as dense, sparse, repetitive, and non-repetitive, with each term intuitively defined by visual inspection.

Table 6.1: Specifications for an industry microprocessor designed for the 65nm device generation.

Manufacturing specifications		Maskless lithography specifications	
Minimum feature	65 nm	Pixel size	32 nm
Edge placement	1 nm	Pixel depth	6 bits (0-32) gray
Chip size	8.3 mm \times 14.1 mm	Pixel data (one chip layer)	689 Gb
Wafer size	300 mm	Wafer data (one wafer layer)	241 Tb
Wafer throughput (one layer)	1 wafer per 60s	Average data throughput	4.0 Tb/s over one wafer layer

This manual ad hoc characterization does not scale to a full chip run. Instead, we define here a metric for polygon complexity which intuitively matches to the concept of “dense”, namely the number of polygon vertices within a given area, or *vertex density*. If the number of vertices is large in a fixed area, then it must be caused by either the presence of many distinct polygons, or polygons with very complex fragmented edges. In either case, for the simple 3-pixel prediction mechanism used by C4 and BlockC4, the number of vertices is directly correlated with the number of context-based prediction errors, as we have shown previously in Section 4.2.

In terms of repetitions, it is difficult to find a single metric that decisively determines this for a 2D image and that is reasonable to compute for such a large data set. One method would have been to use the same search based segmentation used by LZ77/C4 itself, but this defeats the purpose of having an independent metric. Other techniques evaluated, such as image correlation, window-based DCT do not correlate well with the copy mechanism of C4 and LZ77 where the cost of even correcting a small 1% intensity error is fairly high. Such techniques are more appropriate for lossy

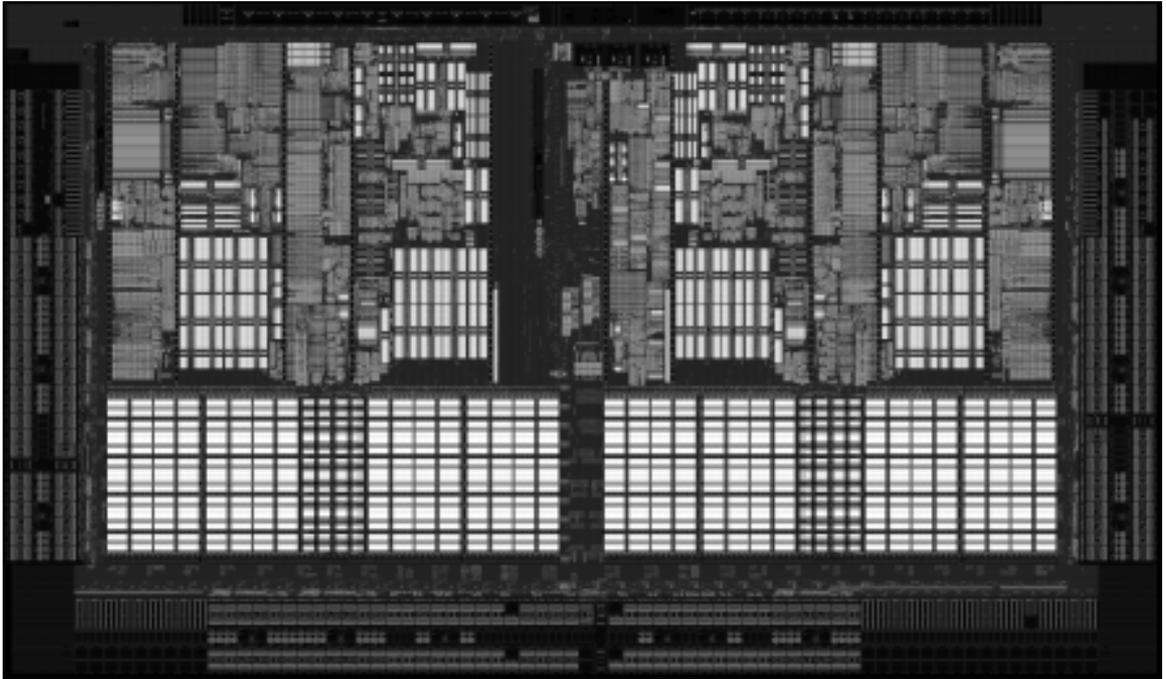


Figure 6.1: A vertex density plot of poly gate layer for a 65nm microprocessor.

compression techniques where such errors may be ignored. In the end, we choose to use a metric taken from the layout hierarchy itself. The measure of repetition is defined as the number of cells in a given region, minus the number of unique cells in that same region. As an example, suppose a region contains 5 instances of cell A, 4 instances of cell B, and 1 instance of C, D, and E. Then the total number of cells in that region is $5 + 4 + 1 + 1 + 1 = 12$ whereas the total number of unique cells is 5 (A-E), so the “repetition” of this region is 7.

In order to provide a visualization of these metrics, Figure 6.1 shows a grayscale picture of the vertex density metric as applied to the poly gate layer. Each pixel in this picture corresponds to a $32\mu\text{m} \times 32\mu\text{m}$ block of the chip. Vertex densities range from 0 to 20,000 per block. Higher vertex density blocks are assigned brighter pixels, and

lower corner vertex density blocks are assigned darker pixels. It is easy to discern from this image regions of very high vertex densities that are arranged in rectangular arrays throughout the design. These are the various memory arrays of the microprocessor. The darker grays are likely to be logic circuit areas, also arranged in rectangular arrays. Finally, the periphery regions are very dark, indicating low corner densities.

A plot of “repetitions” visually looks the same as Figure 6.1. Although there are small differences in the data which are detectable through data analysis, it is impossible to visually discern these differences. The visual similarity between a plot of “repetitions” and a plot of vertex density justifies the fundamental rationale behind C4. Highly dense layout regions are also highly repetitive, and therefore compress well with copying techniques. Non-repetitive regions tend to be sparse, and hence compress well with context based prediction techniques, as polygon corners generally correspond to prediction errors for Manhattan geometries.

As a point of comparison, the vertex density plot of Metal1 is shown in Figure 6.2. Although there are a few discernable differences, for the most part, Figures 6.1 and 6.2 look very similar as well.

For each of the $32\mu m \times 32\mu m$ blocks, rasterization is performed using the methodology described in Chapter 2, where the pixel size is 32nm, and 33 gray levels are allowed (0-32) resulting in a fine 1nm edge placement grid. One full chip layer contains 116,328 such blocks, equal to the number of pixels in Figure 6.1. Each rasterized block is then passed through 3 compression algorithms, ZIP, BZIP2, and Block C4

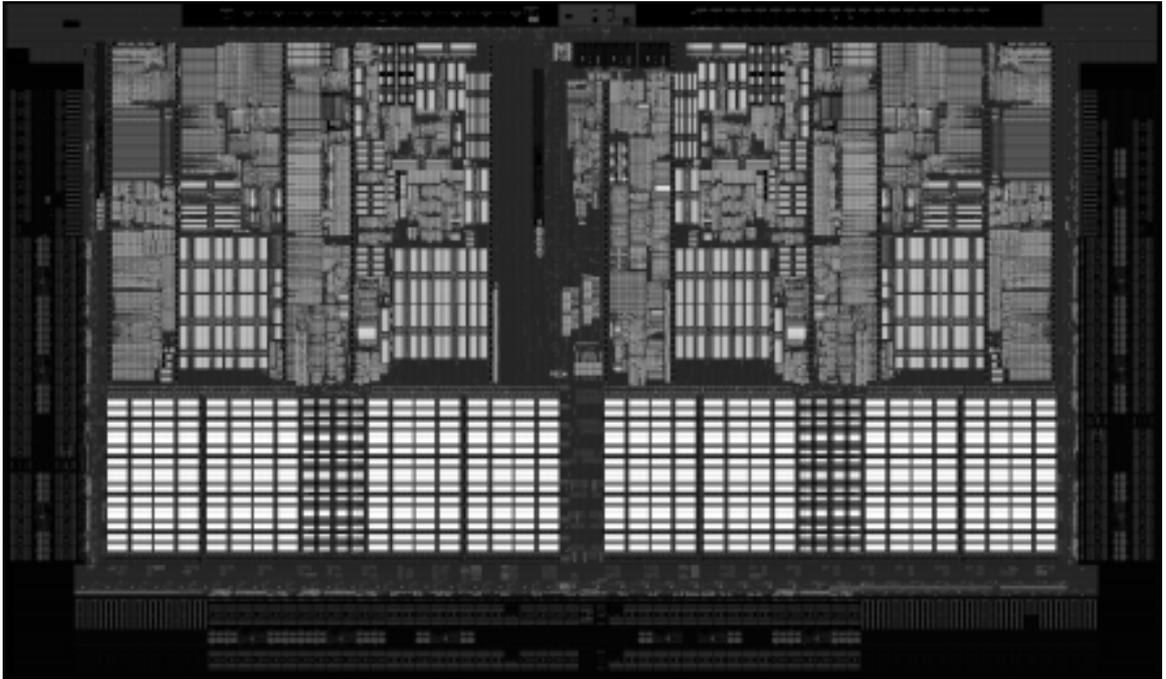


Figure 6.2: A vertex density plot of Metal1 layer for a 65nm microprocessor.

and compression and decompression statistics are gathered for each. This process is then repeated for all the critical layers of the design: diffusion, also known as active, poly, contact, metal1, via1 and metal2.

For this experiment, decoder buffer size of ZIP, BZIP2 and Block C4 are 4kB, 900 kB, and 1.7 kB respectively, chosen based on the tradeoff analysis presented in Section 4.7. The small buffer size used by Block C4 makes it particularly attractive for implementation in hardware for the datapath architecture presented in Chapter 1.

6.1 Full chip compression statistics

Table 6.2 contains a summary of these full chip runs. Column 1 is the name of the full-chip statistic being reported. Column 2 is the chip layer which is rasterized and compressed. Columns 3, 4, and 5 are the statistics for ZIP, BZIP2 and Block C4 respectively. Each row in the table represents a layer statistic. The relevant statistics reported are the average compression ratio for the entire layer, the minimum compression ratio over individual $32\mu m \times 32\mu m$ blocks, the total encoding run time for each layer, the total decoding run time for each layer, and the percentage of blocks with compression ratio below 10.

Examining the average compression ratio for all layers, the compression efficiency of ZIP is generally lower than that of BZIP2 and Block C4. BZIP2 and Block C4 are generally comparable to each other. Considering that BlockC4 uses 2 or 3 orders of magnitude less decoder buffer to achieve more or less the same compression efficiency as BZIP2, clearly it is the algorithm of choice for hardware implementation. From layer to layer, Metal1 is most challenging to compress, followed by Metal2, Via1, Poly, Contact, then Active. One different characteristic of Poly layout in this particular design style is that all gates are oriented in a single direction, and are spaced apart by a characteristic common pitch. Regularized design styles such as these can take better advantage of the copy mechanism in C4 to achieve high compression efficiency. Of particular concern is the average compression ratio of the Metal1 and Metal2 layers which are 5.2 and 7.2 respectively, which fall below the target compression ratio of

Table 6.2: Full-chip compression summary table.

Statistic	Layer	ZIP	BZIP2	Block C4
Avg. Compression Ratio	Poly	12.6	15.3	14.1
	Metal1	4.2	4.5	5.2
	Metal2	6.1	7.2	7.2
	Contact	14.1	16.0	23.2
	Active	20.2	31.7	39.2
	Via1	12.3	14.1	14.0
Min. Compression Ratio	Poly	2.6	3.1	4.4
	Metal1	0.96	1.3	1.7
	Metal2	1.0	1.3	2.1
	Contact	2.7	4.3	4.8
	Active	8.1	11.1	12.8
	Via1	2.2	3.6	4.5
Total Encoding Time	Poly	42 min	2.3hrs	420 hrs
	Metal1	45 min	2.3hrs	420 hrs
	Metal2	45 min	1.9hrs	408 hrs
	Contact	46 min	2.1hrs	419 hrs
	Active	43 min	1.9hrs	418 hrs
	Via1	46 min	2.1hrs	419 hrs
Total Decoding Time	Poly	17 min	1.2hrs	36 min
	Metal1	14 min	1.2hrs	35 min
	Metal2	19 min	1.4hrs	38 min
	Contact	15 min	1.4hrs	38 min
	Active	15 min	1.3hrs	37 min
	Via	15 min	1.4hrs	38 min
Percentage of Blocks with Compression Ratio Below 10 (lower is better)	Poly	25.33%	22.84%	23.66%
	Metal1	65.73%	59.69%	55.12%
	Metal2	44.20%	44.88%	41.95%
	Contact	0.73%	0.07%	0.00%
	Active	7.85%	0.00%	0.00%
	Via	4.94%	0.22%	0.14%

10 presented in Chapter 1.

Another important metric to consider is the minimum compression ratio over all $32\mu m \times 32\mu m$ blocks for a layer. This is the most difficult block of any given layer to compress. In this case, only the Active layer meets a target compression ratio of 10. The remaining 5 layers fall below that target, and in the worst case block of Metall1, the compression ratio is 1.7.

6.2 Managing local variations in compression ratios

So what are the implications of missing the compression target, and which is more relevant, the average compression ratio, or the more pessimistic minimum compression ratio? The answer depends on how well the maskless lithography system as a whole can absorb *local variations* in data throughput. This can be accomplished by physically varying the throughput of the maskless lithography writers, or by introducing various mechanisms in the datapath to absorb these variations which we will speculate on later. By *local variations*, we are referring to inter-block variations of compression ratios. In choosing our block size for analysis, we already assume there is at least a single block buffer in the system so that we may ignore intra-block variations in compression ratio. This buffer is distinct from the memory used by the decompression hardware. An example of such a buffer is the “SRAM Writer Interface” found

in [39].

6.2.1 Adjusting board to chip communication throughput

In the worst case, (a) the maskless lithography writers are fixed at a constant writing speed over all blocks of a layer; and (b) the datapath cannot help absorb these inter-block variations of compression ratios. In this case, the writing speed is limited by the data throughput of the minimum compression ratio block. From the the maskless datapath presented in Chapter 1, the formula to compute actual wafer throughput is $r_{wafer} = r_{comm,max} \times C_{min}/d_{wafer}$ where r_{wafer} is the wafer layer throughput, $r_{comm,max}$ is the maximum board to chip communication throughput, C_{min} is the minimum compression ratio for Block C4, and $d_{wafer} = 241$ Tb is the total data for one wafer layer, from Table 6.1.

Since d_{wafer} is fixed and C_{min} has been empirically determined for each layer, the total wafer throughput depends entirely on $r_{comm,max}$ which is the *maximum* data throughput of board to chip communication. The reason maximum is emphasized is that this throughput is only required for the minimum compression ratio block. For blocks of higher compression ratio, the communication throughput can be reduced. As an example, if maximum communication throughput $r_{comm,max} = 1$ Tb/s, then the wafer layer throughput for Metall1 is $1 \text{ Tb/s} \times 1.7 / 241 \text{ Tb} \times 3600\text{s/hr} = 25.5$ wafer layers per hour. This same formula can be applied to each layer for various assumed values of $r_{comm,max}$. The results of this exercise are shown on Table 6.3.

Table 6.3: Maximum communication throughput vs. wafer layer throughput for various layers in the worst case scenario, when data throughput is limited by the minimum compression ratio for Block C4.

Layer	C_{min}	$r_{comm,max}(Tb/s)$	$r_{wafer}(wafer \cdot layer/hr)$
Poly	4.4	1	65.7
Metal1	1.7	1	25.5
Metal2	2.1	1	31.4
Contact	4.8	1	71.7
Active	12.8	1	191
Via1	4.5	1	67.2
Poly	4.4	0.91	60
Metal1	1.7	2.36	60
Metal2	2.1	1.91	60
Contact	4.8	0.83	60
Active	12.8	0.31	60
Via1	4.5	0.89	60

The columns of Table 6.3 are layer, minimum compression ratio, maximum board to chip communication throughput, and wafer layer throughput, respectively. In the first 5 rows, we assume a maximum communication throughput of 1 Tb/s and compute the wafer throughput for various layers. In the next 5 rows, we target a wafer throughput of 60 wafer layers per hour, and compute the maximum communication throughput needed to support this writing rate for each layer. As a point of reference, a state-of-the-art HyperTransport 3.0 (HT3) link offers 0.32 Tb/s maximum throughput [40]. Examining Table 6.3 for Metal1 with a target wafer throughput of 60 wafers per hour, a maskless datapath requires at least $\lceil 2.36/0.32 \rceil = 8$ such links to achieve the required communications throughput. Implementing 8 links is costly, in terms of both circuit power dissipation and chip area [34] [23]. However, a chip designer may be able to conserve power by taking advantage of the fact that the

Table 6.4: Average communication throughput vs. wafer layer throughput for various layers, computed using the average compression ratio for Block C4.

Layer	C_{min}	$r_{comm,avg}(Tb/s)$	$r_{wafer}(wafer \cdot layer/hr)$
Poly	14.1	1	211
Metal1	5.2	1	77.7
Metal2	7.2	1	108
Contact	23.2	1	347
Active	39.2	1	586
Via1	14.0	1	209
Poly	14.1	0.28	60
Metal1	5.2	0.77	60
Metal2	7.2	0.56	60
Contact	23.2	0.17	60
Active	39.2	0.10	60
Via1	14.0	0.29	60

maximum communication throughput is only needed for a few blocks. The average communication throughput, as we shall see shortly, is significantly lower.

The equation relating wafer throughput r_{wafer} to average board to chip communication throughput $r_{comm,avg}$ and average compression ratio C_{avg} is straightforward: $r_{wafer} = r_{comm,avg} \times C_{avg}/d_{wafer}$. To be precise, the average is computed over all blocks of an wafer layer. Using this formula, we can relate wafer throughput to average communication throughput for various layers. The results are presented in Table 6.4. The columns are layer, average compression ratio, average board to chip communication throughput, and wafer layer throughput, respectively. The first 5 rows assume an average communications throughput of 1 Tb/s, and the next 5 rows target a wafer throughput of 60 wafer layers per hour.

Since the average compression ratio is significantly higher than the minimum compression ratio for all layers, the average communication throughput is also significantly

lower than the maximum communication throughput computed previously. Continuing our previous example using a HT3 link as reference, for Metal1 with a target wafer throughput of 60 wafers per hour, a maskless datapath requires only $0.77/0.32 = 2.4$ links on average. So even though 8 links are required to accommodate the maximum throughput, on average only $2.4/8 = 30\%$ of the capacity is being used. The maskless datapath can take advantage of this by powering down unused communication links to conserve power. However, that still leaves an area cost of implementing 8 links in the first place. What can be done to effectively smooth the data throughput so that communication links can be utilized more effectively?

6.2.2 Statistical multiplexing using parallel decoders

An important feature to take advantage of is the opportunity to utilize averaging inherent in the parallel design of the maskless lithography datapath. As described in [41], the decoder in Figure 1.9 is implemented as a parallel array of decoder paths, i.e. multiple blocks are being decoded simultaneously. In its simplest form, the communication throughput is evenly divided among the parallel decoder paths. However, additional logic, such as packet scheduling, can be implemented to allocate communications throughput to each decoder path based on need. As such, a decoder path working on a block with low compression ratio is allocated more communication packets than a decoder path working on a block with high compression ratio. The result is that inter-block variations in compression ratio is effectively statistically multiplexed

by the number of decoder paths in the system.

Suppose we have N decoder paths working in parallel on N adjacent blocks in a row. In communication order, we form M frames of N blocks per frame, where $MN \geq 116,326$. Statistical multiplexing effectively allows us to average the compression ratio over each frame. We can then compute the minimum over all frames and denote this value as $C_{min,N}$. Note, that by definition $C_{min,1} = C_{min}$ and $C_{min,116,328} = C_{avg}$. $C_{min,N}$, r_{wafer} and $r_{comm,max}$ are related through this equation: $r_{wafer} = r_{comm,max} \times C_{min,N}/d_{wafer}$.

Using different values for N , we compute the $C_{min,N}$ and $r_{comm,max}$ for Block C4, Metall1, and a target throughput of 60 wafer layers per hour. These results are summarized in Table 6.5. In columns are the number of decoder paths N , the minimum frame compression ratio $C_{min,N}$, the maximum board to chip communications throughput $r_{comm,max}$, the wafer throughput r_{wafer} , and the number of HT3 links needed to support the communications throughput. Clearly, $C_{min,N}$ increases as the number of decoder paths N increases. At $N = 1000$, $C_{min,N} = 4.9$ which is very close to $C_{avg} = 5.2$, demonstrating the strength of the statistical multiplexing approach. The corresponding maximum communication throughput is 0.82 Tb/s which can be met with $\lceil 0.82/0.32 \rceil = 3$ HT3 links.

Table 6.5: Effect of statistical multiplexing using N parallel decoder paths on Block C4 compression ratio and communication throughput for Metal1.

N	$C_{min,N}$	$r_{comm,max}(Tb/s)$	$r_{wafer}(wafer \cdot layer/hr)$	# of HT3 links
1	1.7	2.36	60	8
2	2.3	1.74	60	6
10	2.5	1.60	60	5
100	3.3	1.21	60	4
1000	4.9	0.82	60	3
116,328	5.2	0.77	60	3

6.2.3 Adding buffering to the datapath

Another way to smooth the data throughput is to introduce a memory buffer at the output of the communications channel before decompressing the data in Figure 1.9. The resulting system resembles Figure 1.7, except the memory buffer is much smaller. This buffer absorbs variations in data throughput caused by inter-block variations of compression ratios. For blocks with high compression ratio, excess communication throughput is used to fill the buffer. For blocks with low compression ratio, data is drained from the buffer to supplement the communication channel. Intuitively, the larger the buffer is, the more variations it can absorb, and the lower is the required maximum communication throughput. On the other hand, the primary advantage of spending area on a buffer in the first place is to save on chip area devoted to communication. Therefore, there is a tradeoff between the area needed by the buffer and the additional area saved by reducing the number of communication links.

We can roughly estimate the amount of buffer to add using the following steps. Suppose we add sufficient buffer equivalent to the minimum compressed block. For Metal1, this buffer is $(1000 \times 1000 \times 6bits)/1.7 = 3.5Mb$ in size for Block C4. Now

suppose, in communication order, we group blocks pairwise and compute each pair's compression ratio, followed by computing the minimum over all pairs $C_{min,pair}$. This number is guaranteed to be higher than C_{min} and lower than C_{avg} . Empirically for Metall1, $C_{min,pair} = 2.3$ for Block C4, assuming raster scan order. For this system, the following inequality holds: $r_{wafer} \geq r_{comm,max} \times C_{min,pair}/d_{wafer}$. That is, at the very least, we should be able to replace C_{min} with the higher $C_{min,pair}$ for relating wafer throughput to the maximum communication throughput. Continuing our previous example for Metall1 with a target wafer throughput of 60 wafers per hour, the result is $r_{comm,max} \leq 1.74Tb/s$, equivalent to $\lceil 1.74/0.32 \rceil = 6$ HT3 links. Compared with the 8 HT3 links for zero buffering, this is a reduction of 2 links for 3.5Mb of buffering, which seems to be worthwhile tradeoff. Clearly, more systematic analysis of such tradeoffs are necessary for any future practical maskless lithography systems.

6.2.4 Distribution of low compression blocks

The computation of $r_{comm,max}$ in the previous paragraph is a conservative upper bound, in that it focuses on the worst case where low compression ratio blocks may be clustered together. Thus, we require that any drain on the buffer caused by a low compression ratio block to be immediately refilled by the adjacent block. If low compression blocks are spread far apart from each other by coincidence, then $r_{comm,max}$ may be significantly lowered. Furthermore, if the writing system allows for limited re-ordering of the blocks, then this could be used to intentionally spread

the low compression ratio blocks apart. As an example, some maskless lithography systems are written in a step-and-scan mode, where multiple blocks form a frame which is written in a single scan [41]. In this case, blocks may be re-ordered within a frame to smooth the data rate.

Figure 6.3 is a visualization of the compression ratio distribution of Block C4 for the Metal1 layer. Brighter pixels are blocks with low compression ratios and darker pixels are blocks with high compression ratios. Notice that repetitive memory arrays on the bottom half are relatively dim. Block C4 compresses these repetitive regions effectively. The less regular, but relatively dense layout are clustered in distinct bright regions in the middle. This geographic distribution should be taken into consideration when deciding on the mechanism to smooth inter-block variations.

6.2.5 Modulating the writing speed

Another possibility is to modulate the writing speed of the maskless lithography writers to match the inter-block variations in compression ratio. For example, it is conceivable to divide blocks into discrete classes based on the range of compression ratios they fall into. The lithography writers would then switch between a discrete number of writing speeds depending on the class of block. The “high” compression ratio blocks are written with “high” speed, whereas “low” compression ratio blocks are written with “low” speed. Due to overhead in switching speeds, it may not be feasible to vary the writing speed on a block-by-block basis. In this case, the writers

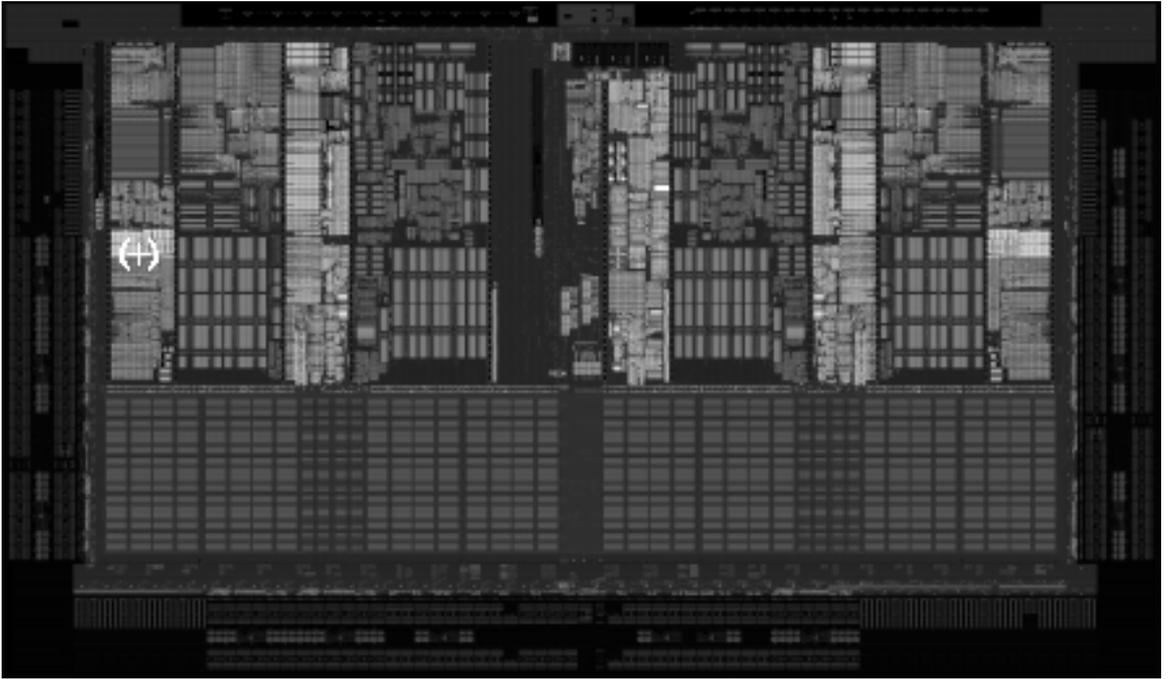


Figure 6.3: A visualization of the compression ratio distribution of Block C4 for the Metal1 layer. Brighter pixels are blocks with low compression ratios, while darker pixels are blocks with high compression ratios. The minimum 1.7 compression ratio block is marked by a white crosshair (+).

would change speed based on the minimum compression ratio within a contiguous group of blocks.

Whichever mechanism is used to smooth the data throughput, the effectiveness depends on the distribution of compression ratios across all blocks of a layer. Intuitively, the higher the number of low compression ratio blocks, the more difficult it is to lower the maximum communication throughput. Let us examine the distribution of these variations.

6.3 Distribution of compression ratios

Figure 6.4 shows the histogram of compression ratios for the full-chip Poly layer for Block C4, C4, and BZIP2. The horizontal axis is the compression ratio bins ranging from 0 to 40 in increments of 1. The vertical axis is the count of the number of blocks which fall into each bin. The histogram of Block C4 is plotted in red with diamond markers, BZIP2 in green with square markers, and ZIP in blue with triangular markers. The first observation to be made about this histogram is that the distribution of compression ratios is multi-modal and non-Gaussian. Second, note that the distribution has an extremely long tail beyond 30. In general, layout contains a large amount of blank regions filled by a few large polygons. The information content in these regions are low, and compress easily.

An alternative view of the same data is presented in Figure 6.5. In this case, we plot the cumulative distribution of blocks on the vertical axis, against the compression

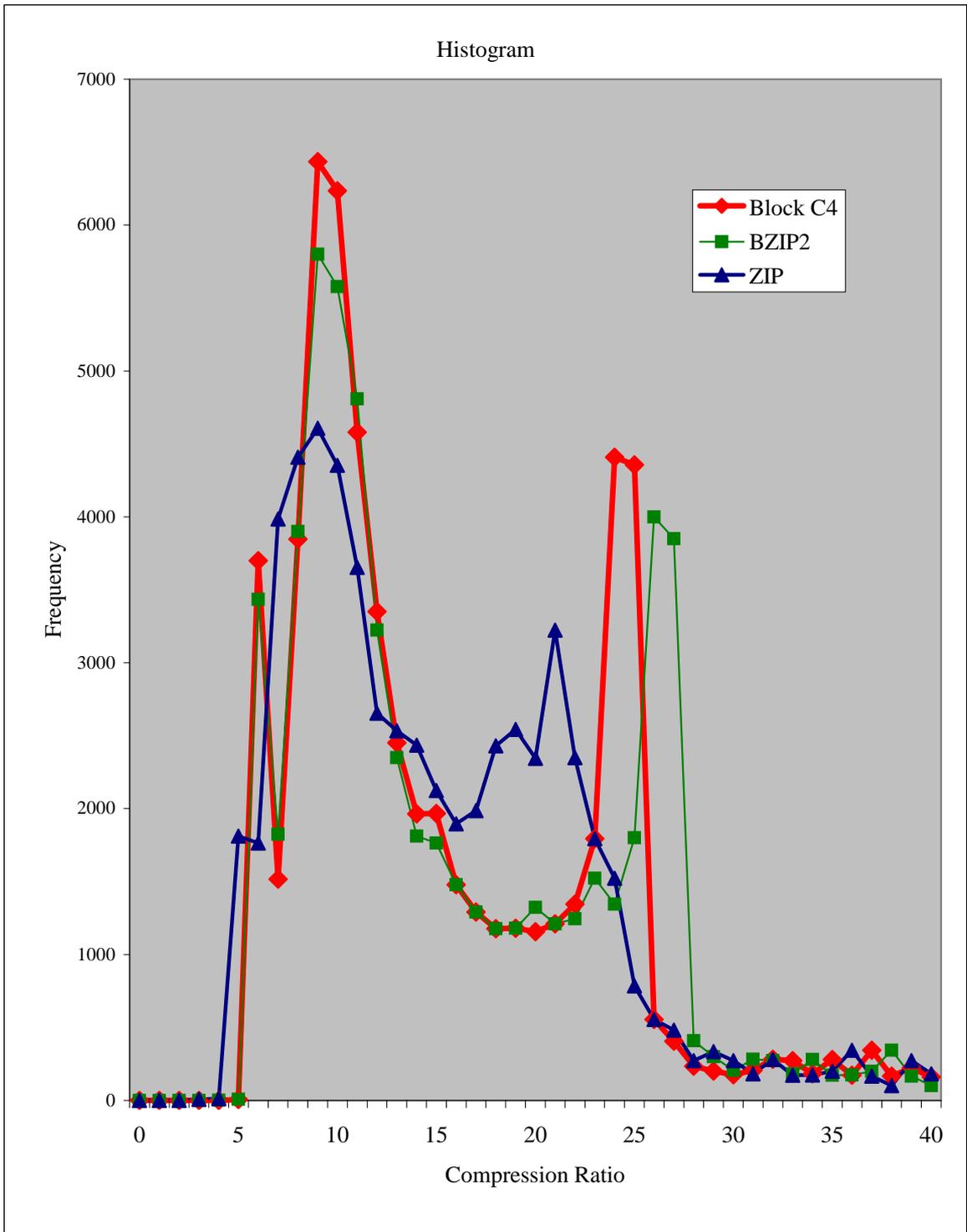


Figure 6.4: Histogram of compression ratios for BlockC4, BZIP2, and ZIP for the Poly layer.

ratio on the horizontal axis. Figure 6.5 is essentially the normalized integral of the plot in Figure 6.4. The cumulative distribution function (CDF) of the compression ratio of Block C4 is plotted in red with diamond markers, BZIP2 in green with square markers, and ZIP in blue with triangular markers. A point on the CDF curve represents the percentage of blocks Y with compression ratio less than X . Generally speaking, when the curve shifts to the right, the overall compression efficiency of a layer is improved.

Of particular interest is compression ratio bins at the low end of the spectrum, as these are our throughput bottlenecks. In Figure 6.5, 25.3% of ZIP blocks, 22.8% of BZIP2 blocks, and 23.7% of Block C4 blocks have compression ratio less than 10. Therefore, in the low end of the compression spectrum, Block C4 and BZIP2 have about the same compression efficiency, and both have better efficiency than ZIP. In addition, even though the reported minimum compression ratio in Table 6.2 for Block C4 and BZIP2 are 4.4 and 3.1 respectively, the CDF curve clearly shows that very few blocks have compression ratios less than 5. In fact, for this poly layer, only 7 of the 116,328 blocks have compression ratio's less than 5 for Block C4 and BZIP2. These 7 blocks are clustered in 2 separate regions, and within a region no two blocks are adjacent to each other. The total size for these 7 blocks compressed by Block C4 is 9.1 Mb. Therefore, if we have enough memory buffer to simply store all 7 compressed blocks then we can effectively use 5 as the minimum compression ratio for Poly. On the other hand, $2.8\% \approx 1800$ of ZIP blocks have compression ratio less than 5. Since

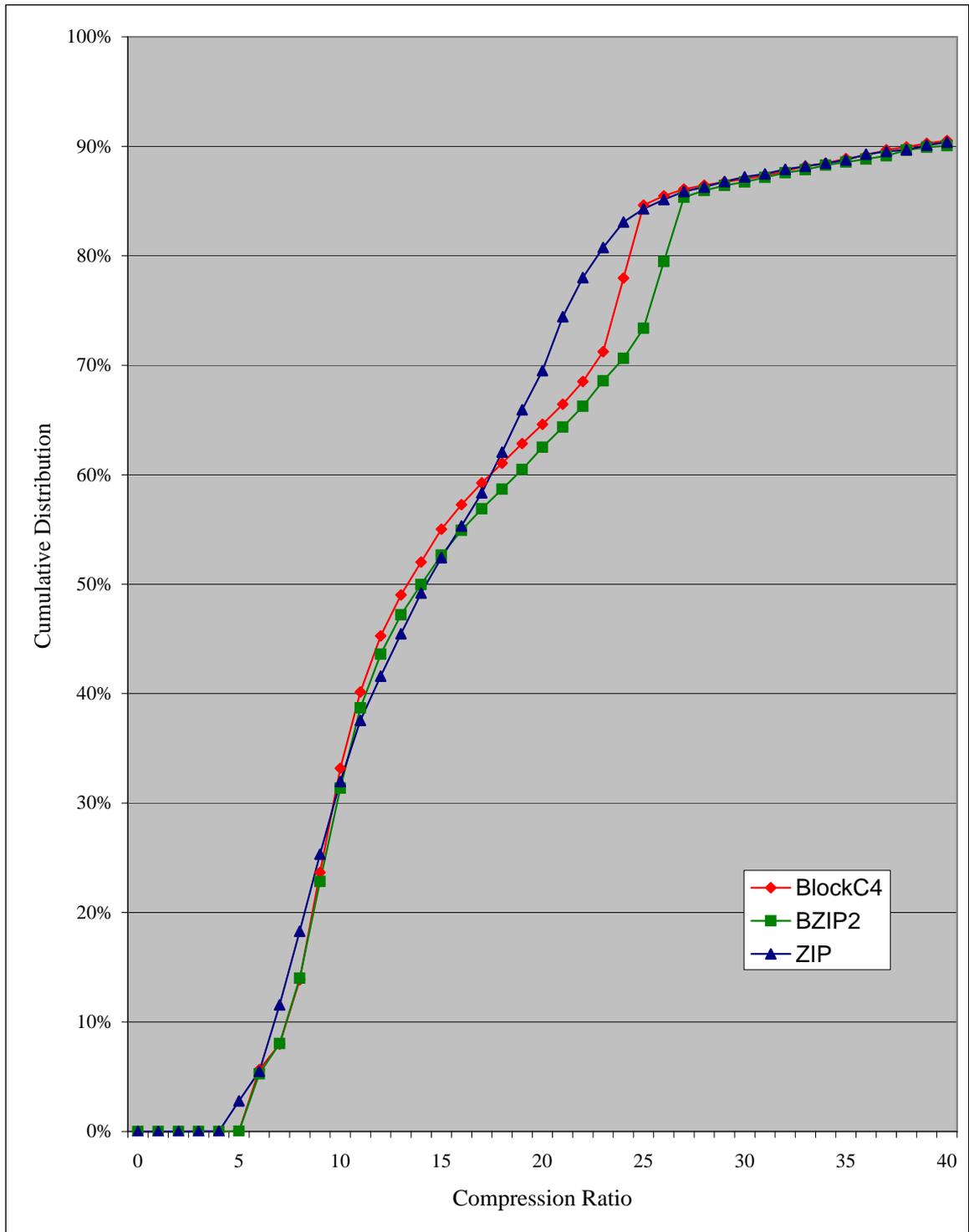


Figure 6.5: Cumulative distribution function (CDF) of compression ratios for BlockC4, BZIP2, and ZIP for the Poly layer.

there are more variations, the system has to work harder to absorb them.

An alternative to absorbing the variation is to re-examine the compression algorithm to look for ways to compress these difficult blocks more efficiently. Figures 6.6 and 6.7 are samples of such hard to compress blocks for Poly and Metal1 layout. The key observation to make is that these blocks are dense in polygon count, and yet are not regular repeated structures, although some repetition does exist. Metal1 is more dense and less repetitive, and therefore has significantly lower compression ratio than Poly. Increasing the buffer size of BlockC4 from 1.7 kB to 656 kB does improve the compression efficiency, but not by a commensurate amount. For the Poly block in Figure 6.6, the Block C4 compression ratio improves from 4.4 to 5.1, and for the Metal1 block in Figure 6.7, the Block C4 compression ratio improves from 1.7 to 1.9.

Another way to gauge the difficulty of compressing the blocks in Figures 6.6 and 6.7 is to compute the entropy. Entropy is the theoretical minimum average number of bits needed to losslessly represent each pixel, assuming pixels are independently and identically distributed. This assumption does *not* hold for layout pixel data. Nonetheless, entropy still serves as a useful point of reference. For Figure 6.6, the entropy is 3.7 bits per pixel (bpp) which corresponds to a compression ratio of $6bpp/3.7bpp = 1.6$. For Figure 6.7, the entropy is 4.8 bpp, which corresponds to a compression ratio of $6bpp/4.8bpp = 1.3$. Huffman coding realizes a compression ratio very close to entropy: 1.6 and 1.2 for Figures 6.6 and 6.7 respectively.

Another alternative is to systematically change the layout so as to improve its

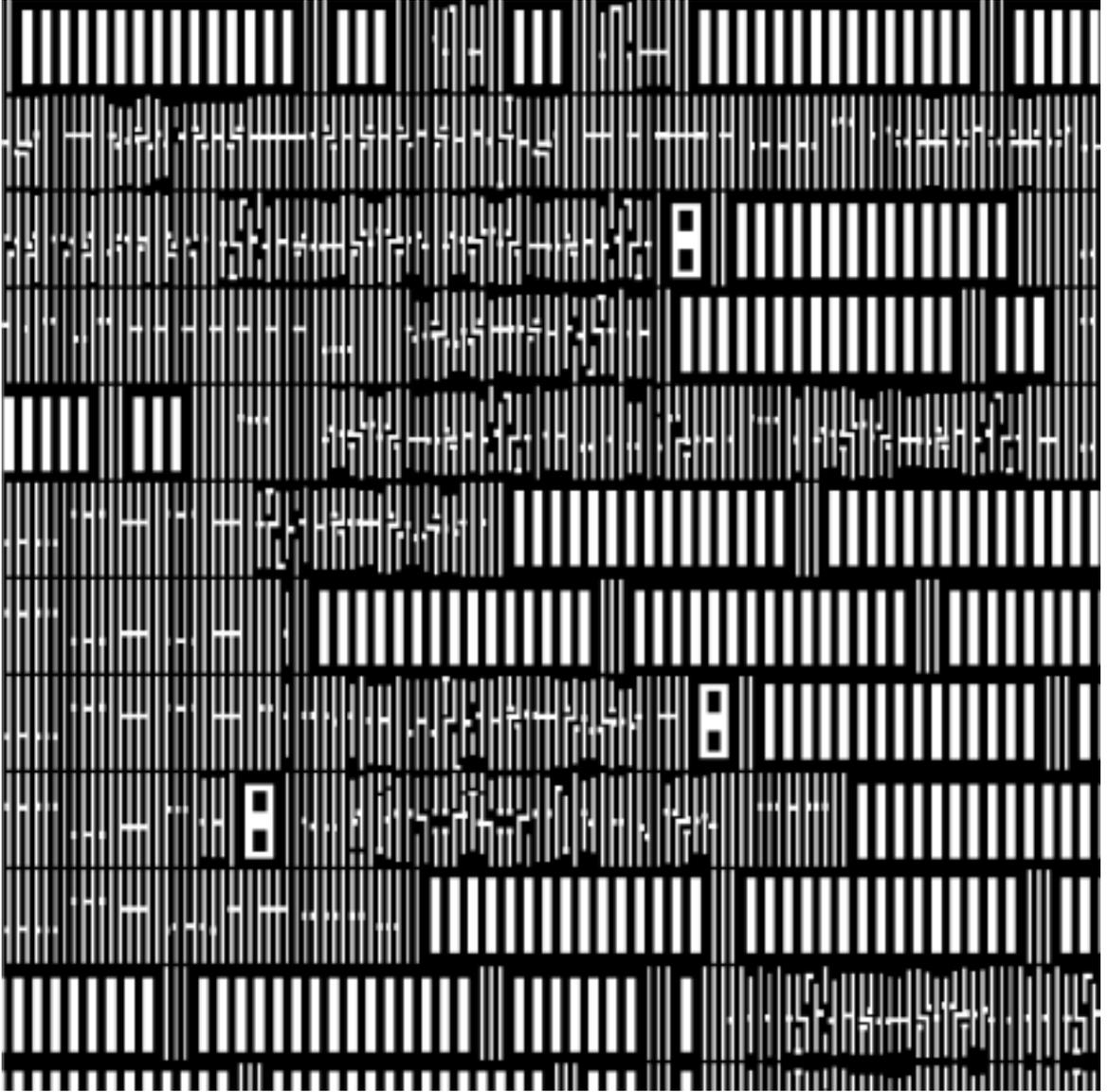


Figure 6.6: A block of the poly layer which has a compression ratio of 2.3, 4.0, and 4.4 for ZIP, BZIP2, and Block C4 respectively.



Figure 6.7: A block of the M1 layer which has a compression ratio of 1.1, 1.4, and 1.7 for ZIP, BZIP2, and Block C4 respectively.

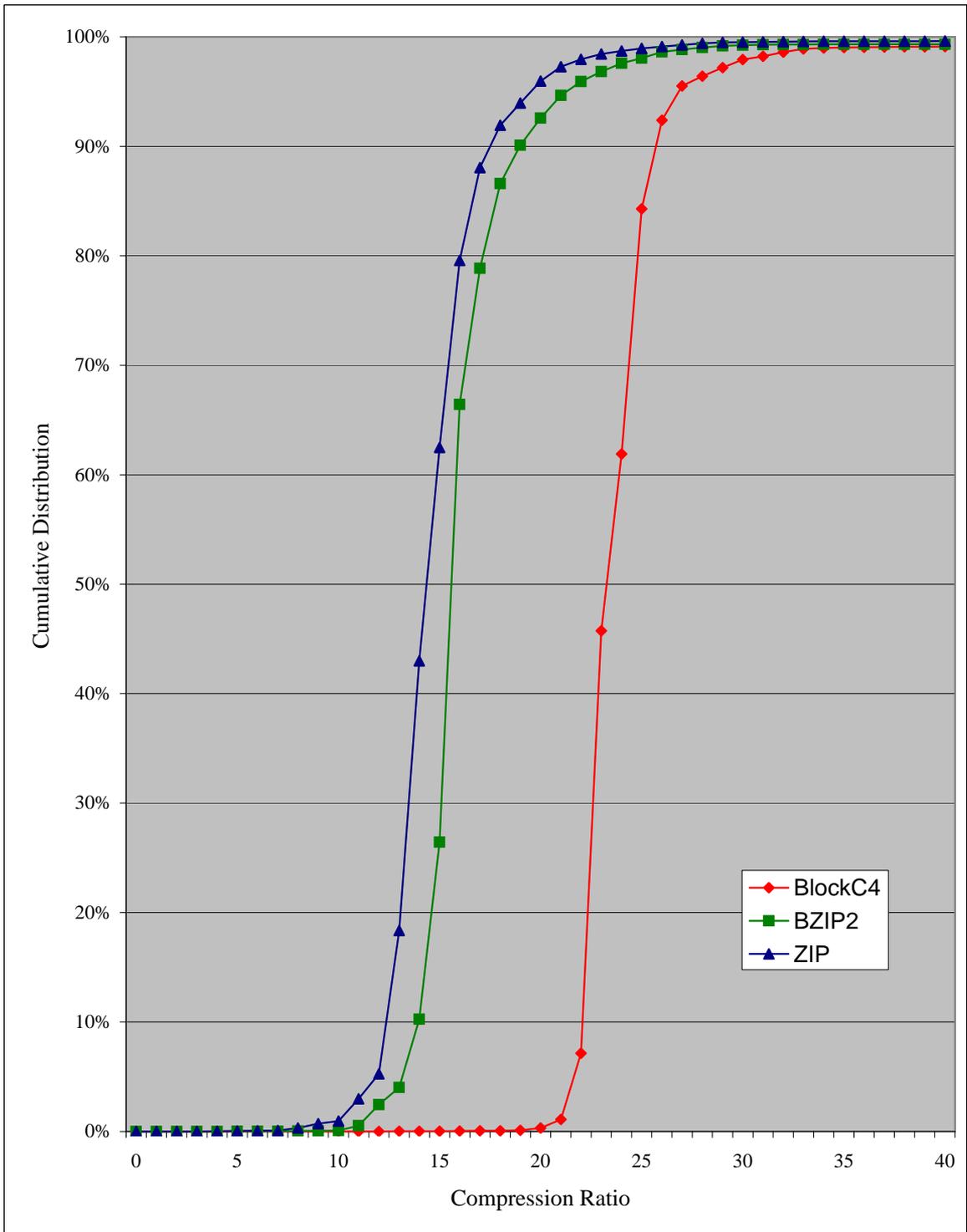


Figure 6.8: CDF of compression ratios for BlockC4, BZIP2, and ZIP for the Contact layer.

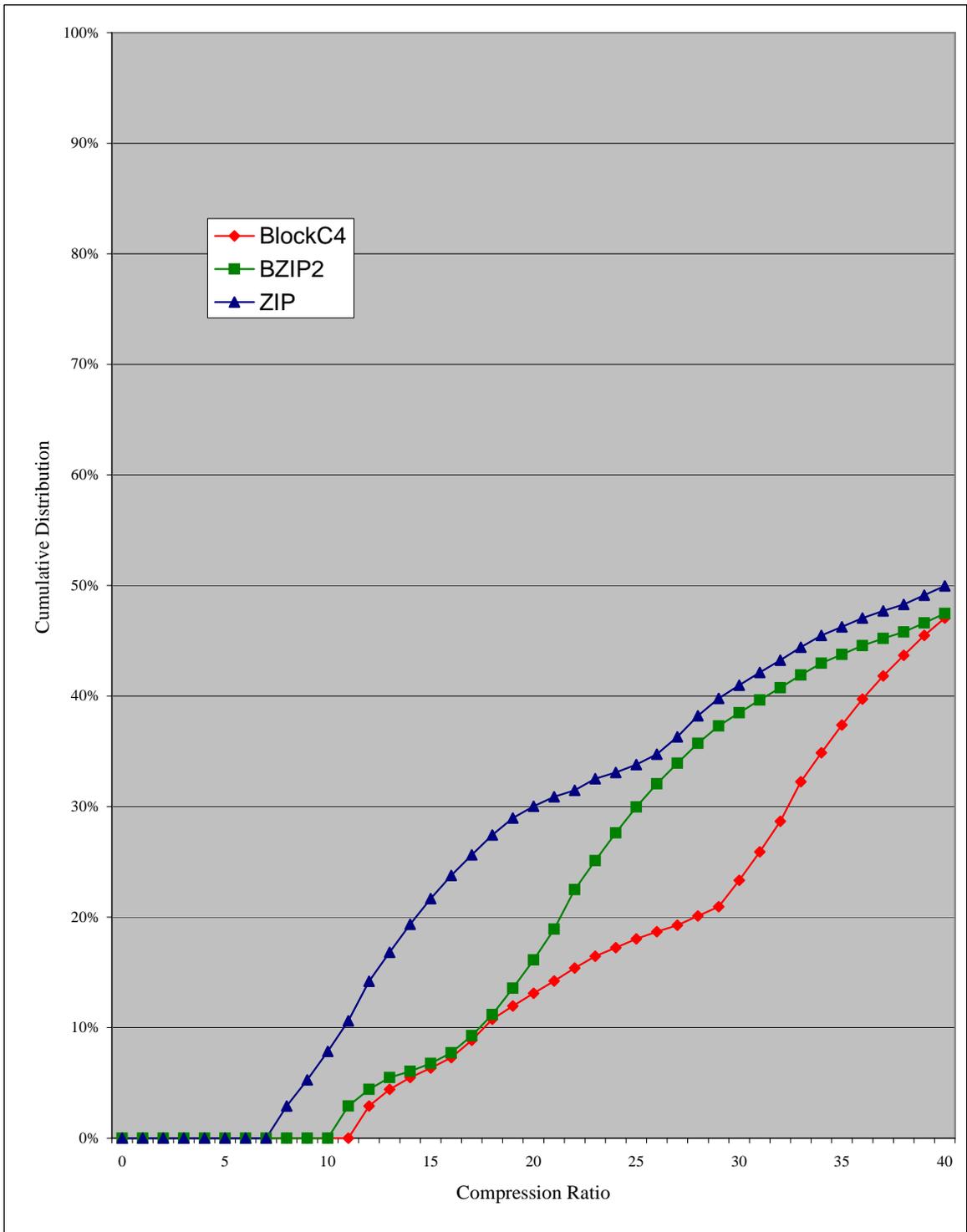


Figure 6.9: CDF of compression ratios for BlockC4, BZIP2, and ZIP for the Active layer.

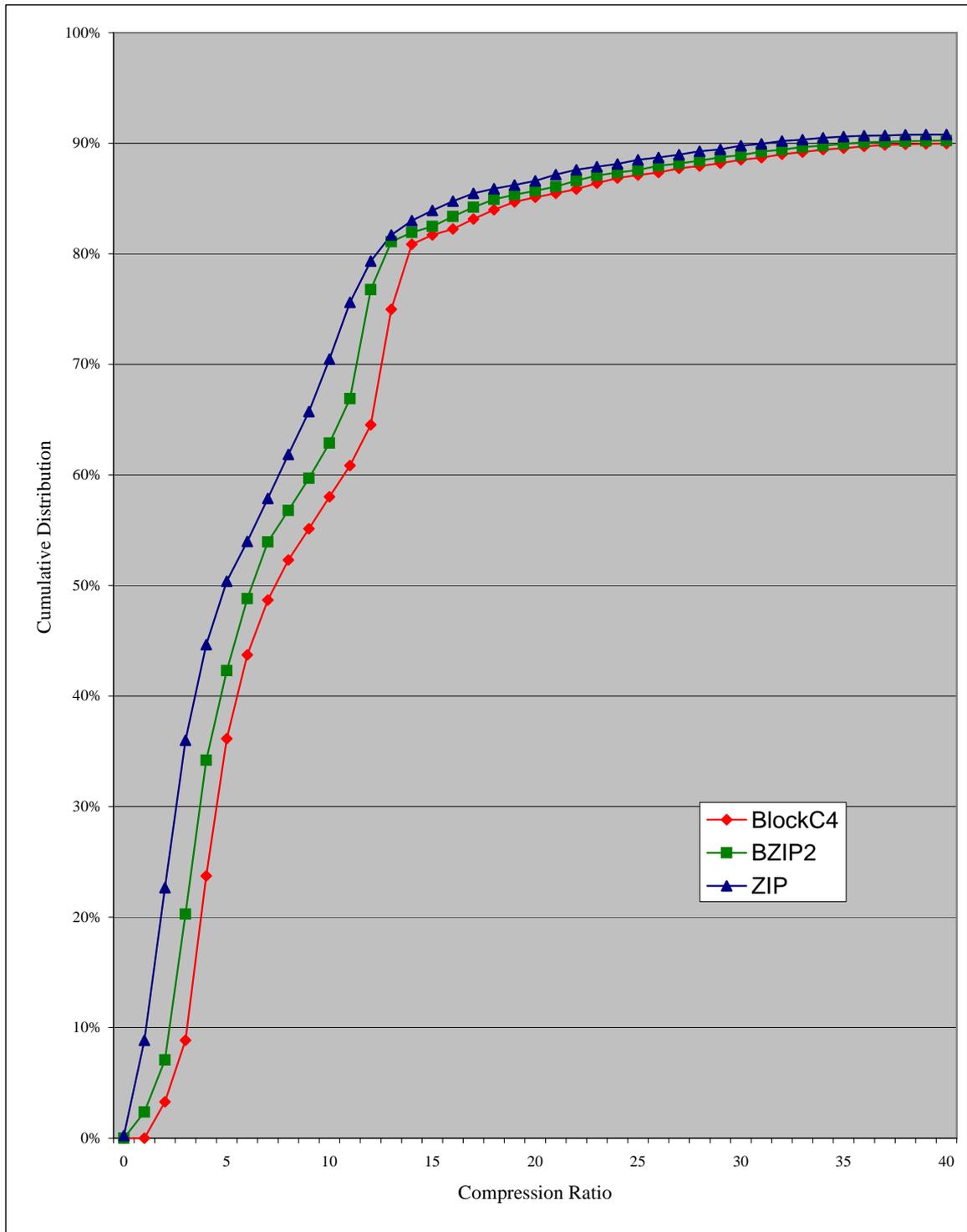


Figure 6.10: CDF of compression ratios for BlockC4, BZIP2, and ZIP for the Metal1 layer.

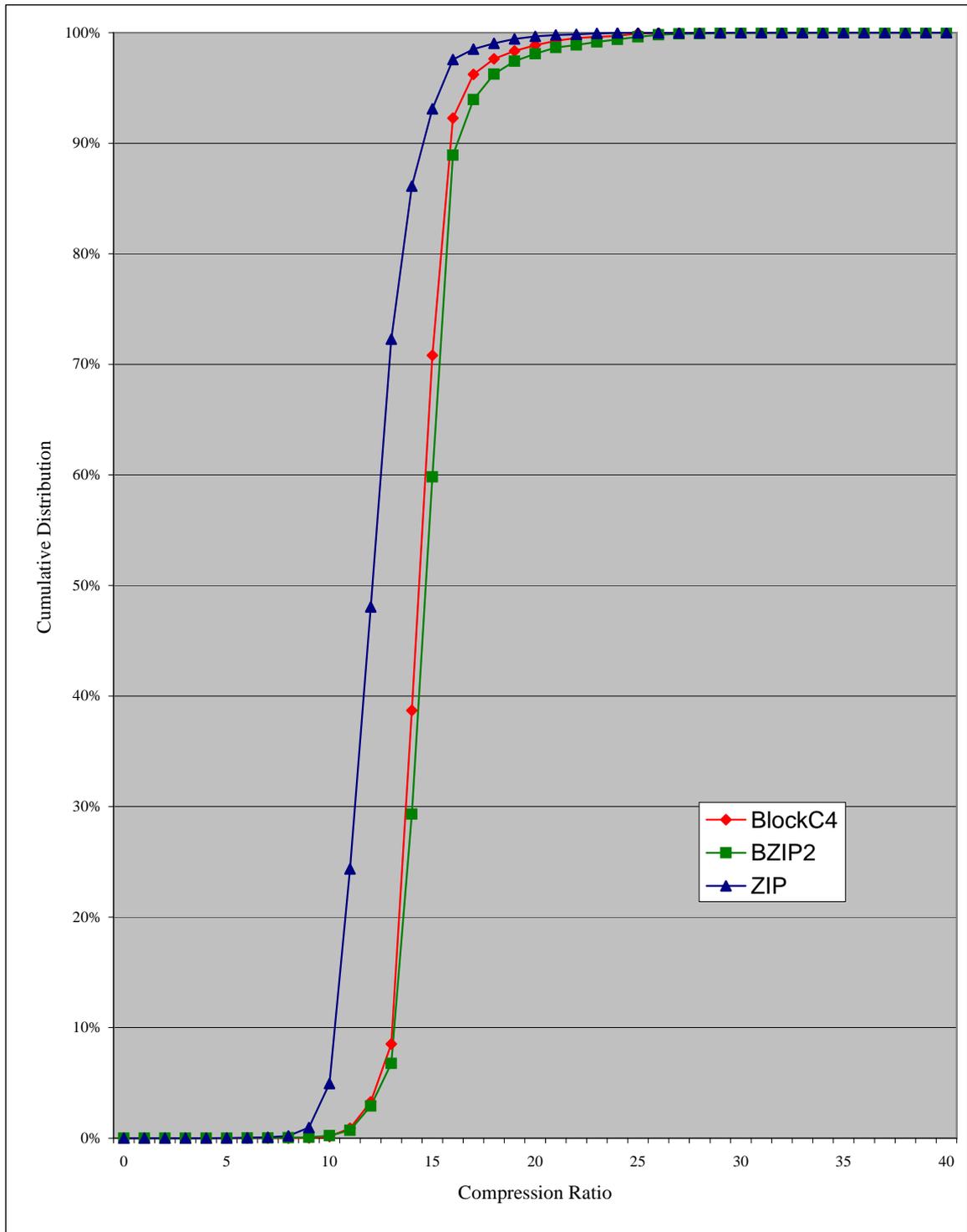


Figure 6.11: CDF of compression ratios for BlockC4, BZIP2, and ZIP for the Via1 layer.

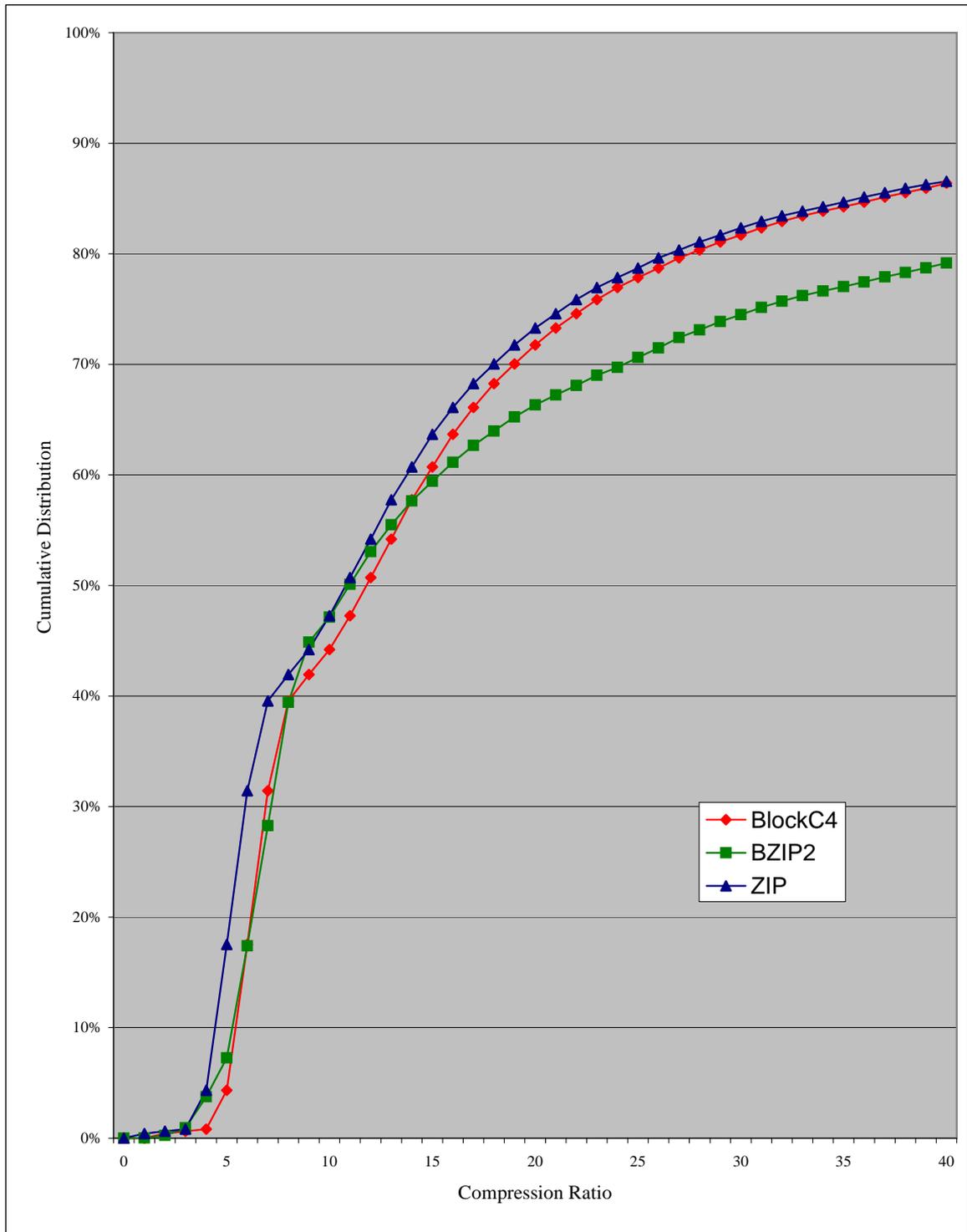


Figure 6.12: CDF of compression ratios for BlockC4, BZIP2, and ZIP for the Metal2 layer.

compression efficiency. It is usually possible to preserve the same design intent using a different physical layout. If the design can be made more “compression friendly” in these difficult blocks, then the compression efficiency can be improved.

For completeness of analysis, Figures 6.8 to 6.11 show the CDF plots of Contact, Active, Metal1, Via1, and Metal2 layers respectively. Examining these plots, Block C4 clearly has higher compression efficiency for Contact, Active, and Metal1 layers than both BZIP2 and ZIP. For the Via1 and Metal2 layers, the compression efficiency of Block C4 is comparable to BZIP2, particularly in the region of compression ratios less than 10. Both Block C4 and BZIP2 have higher efficiency than ZIP.

Comparing the curves between levels, clearly Metal1 is the most difficult to compress. For a given low compression ratio threshold, for example 5, Metal1 has the largest percentage of blocks falling below that threshold, i.e. 24% for Block C4. Metal2 follows with 0.81% for Block C4. The remaining layers contain no blocks below that threshold. Table 6.6 lists the complete numbers for all layers and compression algorithms using a low compression ratio threshold of 5. The reason Metal1 and Metal2 are particularly challenging is simple. These layers are the primary wiring layers connecting device to device, and as anyone who has untangled cables behind a personal computer can attest, wires quickly turn into a complex mess if not carefully managed. Intuitively, this means that the wiring layers tend to be more dense, and less regular than the other chip design layers, making them the most difficult to compress. The density of polygon corners makes it difficult for context predic-

Table 6.6: Percentage of blocks with compression ratio less than 5.

Statistic	Layer	ZIP	BZIP2	Block C4
Percentage of Blocks with Compression Ratio Below 5 (lower is better)	Poly	0.03%	0.00%	0.00%
	Metal1	44.63%	34.20%	23.72%
	Metal2	4.33%	3.75%	0.81%
	Contact	0.02%	0.00%	0.00%
	Active	0.00%	0.00%	0.00%
	Via	0.01%	0.00%	0.00%

tion to achieve good compression, and the irregularity of the design makes it difficult for copying to achieve good compression. The Block C4 segmentation algorithm is stuck between the proverbial rock and a hard place. Nonetheless, to the extent that some compression has been achieved, the algorithm does benefit from having both prediction and copying. As an example, turning off copying reduces the Block C4 compression ratio to 1.4 from 1.7 for the Metal1 block shown in Figure 6.7.

6.4 Excluding difficult, low compression results

Another question we can ask is, if we can exclude the 100 most difficult to compress blocks out of 116,328 blocks, either via buffering or some other mechanism, what is the minimum compression ratio for each layer? The result is shown in Table 6.7. For Metal1, Metal2, and Active, there is little change. However, for Poly, Contact and Via, there is a significant improvement. For these layers, the minimum compression ratio is pessimistic due to a small number of special cases. If these small number of variations can be absorbed by the maskless lithography system, or by systematically altering the design to be more compression-friendly, the overall wafer throughput can

Table 6.7: Minimum compression ratio excluding the lowest 100 compression ratio blocks.

Statistic	Layer	ZIP	BZIP2	Block C4
Min. Compression Ratio over all blocks	Poly	2.6	3.1	4.4
	Metal1	0.96	1.3	1.7
	Metal2	1.0	1.3	2.1
	Contact	2.7	4.3	4.8
	Active	8.1	11.1	12.8
	Via1	2.2	3.6	4.5
Min. Compression Ratio excluding the lowest 100 compression ratio blocks	Poly	4.1	5.2	5.2
	Metal1	1.0	1.4	1.8
	Metal2	1.4	2.5	2.5
	Contact	8.1	10.0	19.8
	Active	8.1	11.1	12.9
	Via	8.2	10.5	11.0

be improved significantly.

6.5 Comparison of encoding and decoding times

Examining the encoding times in Table 6.2, clearly ZIP is the fastest, BZIP2 is about 3 times slower than ZIP, and Block C4 about 20 times slower than BZIP2. Part of the reason that Block C4 is so much slower is the inherent complexity of the Copy/Context prediction segmentation code, and another part is the lack of code optimization. Unlike BlockC4, both ZIP and BZIP2 have been optimized in C code. All 3 algorithms have fairly stable and predictable runtimes which are independent of the layer. This is a significant advantage over the layer dependent and extremely long runtimes of C4 we have seen previously.

Examining decoding times, ZIP is again the fastest, but here Block C4 is faster

than BZIP2 by a factor of 2. Considering Block C4's decode buffer requirement is 2 orders of magnitude less than BZIP2, it is clearly the best choice for hardware implementation. Block C4 is a highly asymmetric algorithm in terms of encoder vs. decoder complexity because segmentation is not required by the decoder, and consequently, its decoding speed is about 40 times faster than its encoding speed.

6.6 Discussion

In summary, the results of this chapter validate the observations of the previous chapters on full chip layout. Overall, a lossless compression ratio of 10 has not been met. Nonetheless, compression can play an important role in most layers, and its shortcomings can be mitigated through careful engineering of the overall maskless lithography datapath and design layout. In addition, Block C4 has shown itself as a strong candidate for implementation in the maskless lithography datapath shown in Chapter 1, with the lowest decoder buffering requirement of 1.7 KB, low decoder complexity in software, high compression efficiency, and a reasonable and predictable compression speed in software.

Chapter 7

Hardware Implementation of the C4 Decoder

To use C4 compression in a maskless lithography datapath shown in Figure 1.9, the C4 decoder must ultimately be implemented as ASIC circuitry built on the same substrate as the array of writers, as described in Chapter 1. The first step in this endeavor is to break down the C4 decoder algorithm into functional blocks. Subsequently, each block needs to be refined, step-by-step, down to the gate level, and finally the transistor level. In this chapter, we consider the first steps of breaking C4 down to functional blocks, and refining the blocks, in particular, the region decoder.

We begin with the high level block diagram of the C4 decoder for grayscale layer images, shown previously in Figure 4.8. In Figure 7.1, we have slightly rearranged Figure 4.8, to emphasize the inputs and outputs. The decoder has 3 main inputs:

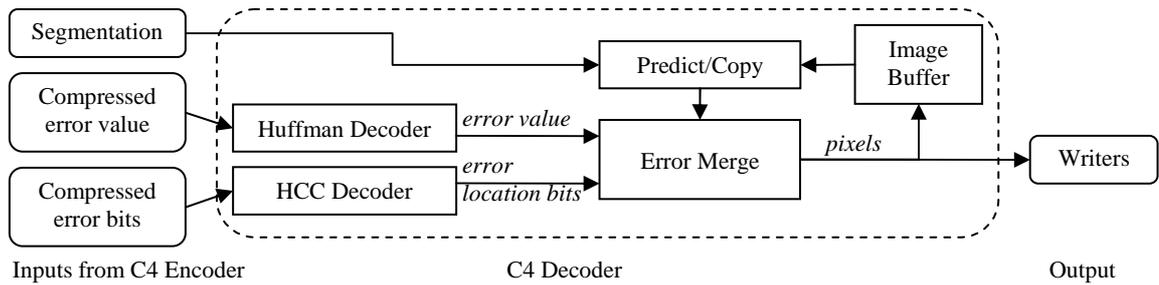


Figure 7.1: Block diagram of the C4 decoder for grayscale images.

a segmentation, a compressed error location map, and a stream of compressed error values. The segmentation is a list of copy regions, which indicate whether each pixel is copied or predicted. The compressed error location map is a compressed stream of bits, decompressed by the HCC Decoder block. Each bit in this stream controls whether the Merge block accepts the Predict/Copy value, or the error value input. The error value stream is generated by Huffman decoding the compressed error value input. If the error location bit is 0, the Predict/Copy value is correct and is sent as output to the writers. If the error location bit is 1, the Predict/Copy value is incorrect, and the error value is sent as output to the writers. In addition, the output to the writers is stored in a image buffer, to be used in the future for prediction or copying.

Of the 5 blocks in the decoder in Figure 7.1, two are discussed in detail in this chapter, the Huffman Decoder in Section 7.1 and the Predict/Copy block in Section 7.2. The implementation of the remaining 2 blocks are either fairly straightforward, or may be extracted directly from existing work in the literature. The function of the Merge block is essentially that of a multiplexer. The image buffer may be implemented

using random access on-chip memory, such as multi-ported SRAM, with 5-bit I/O. Other implementation possibilities for this memory, such as a systolic array, have been covered thoroughly in other papers [26]. The HCC decoder likewise is composed of another 5-bit Huffman decoder, a uniform decoder, and a combinatorial decoder. The uniform decoder, and the combinatorial decoder are straightforward to implement from algorithms described previously using simple adders and memory.

One challenge of implementing any hardware decoder is the usage of memory. Copy operations require past data to copy from. Prediction operations require past data to predict from. And, even though we quote an average compression ratio over a large block of data, the instantaneous compression ratio varies from codeword to codeword. Buffer memory is required to smooth the data rate. On a computer, or even in a cellular phone, all of these memory considerations are a non-issue. Memory is abundant, typically somewhere between 10 megabytes (MB) to 10 gigabytes (GB). However, in our maskless lithography application domain, the decoder circuitry must share space with the lithography writers. Consequently, area available for memory is in the realm of a few hundred kilobytes (KB), approximately 1000 times smaller than what a typical notebook computer carries. In short, memory usage must be conserved, and this choice is reflected through the design of the hardware blocks.

7.1 Huffman Decoder Block

We implement the Huffman decoding algorithm using the canonical Huffman code, chosen for its simple representation that lends itself to a less complex decoder implementation. The software algorithm description can be found in [14]. Huffman encoding works by assigning a shorter code to more frequent data, thus reducing the average number of bits required for representation. In canonical Huffman coding, these codes are arranged such that for each code length starting from 1, there is a minimum valid code. If this minimum is not met, then another bit is shifted in, equivalent to multiplying the existing code by 2 and adding the new bit. At the same time, the code length is incremented, and a new minimum valid code is read from a table. This process continues until the minimum is met, at which point the code known to be valid, and the decoded symbol may be output by performing an addition, subtraction and a pair of memory lookups.

In Figure 7.2, we have converted the software algorithm to a hardware block diagram for implementation. The input rate is a constant 1 bit per cycle, so there is no need for an input buffer. The Code shift register handles the shifting in of the bits. The First Code memory stores the minimum valid code, indexed by the Code Length counter. The output of the First Code Memory is compared to the output of the Code register, and if the minimum is not met, then it sends a signal to Code to shift in another bit, and a signal to Code Length to increment. If the minimum is met, the Code is valid, and the output comes out from a memory lookup to the offset

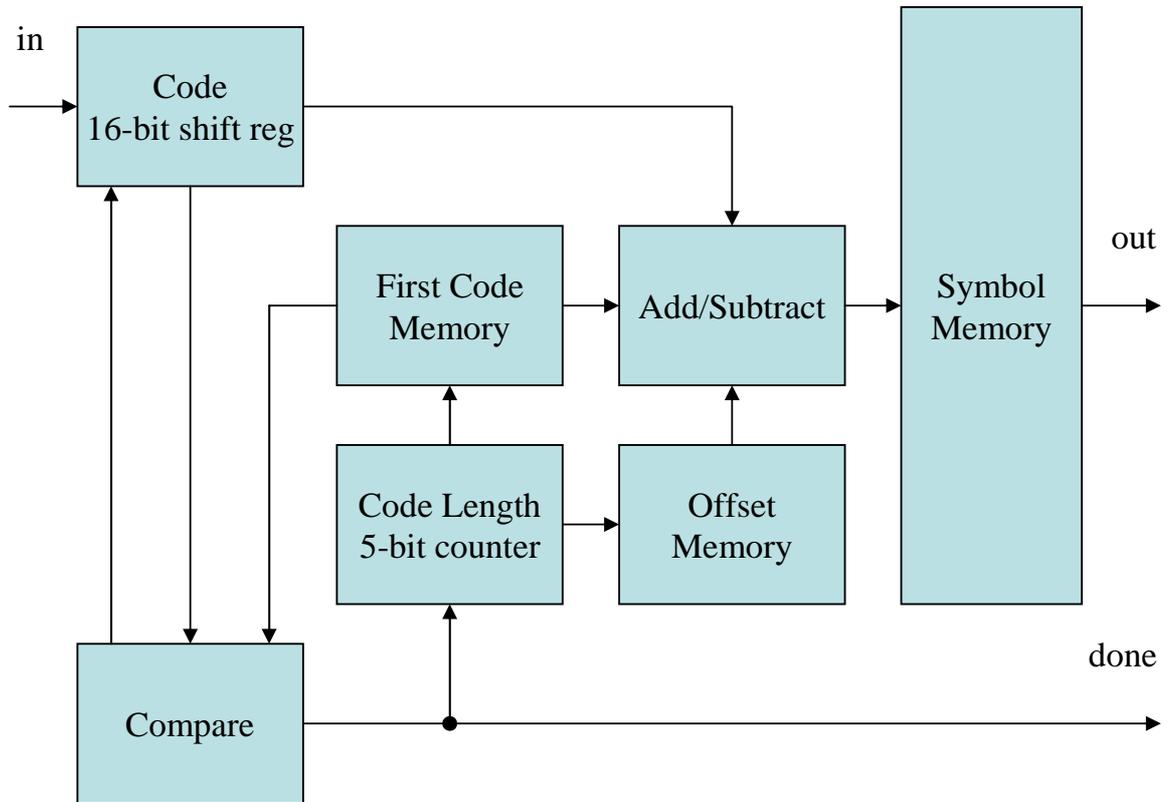


Figure 7.2: Block diagram of a Huffman decoder.

table, an add and subtract, and a final lookup to the symbol table. A done signal accompanies this to indicate that the output is indeed valid, since we do not have a constant output rate.

This Huffman design is small, simple to implement, and fast. It uses one shifter, one comparator, one counter, one adder/subtractor, and 3 small memories, all standard components. The critical speed path is a short loop through one memory lookup, one comparator, and one counter, corresponding to the First Code block, comparator block, and Code Length block, one of which must be registered. Total memory size for a Huffman decoder with N -bit output and a maximum M -bit code length

is $2M^2 + N2^N$ bits. In C4 we set, $N = 5$ in order to accommodate 32 gray levels; also setting $M = 8$ is sufficient to accommodate the statistics of the pixel values. Consequently, total memory usage is 288 bits.

7.2 Predict/Copy Block

The Predict/Copy block receives the segmentation information from the C4 encoder and generates either a copied pixel value, or predicted pixel value based on this segmentation. Data needed to perform the copy or prediction is drawn from the image buffer. In Figure 7.3, we refine the Predict/Copy block into 4 smaller blocks: Region Decoder, Predict, Copy, and Merge. The Region Decoder decodes the segmentation input into control signals for the other blocks. Specifically, it provides the copy parameters (dir, d) to Copy block, and predict/copy signal to the Merge block. The parameter dir , short for direction, indicates whether to copy from the left or from above, and the parameter d indicates the distance in pixels to copy from. Together, (dir, d) are used by the Copy Block to compute the memory address from which to read image buffer, using a shifter and adder. The Predict block performs linear prediction as described in Chapter 4, using a pair of adders with overflow detection. The predict/copy signal selects which input is accepted by the Merge block, a basic multiplexer, and generates an output accordingly. The output leaving Predict/Copy goes through another Merge block, which chooses between the Predict/Copy output and the error value, based on the error bit. Copy, Predict, and Merge are composed

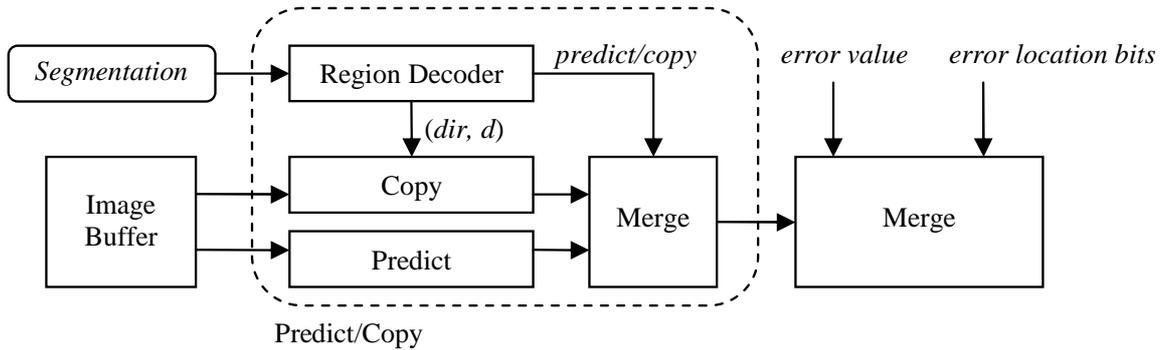


Figure 7.3: Refinement of the Predict/Copy block into 4 sub-blocks: Region Decoder, Predict, Copy, and Merge.

of simple circuits commonly used in digital design.

In contrast, the implementation of the Region Decoder is considerably more complex than the other 3 blocks. It is tasked with decoding the segmentation information, expressed as a list of copy regions (x, y, w, h, dir, d) described in Chapter 4, and converting this information into control signals for the Copy and Merge blocks. In particular, for each pixel to be copied, it must generate the (dir, d) signal for the Copy block, indicating how far to the left or above to copy from; and it must send the control $predict/copy$ signal to the Merge block, to tell it where to accept input from.

This data conversion problem faced by the Region Decoder, can be interpreted as a problem of rasterizing non-overlapping colored rectangles. This visual interpretation of copy regions is illustrated in Figure 7.4. Each copy region can be thought of as a rectangle in an image at location (x, y) , height of h , width of w , and “color” of (dir, d) expressing the copy direction and distance, respectively. All areas outside the list of

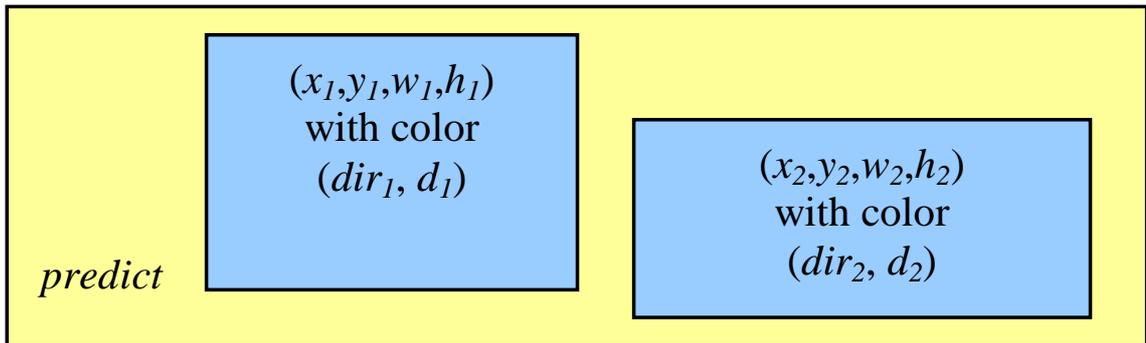


Figure 7.4: Illustration of copy regions as colored rectangles.

rectangles have a “color” predict. The output of the region decoder is the “color” of each pixel, in raster order, e.g. $predict, predict, copy : (dir_1, d_1), predict, copy : (dir_2, d_2), \dots$

7.3 Region Decoder Implementation - Rasterizing Rectangles

An efficient algorithm for rasterizing rectangles is well-known in the computational geometry literature as part of a family of plane-sweep algorithms [27]. The purpose of the discussion here is to make clear the operations and structures needed to implement the Region Decoder in hardware. Plane-sweep works by using a horizontal sweepline that moves from the top to the bottom of the image, as illustrated in Figure 7.5. We call rectangles intersecting the sweepline active rectangles. Information on active rectangles are maintained in an active list. The list is ordered by x -position of each active rectangle from left to right. For example, in $sweepline_1$, there is one rectangle in the active list.

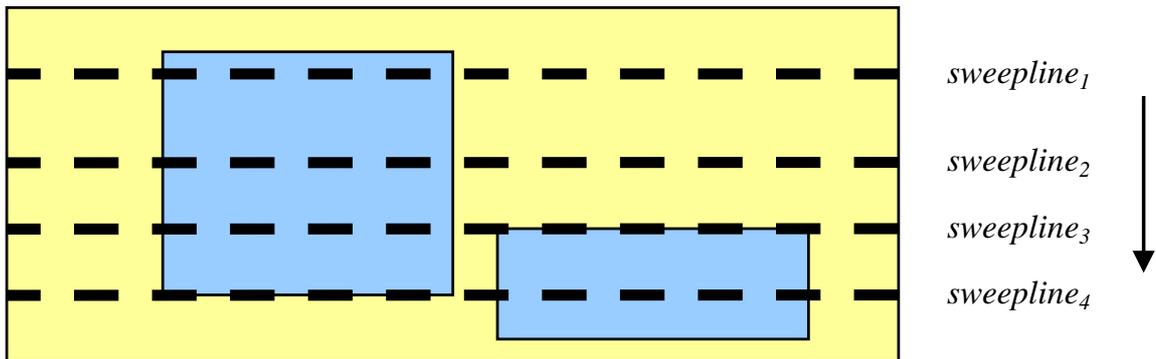


Figure 7.5: Illustration of the plane-sweep algorithm for rasterization of rectangles.

As the sweepline advances from $sweepline_1$ to $sweepline_2$, there is no change in the active list, but the residual height of the active rectangle, defined as the distance from the sweepline to the bottom of the rectangle, decreases. When the sweepline advances to $sweepline_3$, a new rectangle becomes active and must be inserted into the active list in the correct position. When the sweepline advances to $sweepline_4$, the residual height of the left rectangle is reduced to zero. That rectangle now becomes inactive, and must be deleted from active list. In summary, the active list changes only when the sweepline advances, and it must support the following operations: insertion when a rectangle first intersects the sweepline, decrementing the residual height, and deletion when the residual height becomes zero.

Now that we have covered discussed the downward advancement of the sweepline downwards, let us consider the rasterization of a single sweepline. Traversing from left to right, a sweepline is broken into horizontal segments of constant color, alternating between *predict* and *copy* : (dir_i, d_i) . Decoding a sweepline into pixels is a 2-step process: first, output a sequence of $(color, width)$ pairs, where *width* denotes the

width of the colored segment; next, a repeater outputs *color* pixels *width* times. Generating the $(color, width)$ pairs is done by traversing the active list. For example, in $sweepline_1$, there is one rectangle in the active list. From its (x, w, dir, d) we compute the following: the first segment is $(color = predict, width = x)$, the next segment is $(color = [copy : (dir, d)], width = w)$, and the last segment is $(color = predict, width = 1024 - x + w)$. In general, the predict segment between two active rectangles $i - 1$ and i is $(color = predict, width = x_i - x_{i-1} + w_{i-1})$, and the segment corresponding to active rectangle i is $(color = [copy : (dir_i, d_i)], w_i)$. Note that the only computation involved is for the width of the predict segment between 2 rectangles. In summary, rasterization of a sweepline involves: first, read the active rectangle list from left to right; second, compute the width of the predict segment between rectangle i and the previous rectangle $i - 1$; third, compose the $(color, width)$ pairs; and fourth, a repeater to generate actual pixel values.

Having described the region decoder sweepline algorithm, we are now ready to discuss its hardware implementation. Shown in Figure 7.6 is a refinement of the Region Decoder into sub-blocks. At the center is the Active Rectangle List, a first-in-first-out (FIFO) buffer which stores the rectangles intersecting the sweepline, ordered from left-to-right. Each rectangle in the active list cycles in a loop, like race cars in a race track, through the Decrement Residual Height block, the Insert Selector block, and back into the Active Rectangle List block. Each cycle through this loop is equivalent to an increment of the sweepline. The Insert Selector block stores the

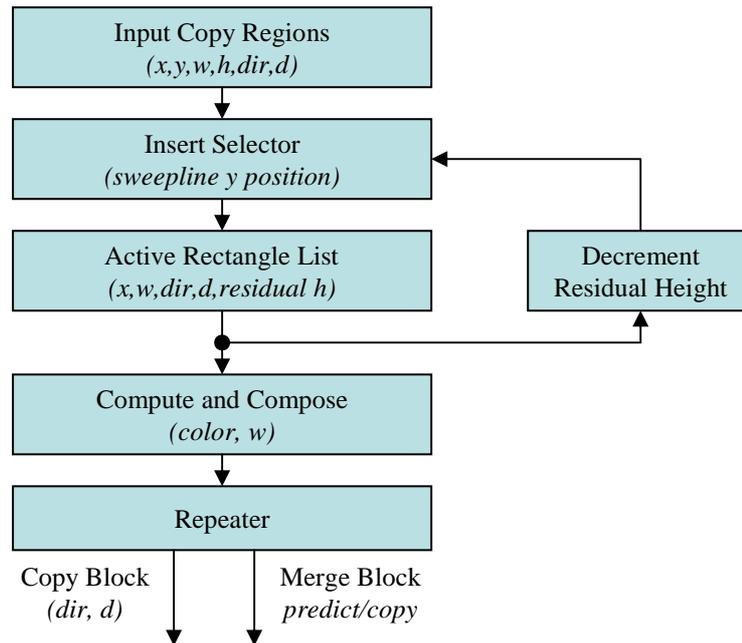


Figure 7.6: Refinement of the Region Decoder into sub-blocks.

current sweepline y position. It determines when and where it is appropriate to insert incoming copy regions into the sequence of rectangles cycling through. The Decrement Residual Height block decrements the residual height of each rectangle as it cycles through the loop. If its height is reduced to zero, the block also removes it from the cycle. These 3 blocks implement the maintenance of the active list as the sweepline advances.

The remaining 2 blocks, Compute and Compose, and Repeater, perform the operations necessary to rasterize a sweepline. Compute and Compose receives as input the active rectangle list, computes the width of predict segments between rectangles, and composes the $(color, width)$ pairs as described previously. The repeater generates actual control signals for the Copy and Predict blocks, by repeating $width$ times the

color, either $(predict, -, -)$, or $(copy, dir, d)$.

Each of the blocks in Figure 7.6, namely Input Copy Regions, Insert Selector, Active Rectangle List, Decrement Residual Height, Compute and Compose, and Repeater, may be implemented via standard hardware circuits, such as registers, memory, adders and comparators. The control of the blocks is modularized, because what we have described is a *dataflow* architecture: each block receives all the data necessary to perform its function, and then passes the result onto the next block. Basic handshaking communication protocols should be the only control that need to pass between blocks. The only major memory block in this design is the FIFO buffer of Active Rectangle List. For 1024×1024 layer images, each coordinate, (x, w, h, d) requires 10-bits to store, and *dir* requires one bit to store. Total memory usage is 41-bits per active rectangle. If we limit the maximum number of active rectangles to 128 at the encoder, then the total amount of memory is 5248 bits. Although the overall behavior is fairly complex, the physical size of the circuit implementation of the Region Decoder should be fairly modest.

Chapter 8

Conclusion and Future Work

Maskless lithography has many hurdles to overcome before it can establish itself as a alternative to optical microlithography. In this thesis, we have examined one of its challenges, the datapath architecture. The data starts as polygonal layer data produced by the designers. This needs to be translated via rasterization into control signals for pixel-based maskless lithography writers. As a whole, these control signals can be visualized a binary or gray pixel image of the layout.

The maskless lithography datapath must deliver this stream of control signal data to those writers in real time, as they print polygons onto the wafer. In designing this datapath, both potential data storage and data throughput problems are considered. In the process, we suggest the use of a lossless data compression as a means of addressing datapath bottlenecks.

To understand what compression efficiencies are achievable, several existing com-

pression algorithms, as well as a novel compression algorithm C4, are introduced and evaluated against each other on a variety of different layouts. In the end, C4 is shown to be well suited for compression of layer images, even though BZIP2 still remains quite competitive in terms of compression efficiency. However, C4 achieves this with a 1.7 kB decoder buffer, significantly smaller than BZIP2's 900 kB decoder buffer. In addition, C4 is engineered to have a simple decoder algorithm suitable for hardware implementation. In contrast, BZIP2 requires a complex block-sorting algorithm to be implemented at the decoder.

In addition, complexity concerns for each of the algorithms are addressed. For C4, encoding complexity is a significant runtime issue, i.e. a single layer of a microprocessor is estimated to take nearly 18 CPU years to compress. This motivates the development of its significantly less complex cousin, Block C4. Block C4 exhibits over 2 orders of magnitude speedup over C4, with comparable compression efficiency to C4. The speed of Block C4 allows the run of full chip evaluations against BZIP2 and ZIP which are impossible to do using C4.

Using the full chip analysis results, we examined in depth the block-by-block compression results of ZIP, BZIP2, and Block C4. We show that there is considerable inter-block variation in compression efficiency within a layer. In the worst case, when the maskless lithography system as a whole cannot absorb this variation, then the wafer throughput is limited by the throughput of the slowest block with the minimum compression ratio. In the ideal case, when all inter-block variations can be

absorbed, then the wafer throughput is limited by the average compression ratio. As the average compression ratio is significantly higher than the minimum compression ratio, it is important to consider where reality might fall between these two extremes. Our analysis shows that for Block C4, only a tiny fraction of blocks have compression ratios near the minimum. As long as these small number of variations are absorbed by the system, either through buffering, variations in the writing speed, or by changing the layout, then the wafer throughput approach the higher value determined by the average compression ratio.

Finally, while the decoders of various compression algorithms are simple and fast to implement in software, there are significant challenges in translating the software algorithm into hardware components for implementation using custom circuitry. Decoder algorithms in general are filled with conditionals and variations in data rates that lend themselves to a standard instruction based processor architecture with large accessible memory. Converting these algorithms into a data processing flow more suitable for hardware implementation is a challenge. Nonetheless, this challenge has been met with the aid of algorithms used in computational geometry, and techniques of logic synthesis.

However, as is typically the case for a project of this magnitude, it has created more questions than it has answered. Although several maskless lithography datapath architectures are considered and presented in this thesis, it is certainly not a comprehensive list. Whether compression may play a role in these alternative datapaths

remains to be seen.

The datapath that is the focus of this thesis utilizes off-chip RAM based data storage, coupled with a high-speed communications channel to on-chip decoding. If compression is removed from this datapath, the on-chip decoder can be removed as well, but the speed of the communications channel must increase to compensate for the higher data rate of the uncompressed stream. In our full chip analysis, we show that compression can be thought of as a multiplicative factor on the board-to-chip communication channel which varies from layer to layer. The higher compression ratio, the slower the communication channel can operate to achieve the same wafer throughput. Conversely, the lower the compression ratio, the faster the communication channel must operate to achieve the same wafer throughput.

The tradeoff between communications throughput and compression efficiency is an interesting one. Board to chip communications mechanisms vary in design and performance as much as compression algorithms do. State-of-the-art in board to chip communications are such as HyperTransport 3.0 [40] and CELL communications [23], are not just simple wires carrying a digital voltage. Each wire is treated as a digital communications channel with features such as equalization, communications protocols, differential signaling, power management, error detection, flow control and more.

As an example, HyperTransport 3.0 offers a 320 Gb/s link but also consumes a significant amount of chip area and power. Referencing this to Table 6.3, it would

take 3 HyperTransport links to achieve 1 Tb/s allowing the Metal1 layer to print at 25.5 wafers/hr for the minimum compression ratio of 1.7. On the other hand, if we have sufficient buffer to absorb all the variations, then we can apply the average compression ratio instead which is 5.2. This would allow 3 HyperTransport links to print 77.7 wafers/hr.

In this simple example, there are several tradeoffs to consider. We can add circuitry to make the datapath more flexible to inter-block variations. Doing so brings up the overall wafer throughput, but this circuitry costs chip area and power. This must be balanced against the cost of adding another HyperTransport link. Moreover, the optimum tradeoff can shift depending on your target wafer throughput. The answer for 10 wafers per hour may be very different than the answer for 60 wafers per hour. The exact tradeoff in circuit area and power between wafer throughput, communication throughput, and compression buffering is an interesting point for future research and beyond the scope of this thesis. What we have given here is simply a flavor of some of the important considerations and tradeoffs.

In the conversion of polygonal data into pixel images, we have used a simple “idealized pixel printing model” as the basis for rasterization. While there have been demonstrated usage of such a model, there are clearly alternative rasterization models [33]. However the nature of proximity correction is that it represents distortions of the design intent in the first place, so in this realm, loss can be tolerated. Is there some tradeoff to be made then between the fidelity of proximity correction and the

compression efficiency of the pixels? Is there another way to introduce proximity correction besides embedding that information in the pixels?

Last, but not the least, while a hardware decomposition has been presented for a C4 decoder, there is still much work to be done synthesizing each of the hardware components, and computing the power, area, and timing of the entire decoder block. This work is being continued in [34].

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